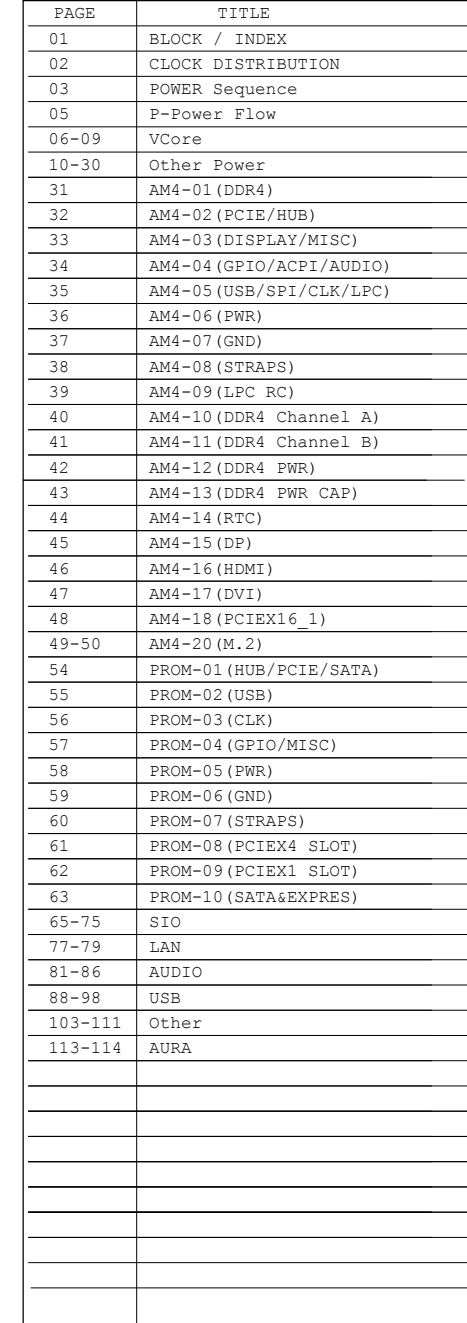
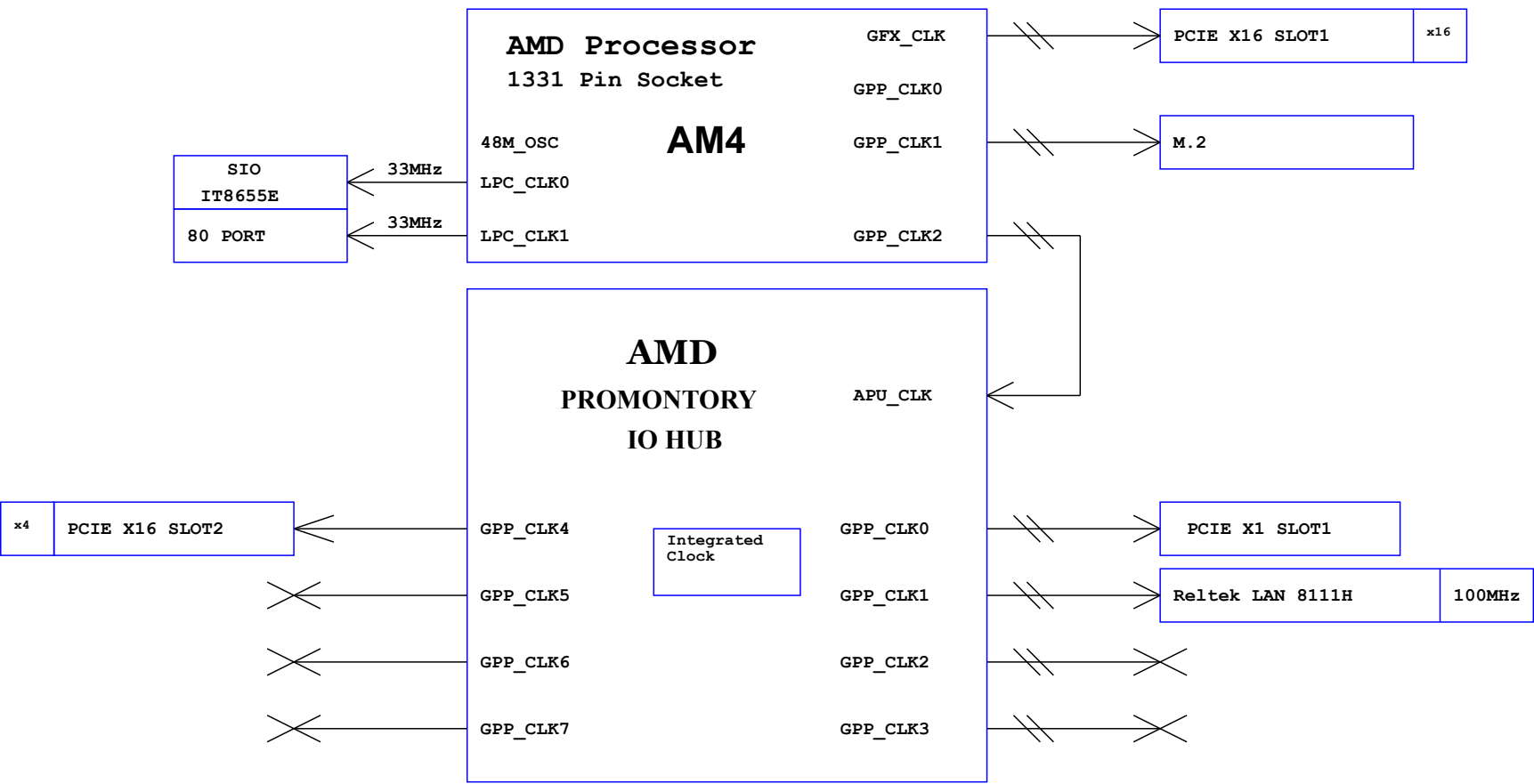
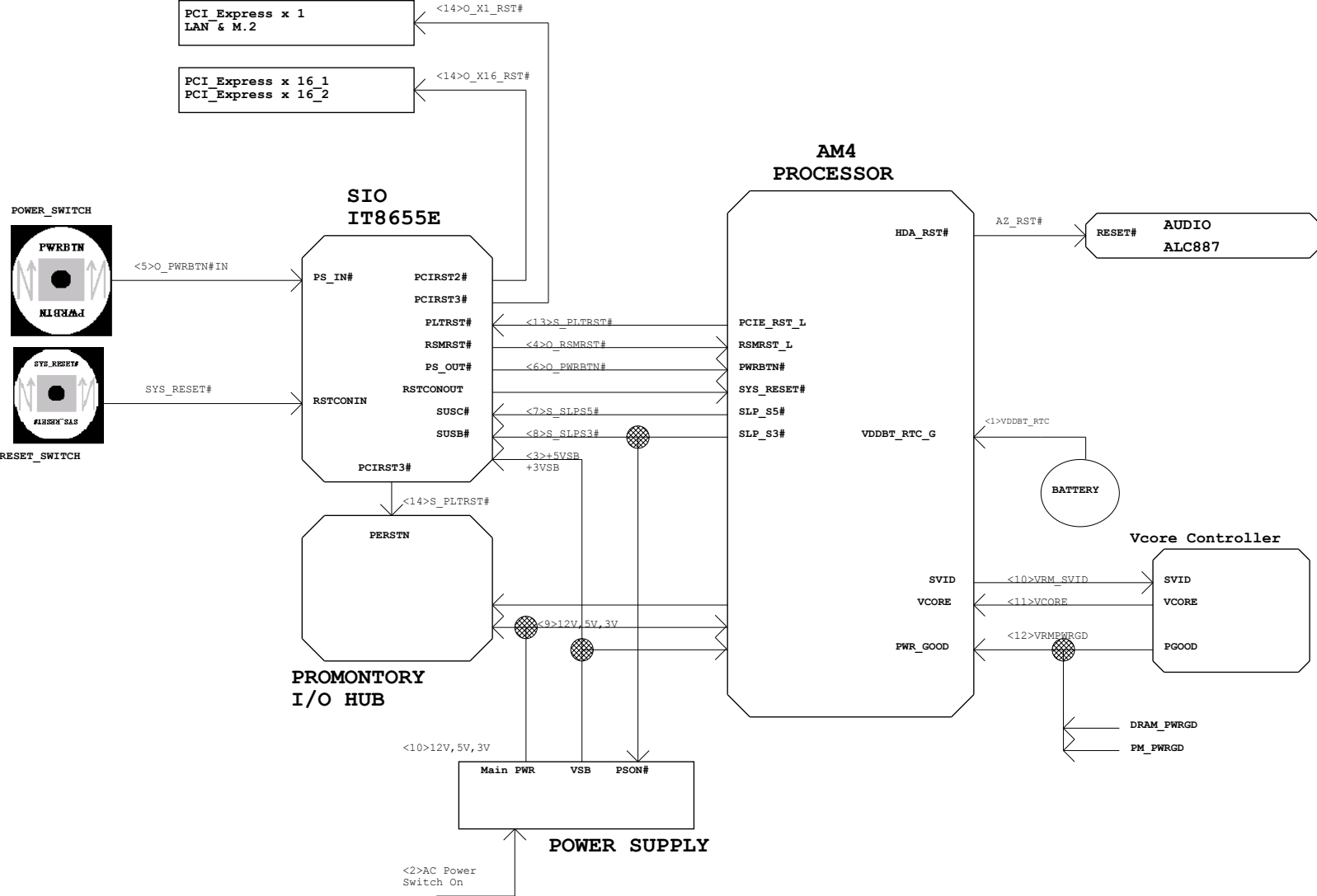


## 2018.6.4









**Title :**

ASUSTek Computer Inc.

**Engineer:** **Elainelx\_Li**

Size

Project Name

Rev

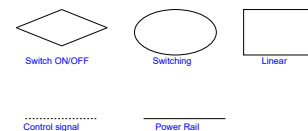
A3

**AM4**

R1.00

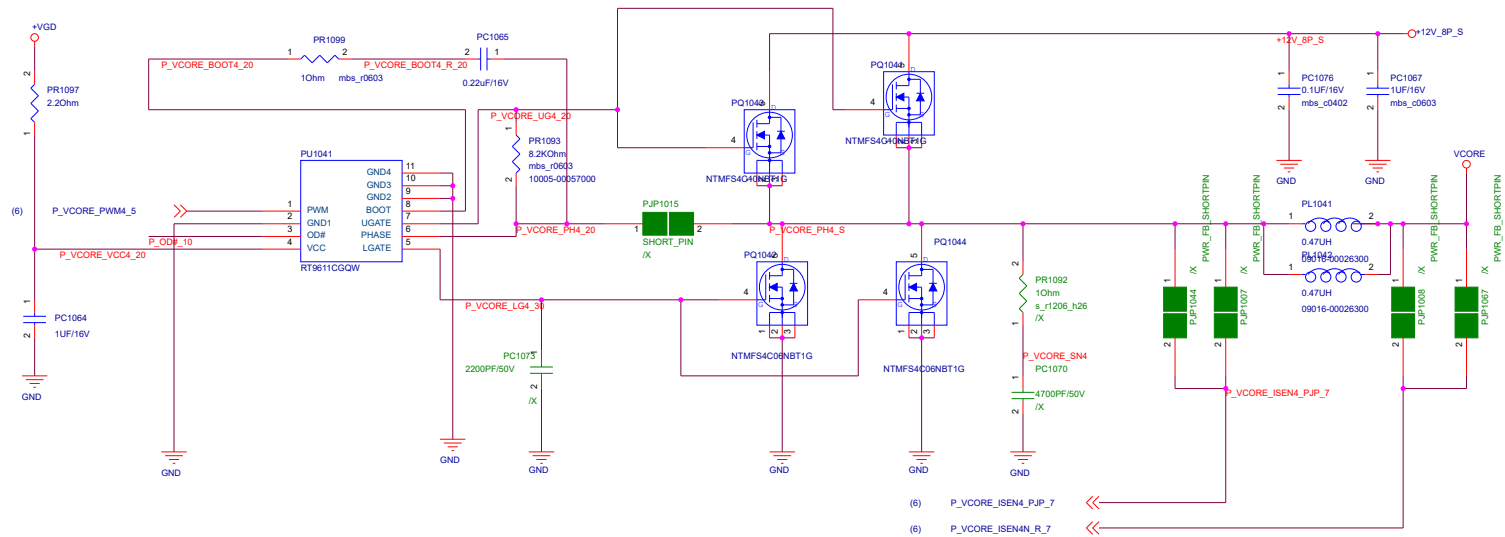
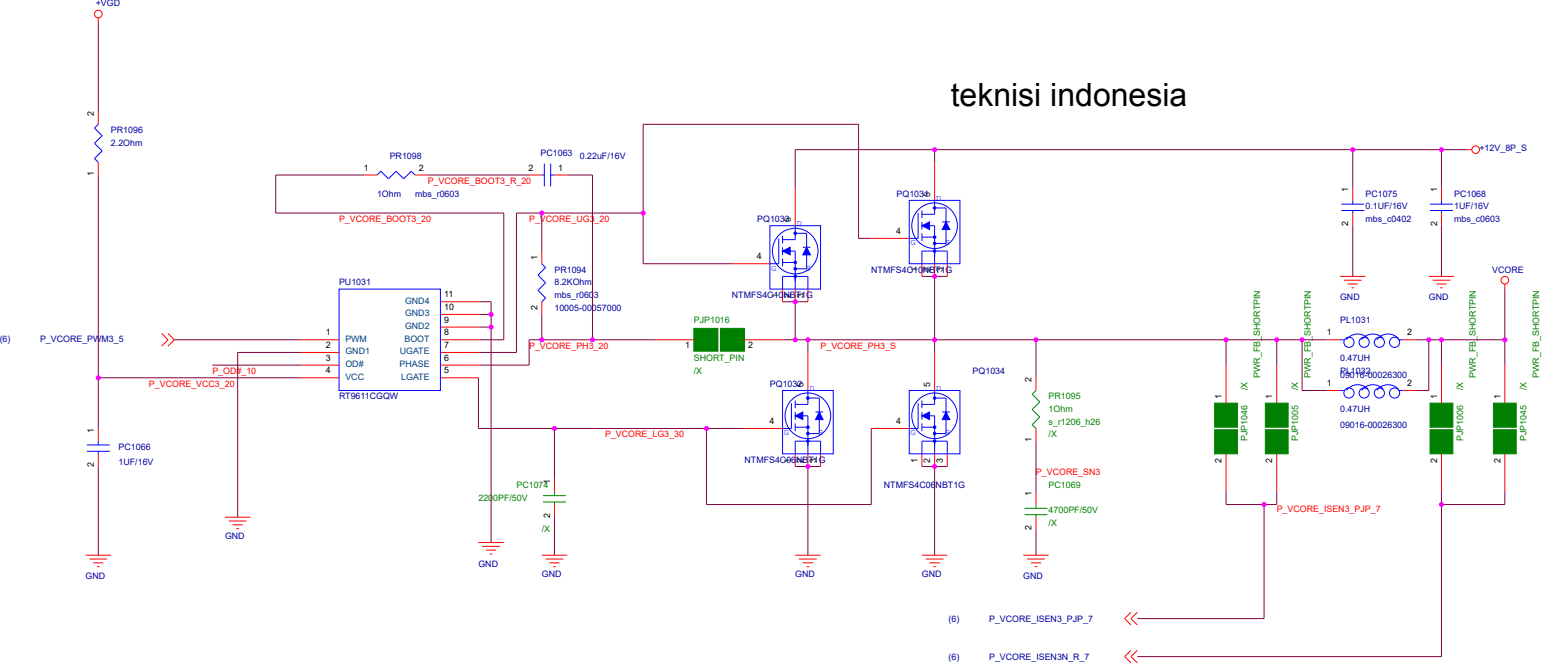
Date: **Friday, August 17, 2018**

Sheet **4** of **117**









P\_ODR\_10 >>> P\_ODR\_10 (7,10)

<Variant Name>





Title : **VDDSOC Controller**

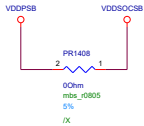
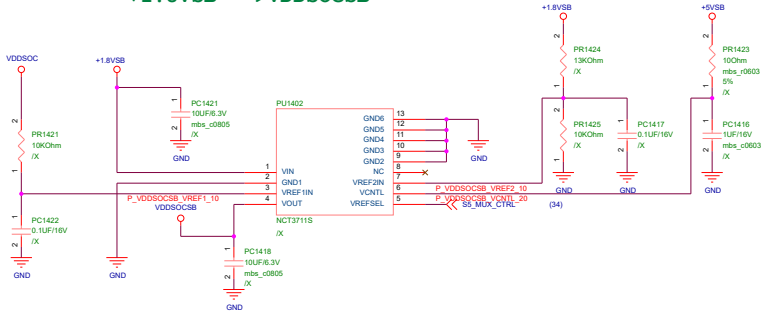
ASUSTek Computer Inc.

Engineer:

Size	Project Name	Rev
A3	<b>18Q2 AM4 1106 4-2PH 1P2P-2P2P?HSY?100</b>	2.00



+1.8VSB==>VDDSOCB



(20,37,67,72)





Title : **NA**

ASUSTek Computer Inc.

Engineer:

Size

Project Name

Rev

**A2**

**AM4**

**1.00**

Date: **Wednesday, August 29, 2018**

Sheet **14** of **109**



Title : NA

ASUSTek Computer Inc.

Engineer:

Size

Project Name

Rev

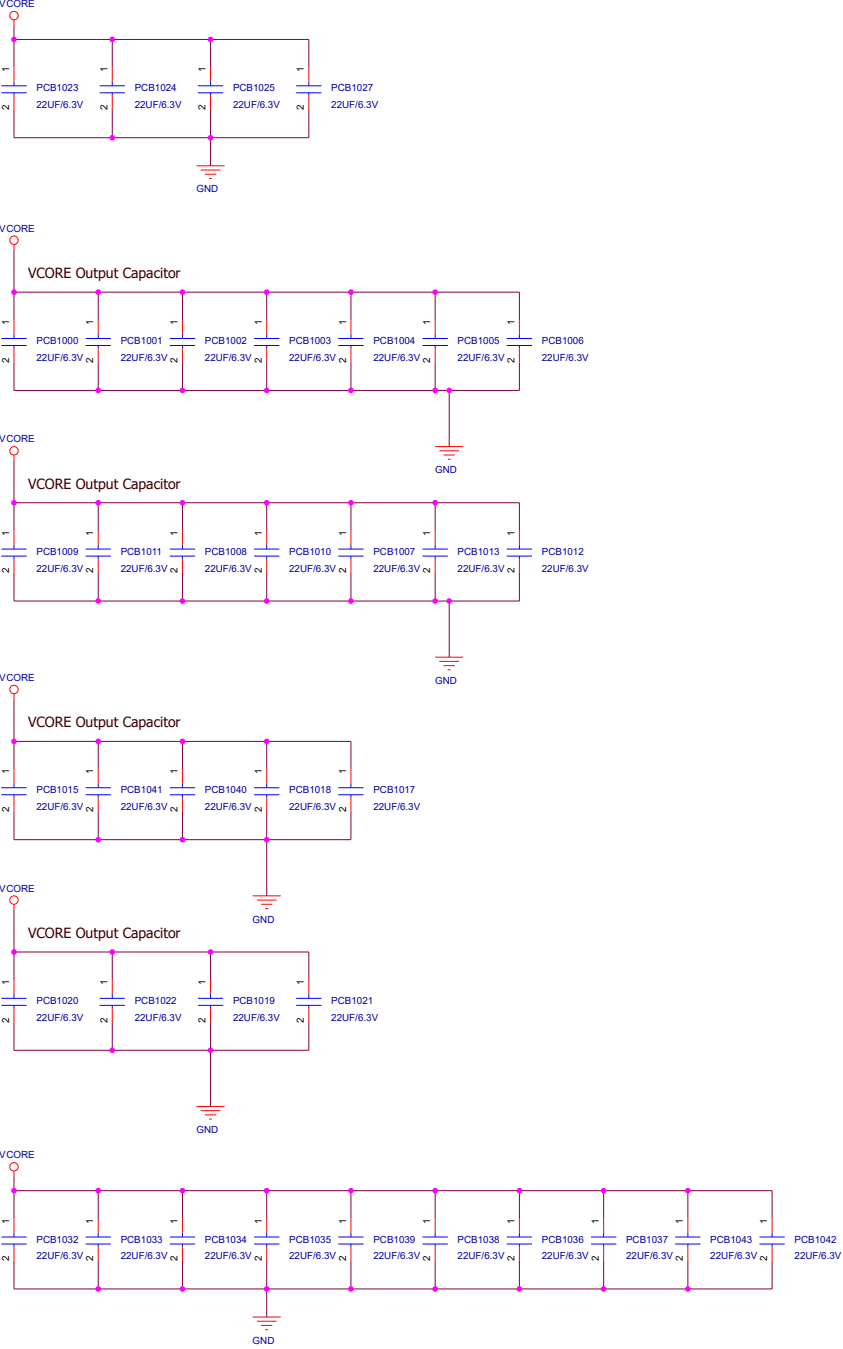
A3

AM4

1.00

Date: Wednesday, August 29, 2018

Sheet 15 of 109



<Variant Name>

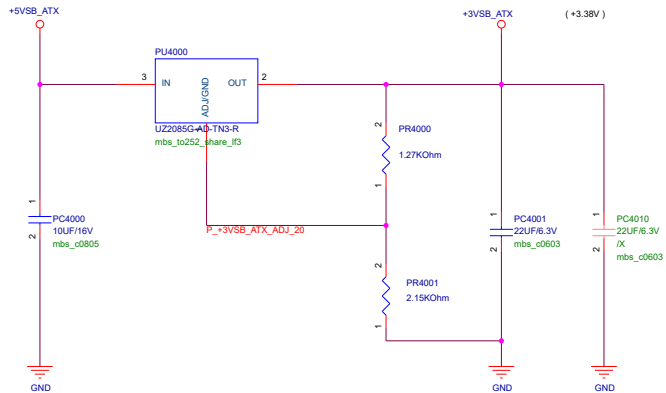




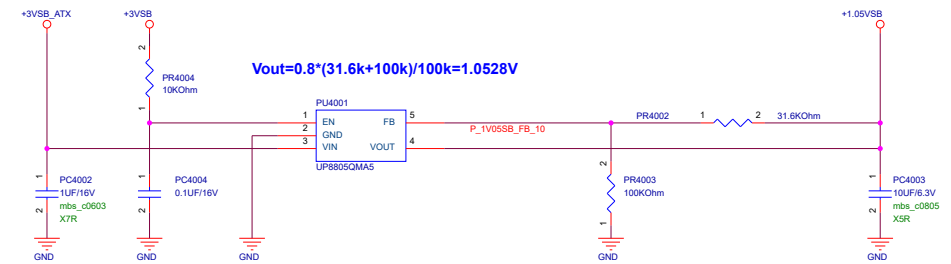


**+5VSB\_ATX ==>+3VSB\_ATX**

**Io:1.5A**

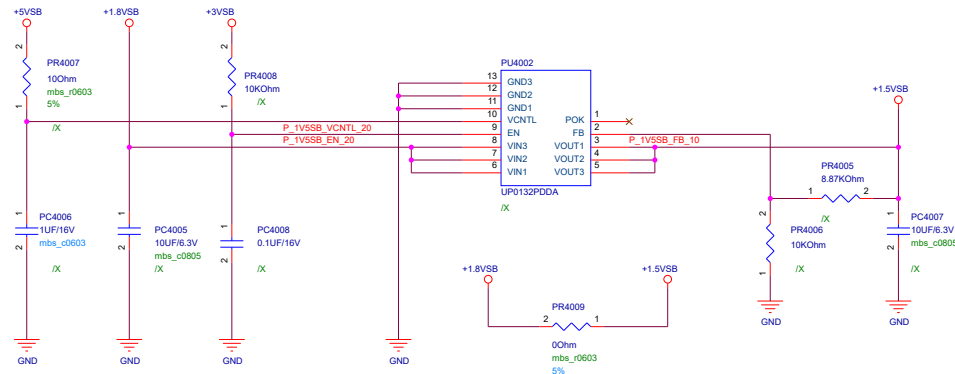


**+3VSB\_ATX ==>+1.05VSB /50mA**



**Power Component place near each other!**

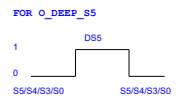
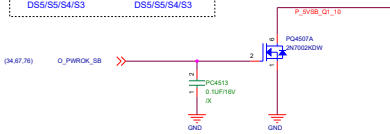
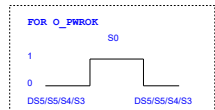
**+1.8VSB==>+1.5VSB /0.75A**



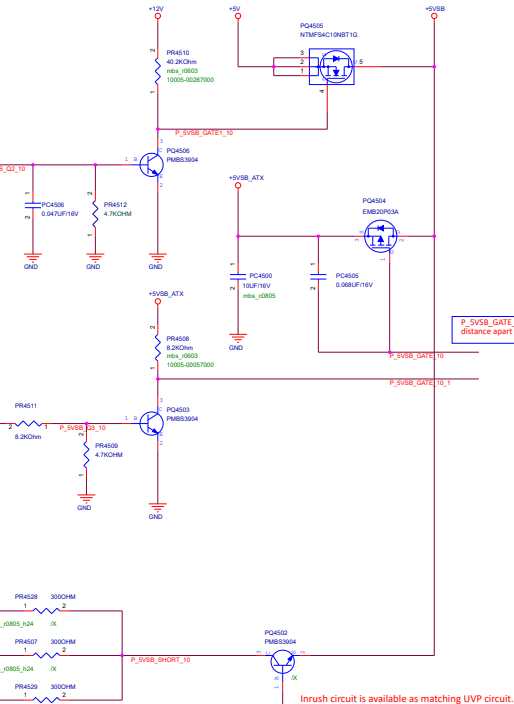
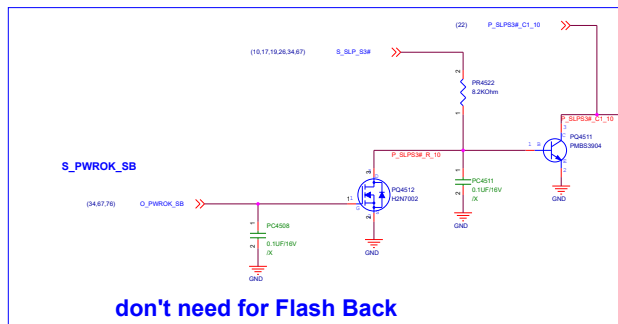
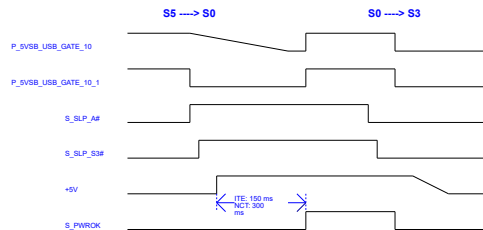
NOTE:which power rail powered to audio ic should be confirmed by EE.

- 1.Vin and Vout keep more than 30mils away.
- 2.input cap and Output cap can't use same GND.
- 3.P\_VSIB\_GATE\_10 is away from Vin more than 15mils,from Vout more than 30mils.

If OVP protection circuit isn't mounted,then PC4500 and PC4501 aren't also mounted.

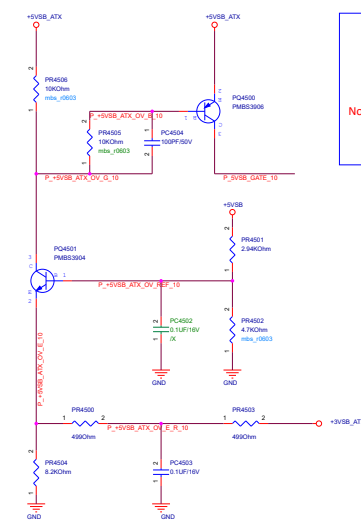


SS/S4/S3/S0

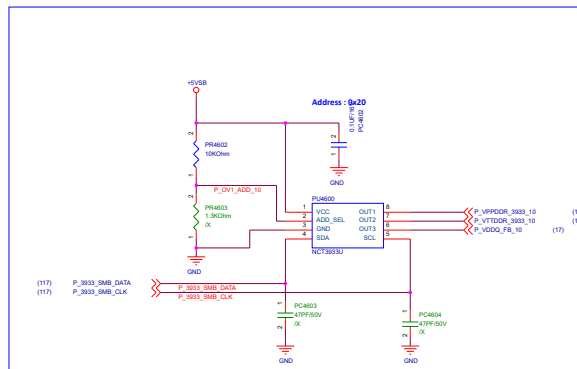


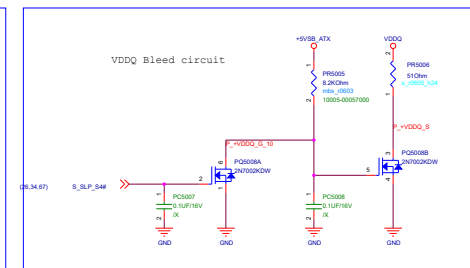
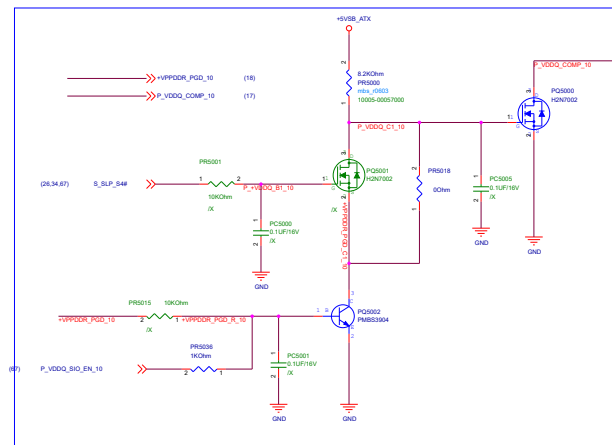
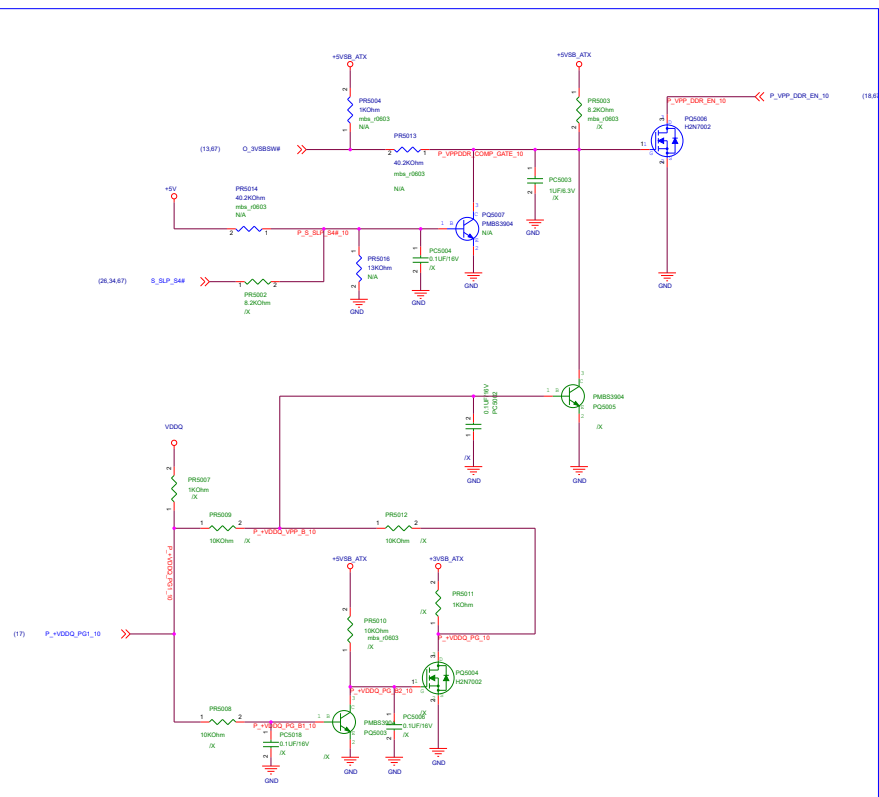
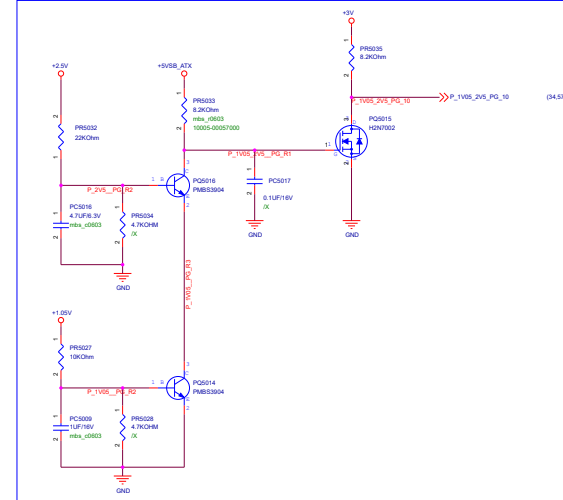
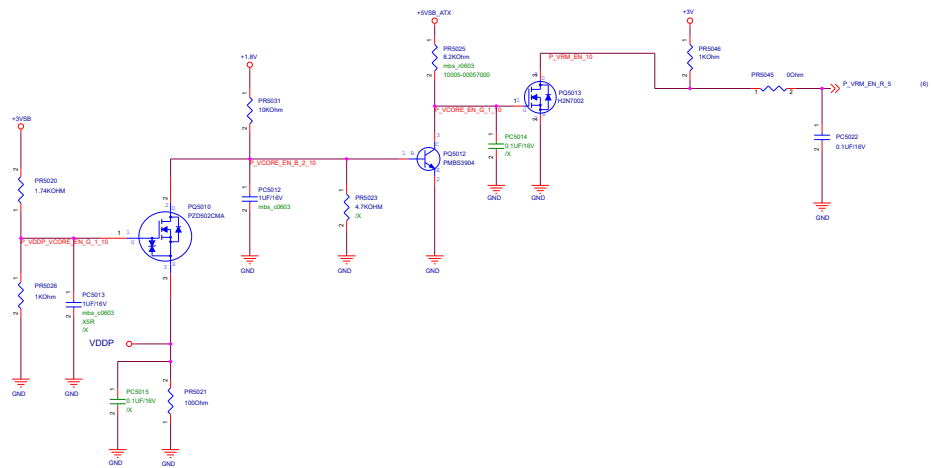
Note:

P\_VSIB\_GATE\_10 is about 15mils or more distance apart from other power rail.



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# Title :

## +3V\_OVP

ASUSTek Computer Inc.

## Engineer:

Size

Project Name

Rev

## A2

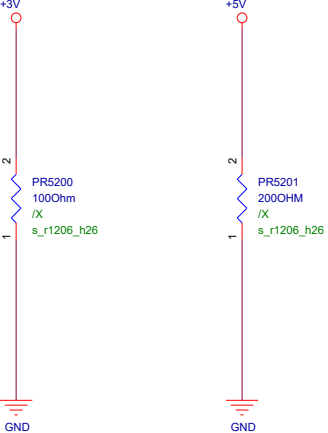
# FM2 PLUS

1.00

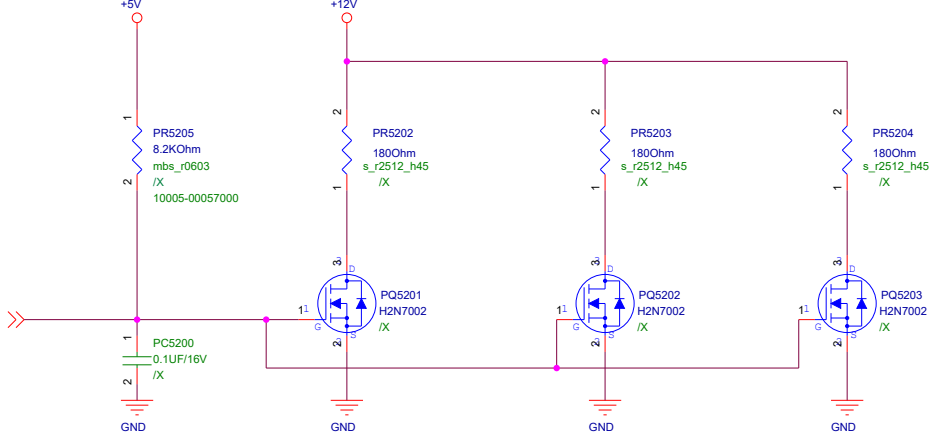
Date: Wednesday, August 29, 2018

Sheet 24 of 109

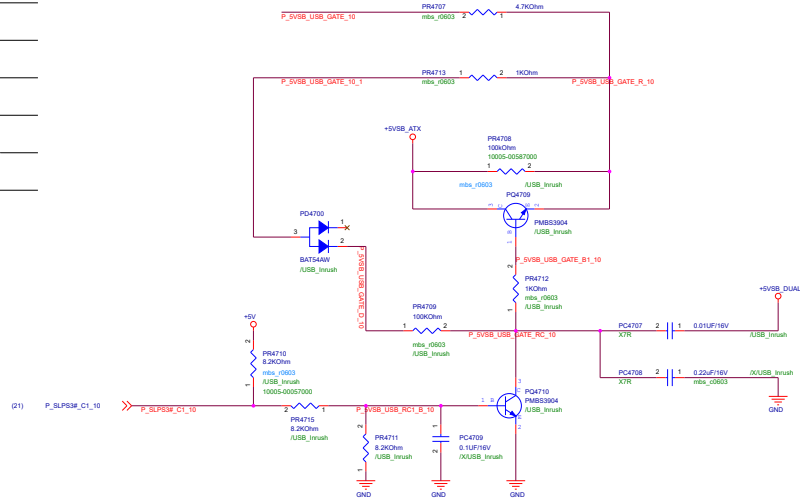
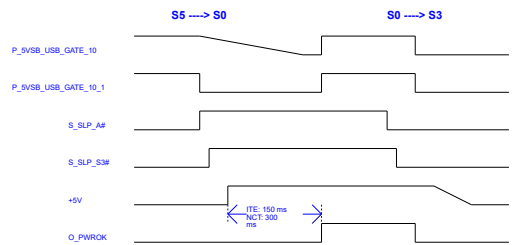
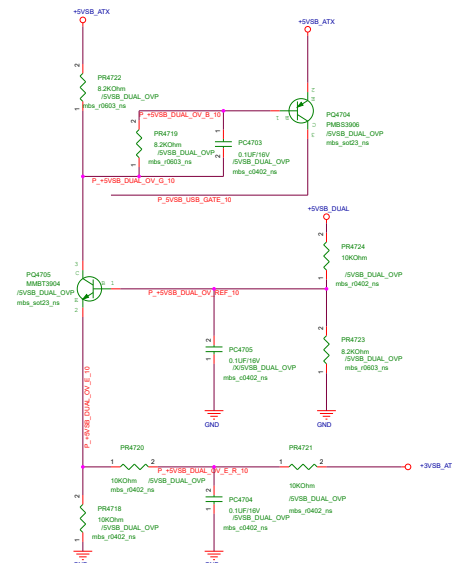


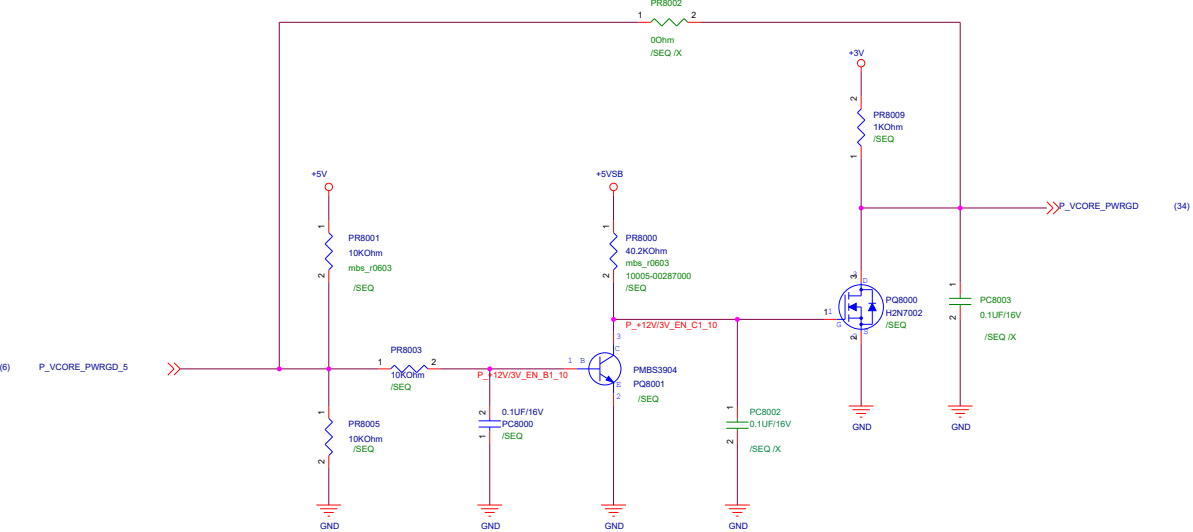


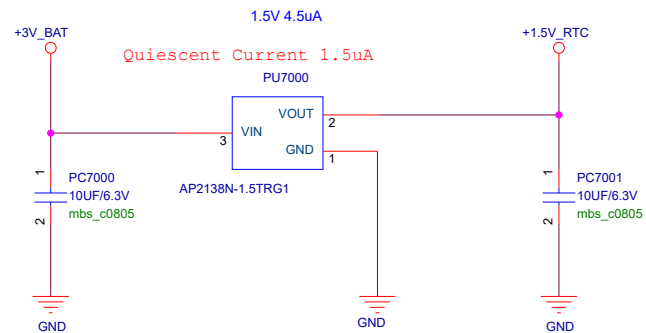
(34) O\_+12V\_DUMMYLOAD\_10











Modify 20170613



**Title :** NA

ASUSTek Computer Inc.

**Engineer:**

Size

Project Name

Rev

A3

**AM4**

1.00

Date: Wednesday, August 29, 2018

Sheet 30 of 110



Title : NA

ASUSTek Computer Inc.

Engineer:

Size

Project Name

Rev

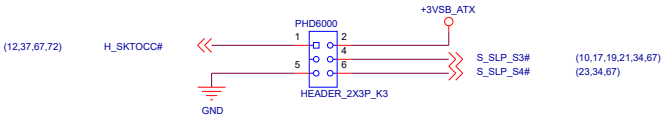
A3

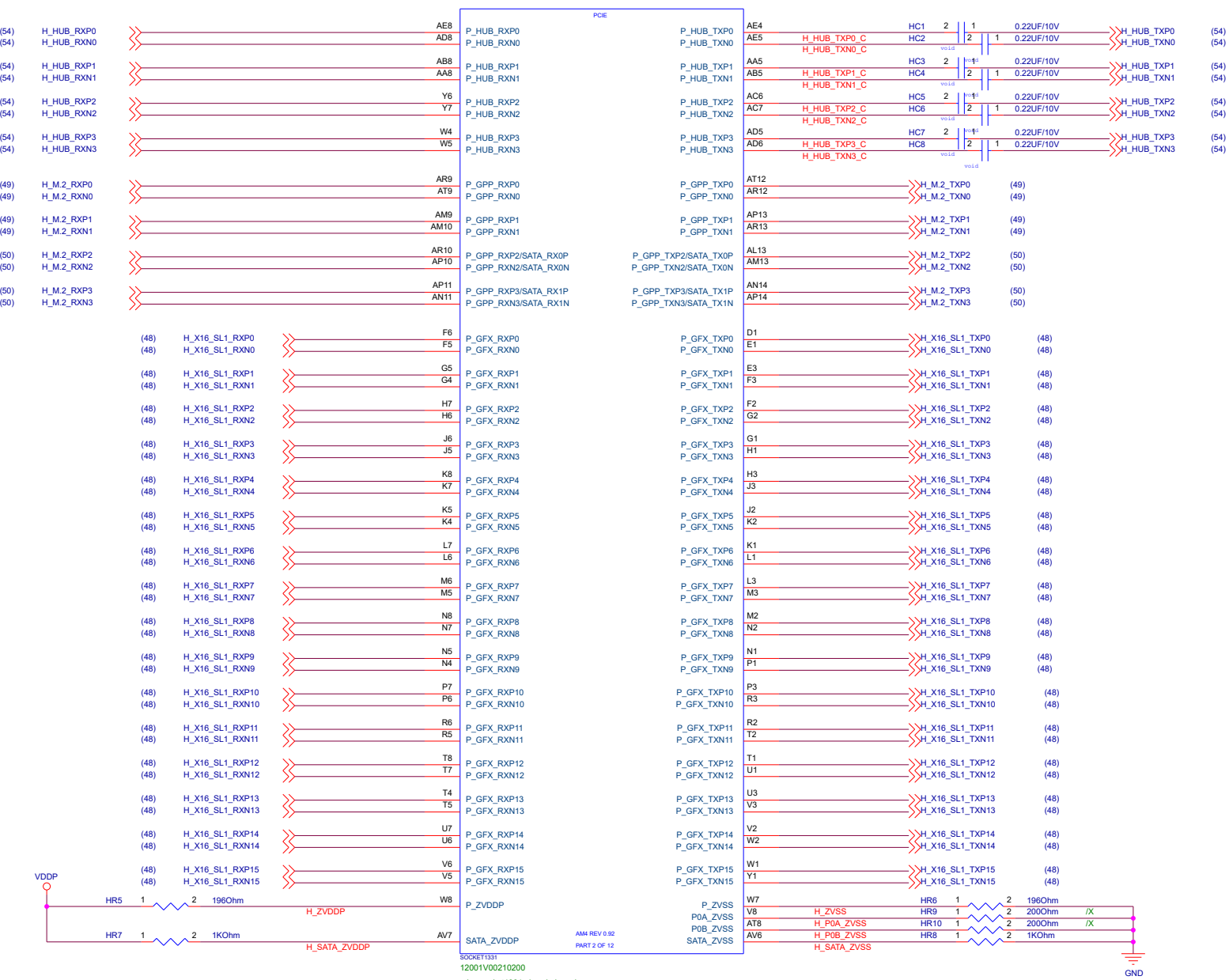
AM4

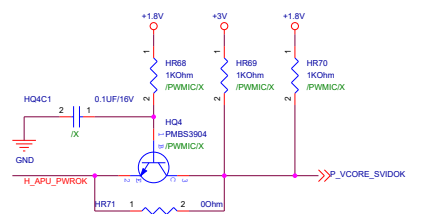
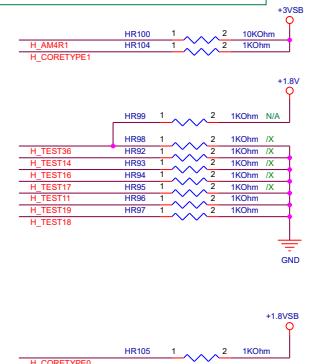
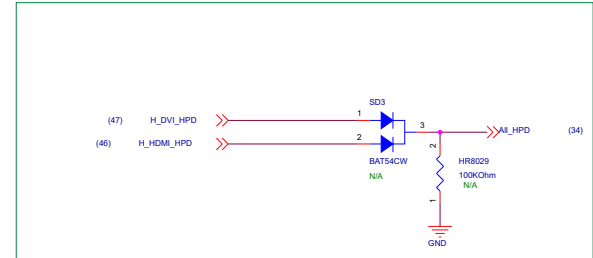
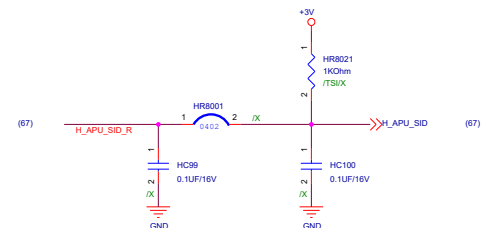
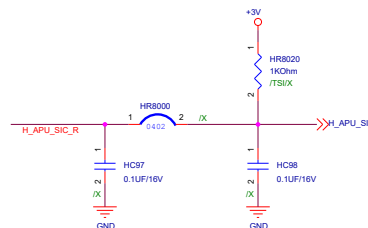
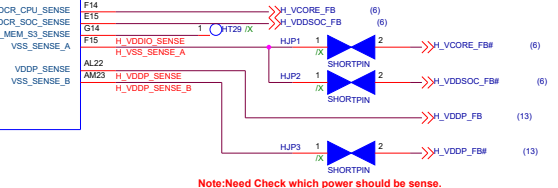
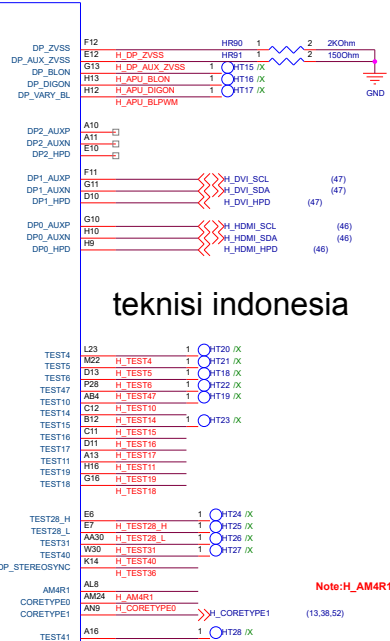
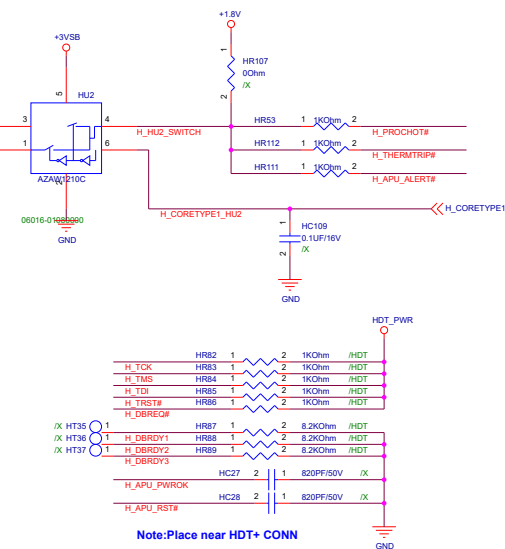
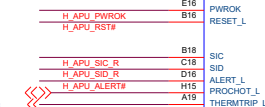
1.00

Date: Wednesday, August 29, 2018

Sheet 29 of 110

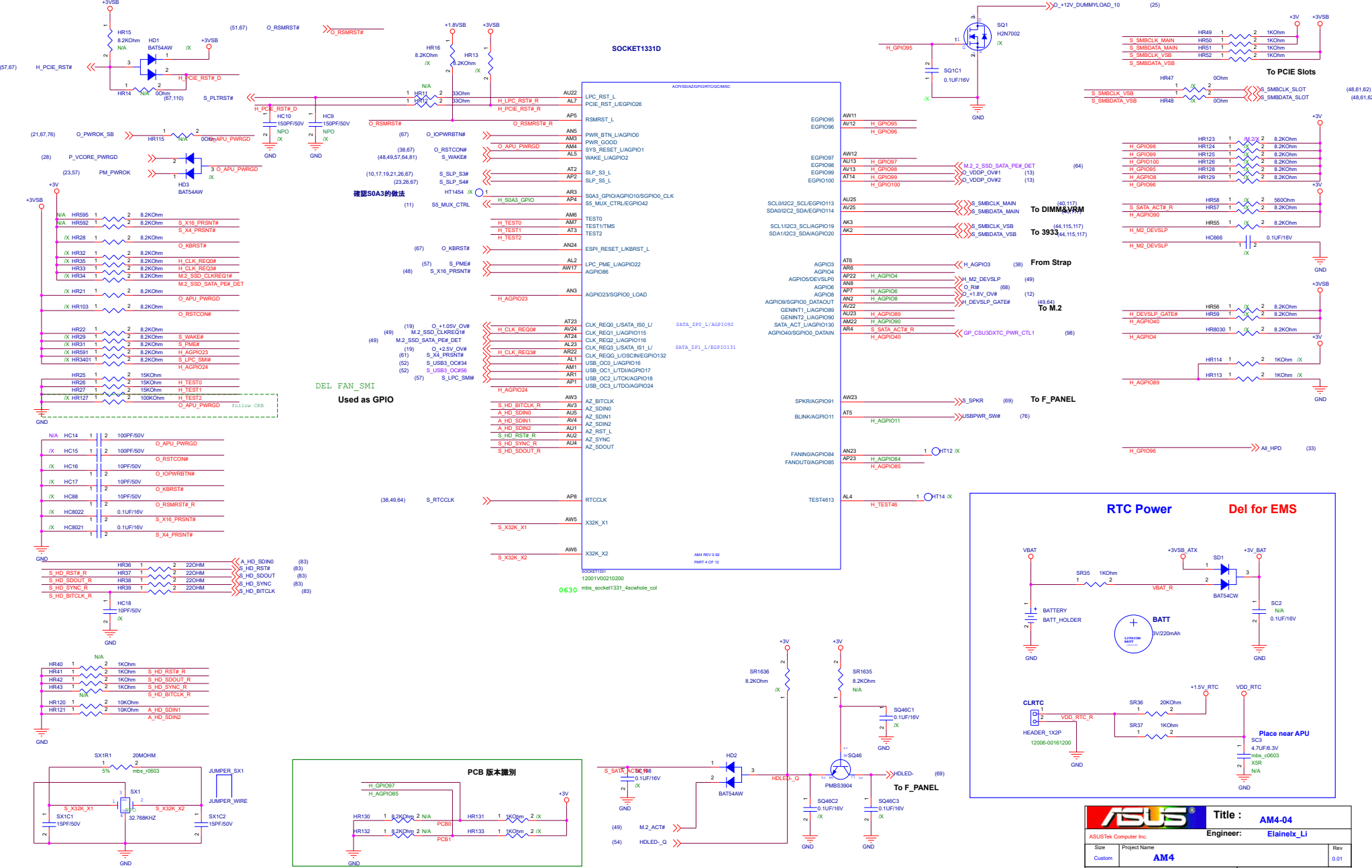


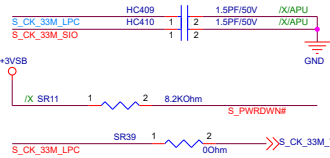
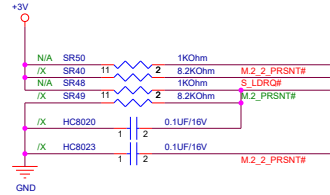
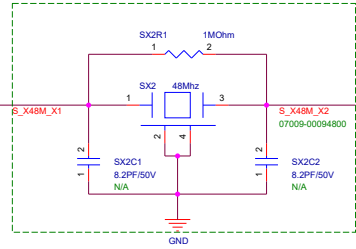




CORETYPE1	CORETYPE0	Family/Model No.	AM4 Type	
0	0	F15h/M60h-6Fh	Type0	Bristol
0	1	Reserved	Type1	ZP
1	0	F17h/M00h-0Fh	Type2	Summit
1	1	F17h/M10h-1Fh	Type3	Raven





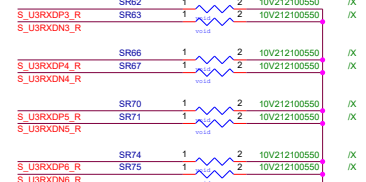
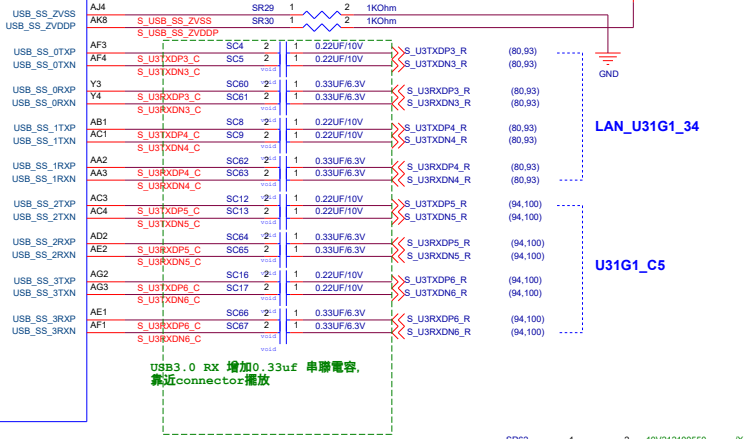
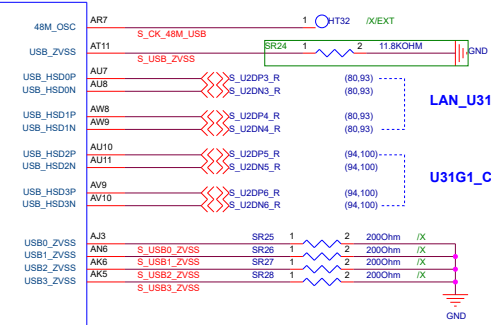
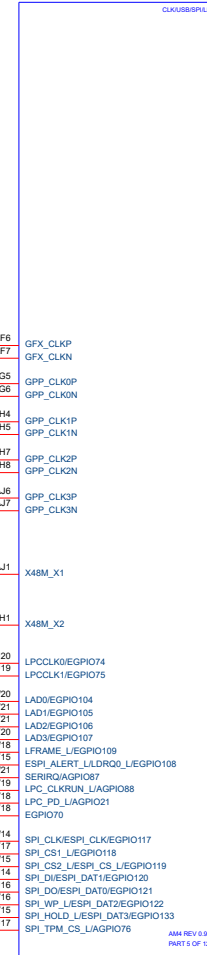
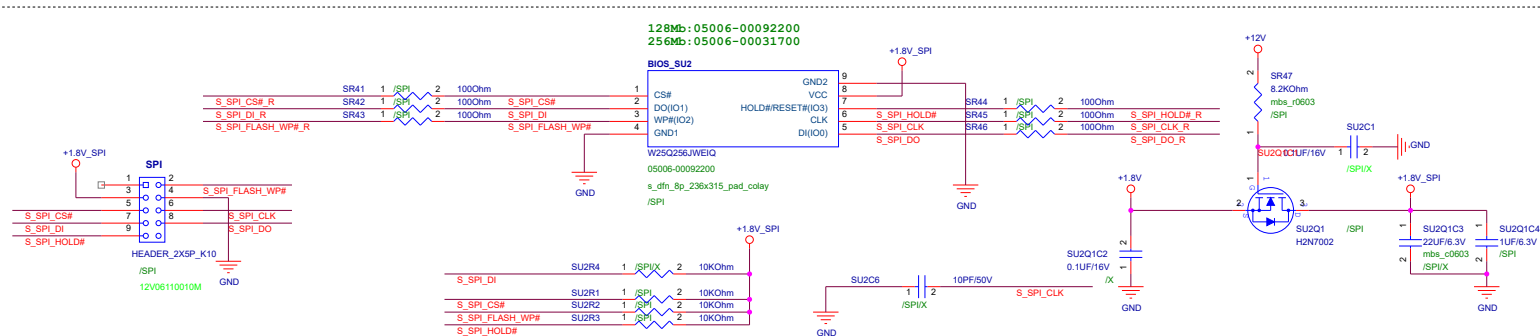


modify for X470-PRO:  
LPC clock 參考X370-F GAMING  
M.2 PRSNT#net name  
改為M.2\_1\_PRSNT#

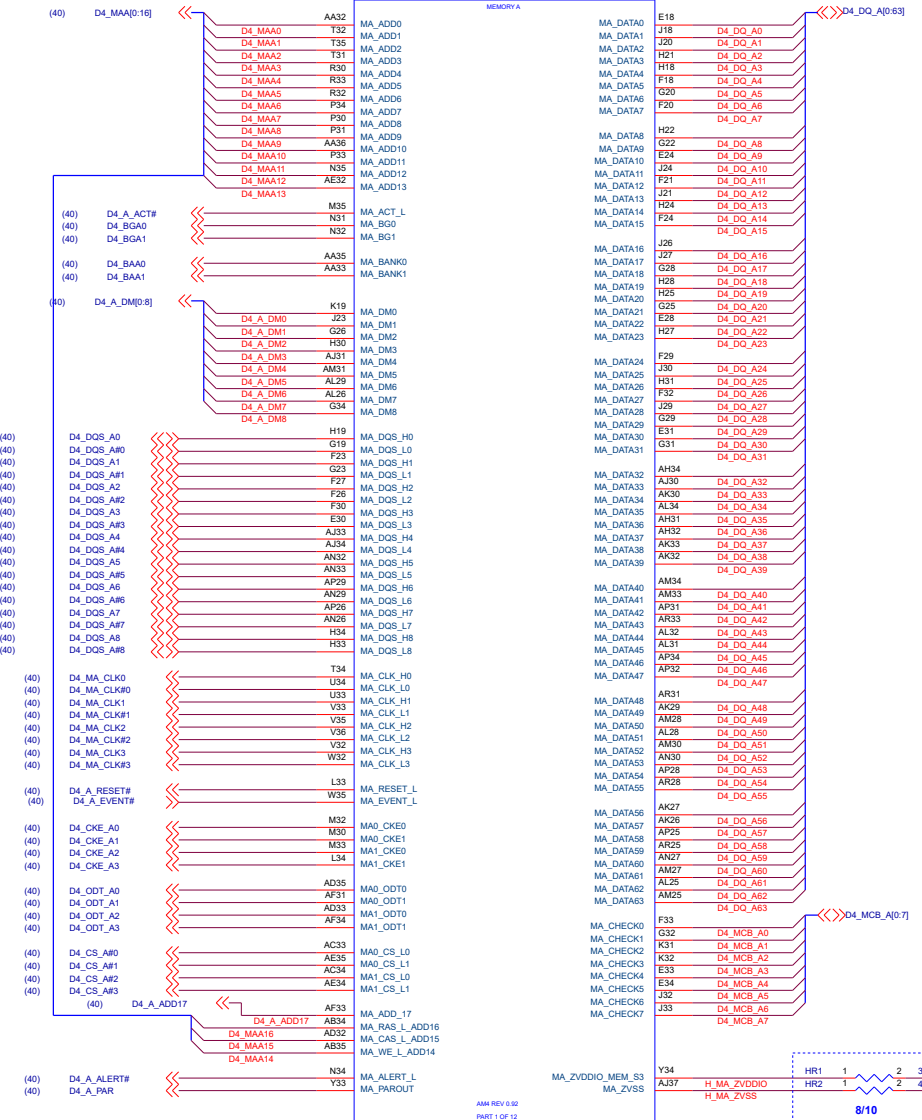
Connect LPC clock 1 to LPC devices that are powered in S0.

Connect LPC clock 0 to LPC devices that are powered in S5 only if the integrated microcontroller (IMC) is enabled.

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# SOCKET1331



SOCKET1331

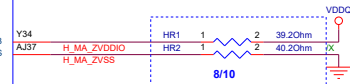
12001V00210200

mba\_socket1331\_4scwwhole\_col

AM REV 0.02

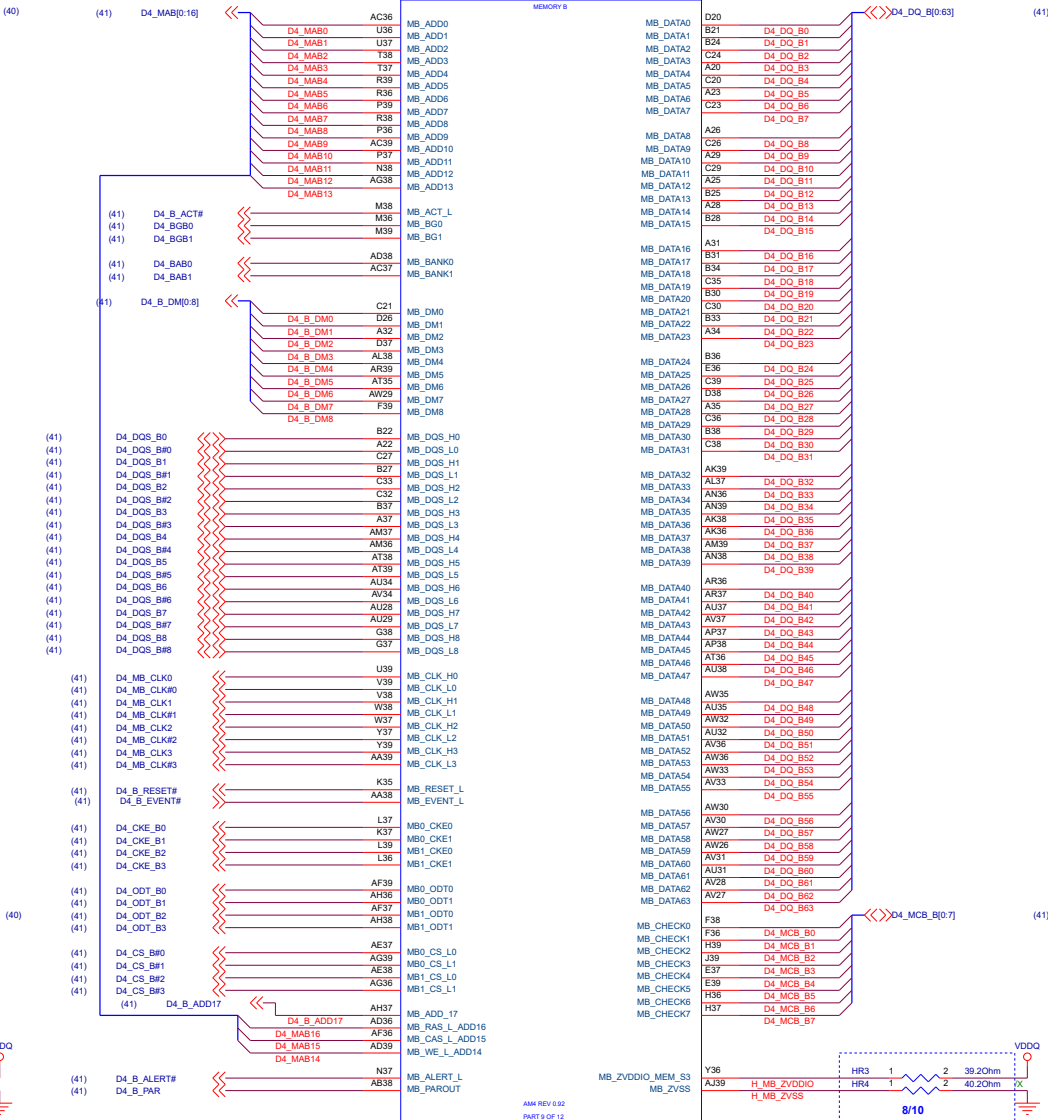
PART 1 OF 12

MA\_VDDIO\_MEM\_S3  
MA\_ZVSS



HR1,HR2,HR3,HR4  
Place Within 1.5" Of APU

# SOCKET1331



SOCKET1331

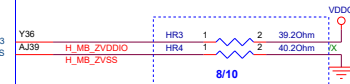
12001V00210200

mba\_socket1331\_4scwwhole\_col

AM REV 0.02

PART 5 OF 12

MB\_VDDIO\_MEM\_S3  
MB\_ZVSS



HR1,HR2,HR3,HR4  
Place Within 1.5" Of APU

Note:  
Type0 APU only:HR1,HR3



Title : AM4-01

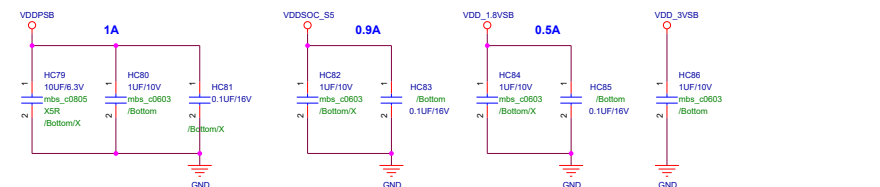
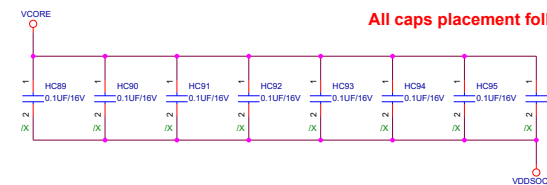
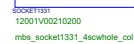
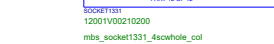
ASUSTek Computer Inc. Engineer: ElaineX\_Li

Size Project Name

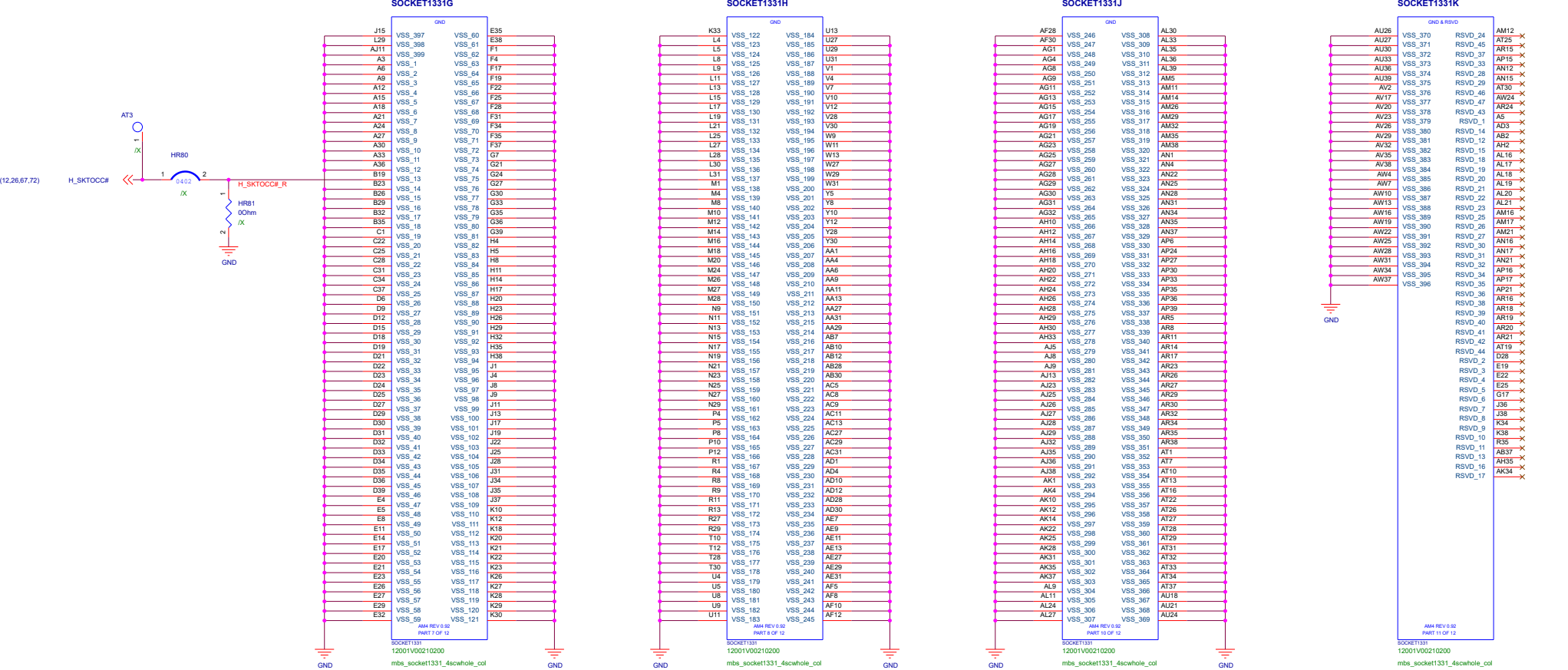
A3 AM4

Date: Wednesday, August 29, 2018 Sheet 31 of 117

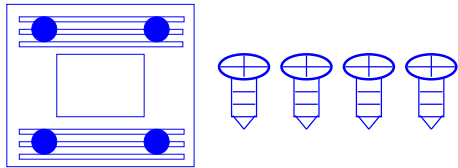
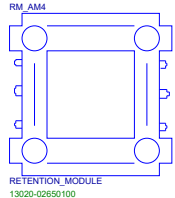
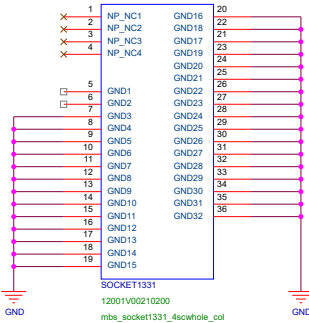
Rev 0.01

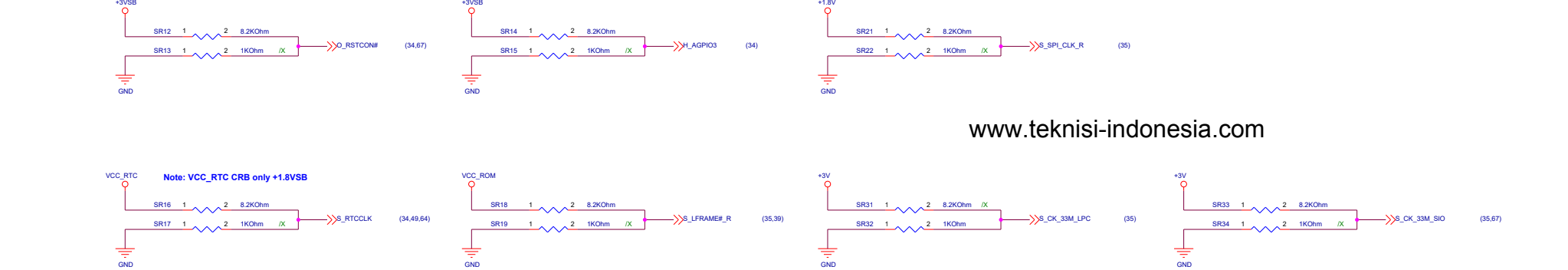


**All caps placement follow layout**



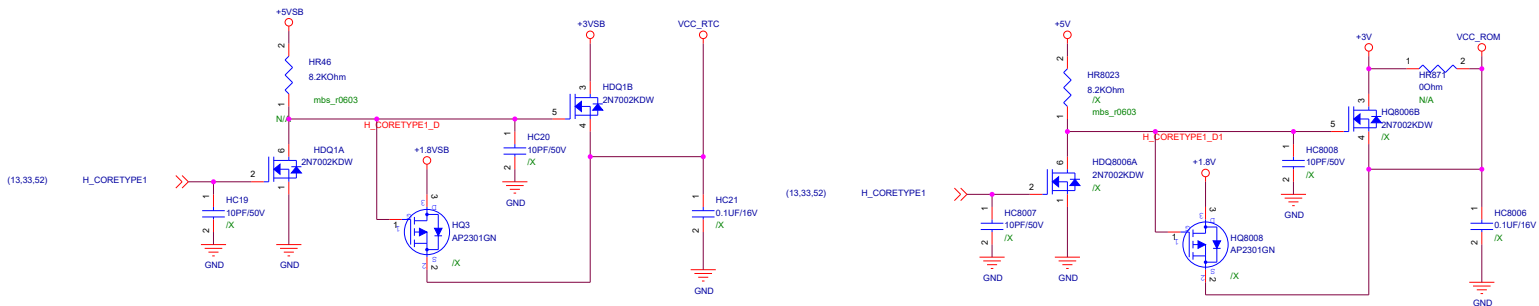
SOCKET1331M





	TYPE0 2	TYPE0	TYPE0	TYPE0	TYPE0	TYPE0	TYPE1 2 3
PIN	LFRAME_L	LPCCLK1	LPCCLK0	RTCCLK	SYS_RESET_L	AGPIO3	SPI_CLK(ZP)
NET	S_LFRAME#_R	C_LPC_TPM	C_LPC_SIO_R	S_RTCCLK	O_RSTCON#	H_AGPI03	S_SPI_CLK
PULL HIGH	SPI ROM Default	48M source and generate both internal and external clocks Default	Boot Fail Timer Enabled	Coin Battery is onboard Default	Normal Reset Mode Default	Enhanced Reset logic for faster resume from S5 Default	48M source and generate both internal and external clocks Default
PULL LOW	LPC ROM	100M source and generate internal clock only	Boot Fail Timer Disabled Default	Coin Battery is onboard	Short Reset Mode	Traditional Reset logic	100M source and generate internal clock only

CORETYPE1	CORETYPE0	Family/Model NO.	AM4 Type
0	0	Family 15h/Models 60h-6Fh	Type 0 Bristol
0	1	Reserved	Reserved
1	1	Family 17h/Models 20h-2Fh	Type 1 Raven-2
1	0	Family 17h/Models 00h-0Fh	Type 2 Summit/Pinnacle
1	1	Family 17h/Models 10h-1Fh	Type 3 Raven-1



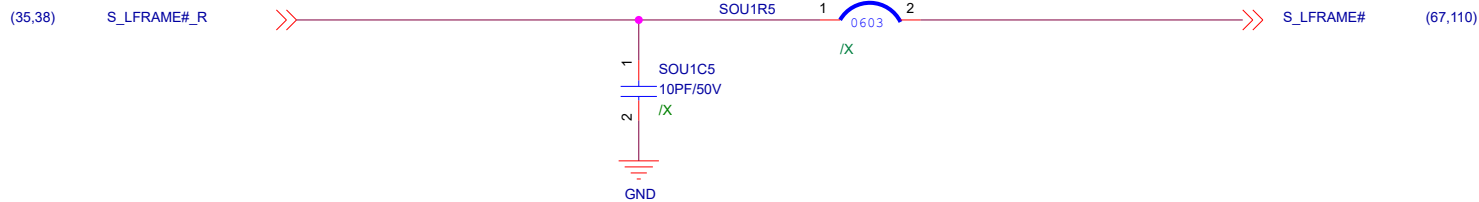
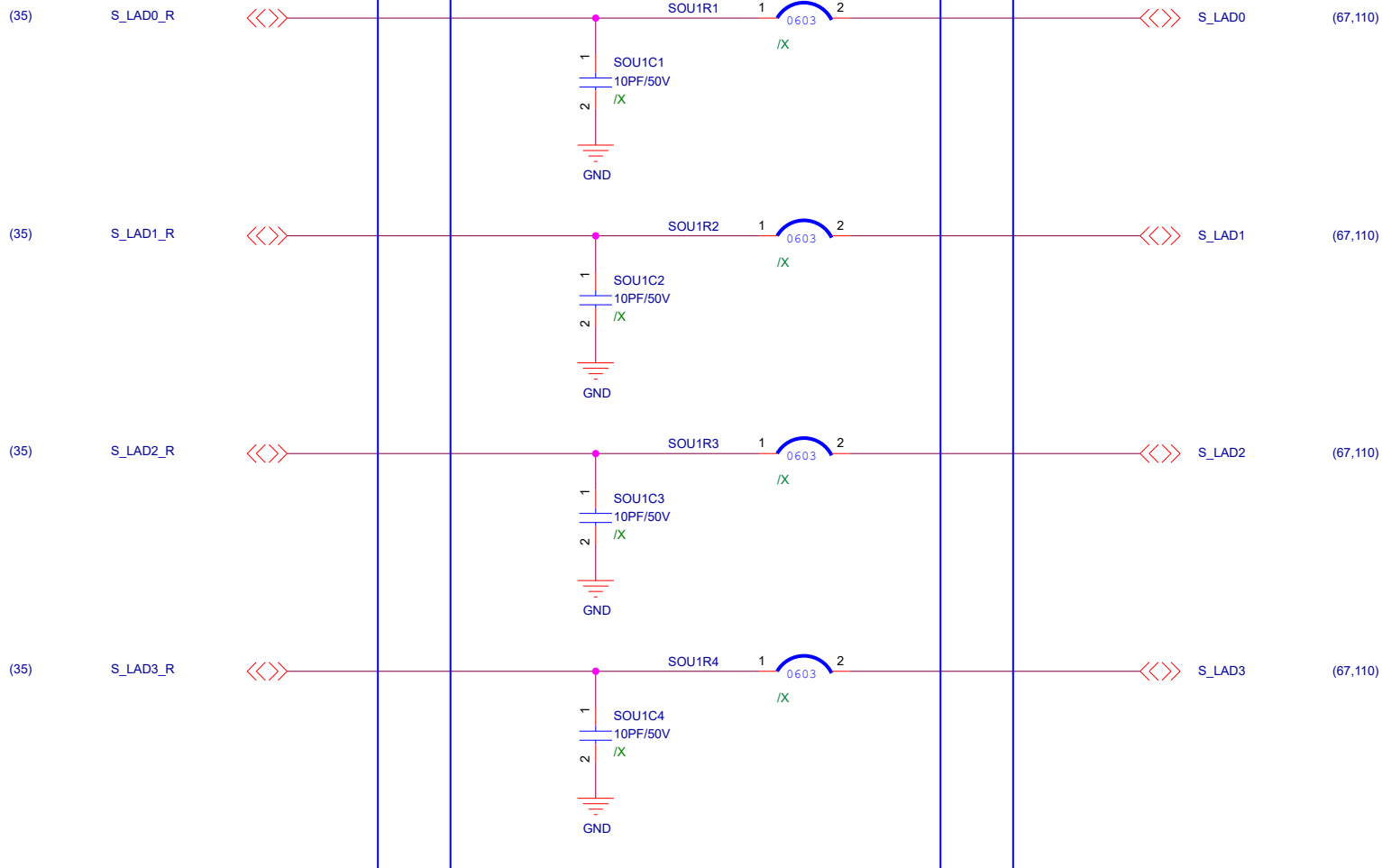
APU TYPE	H_CORETYPE1	VCC_RTC
Type0	0	+3VSB
Type2,3	1	+1.8VSB



# APU SIDE

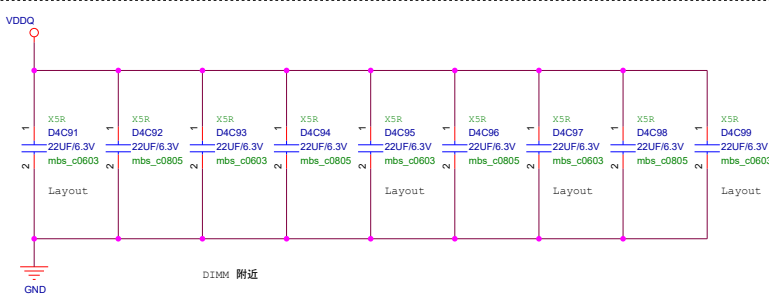
# Place near SIO

# SIO SIDE

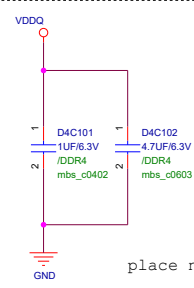




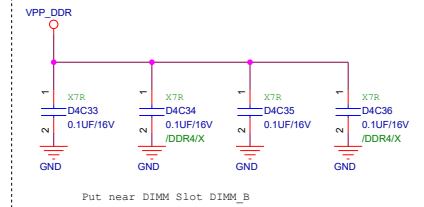
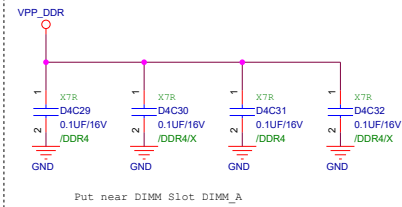
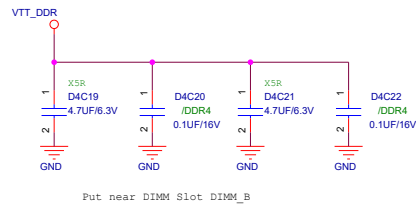
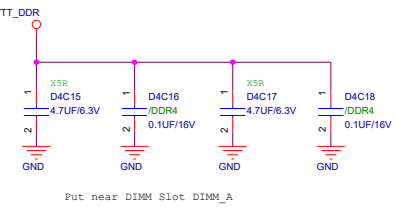
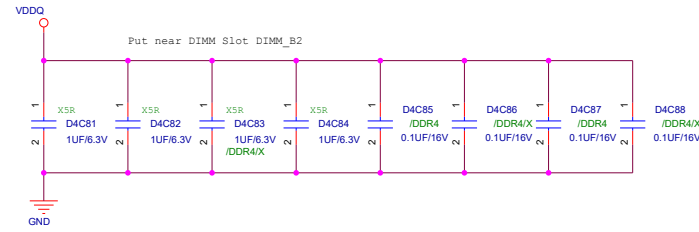
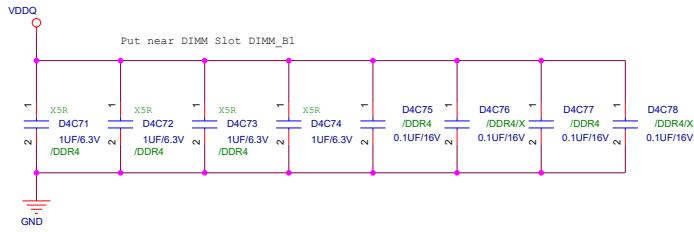
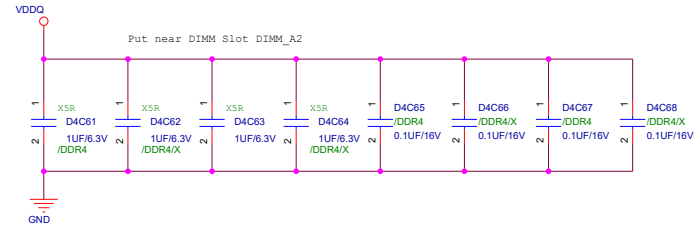
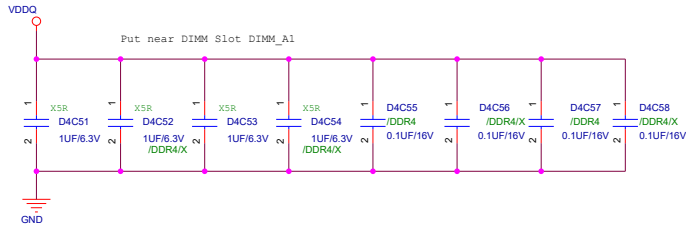
Layout to 0603



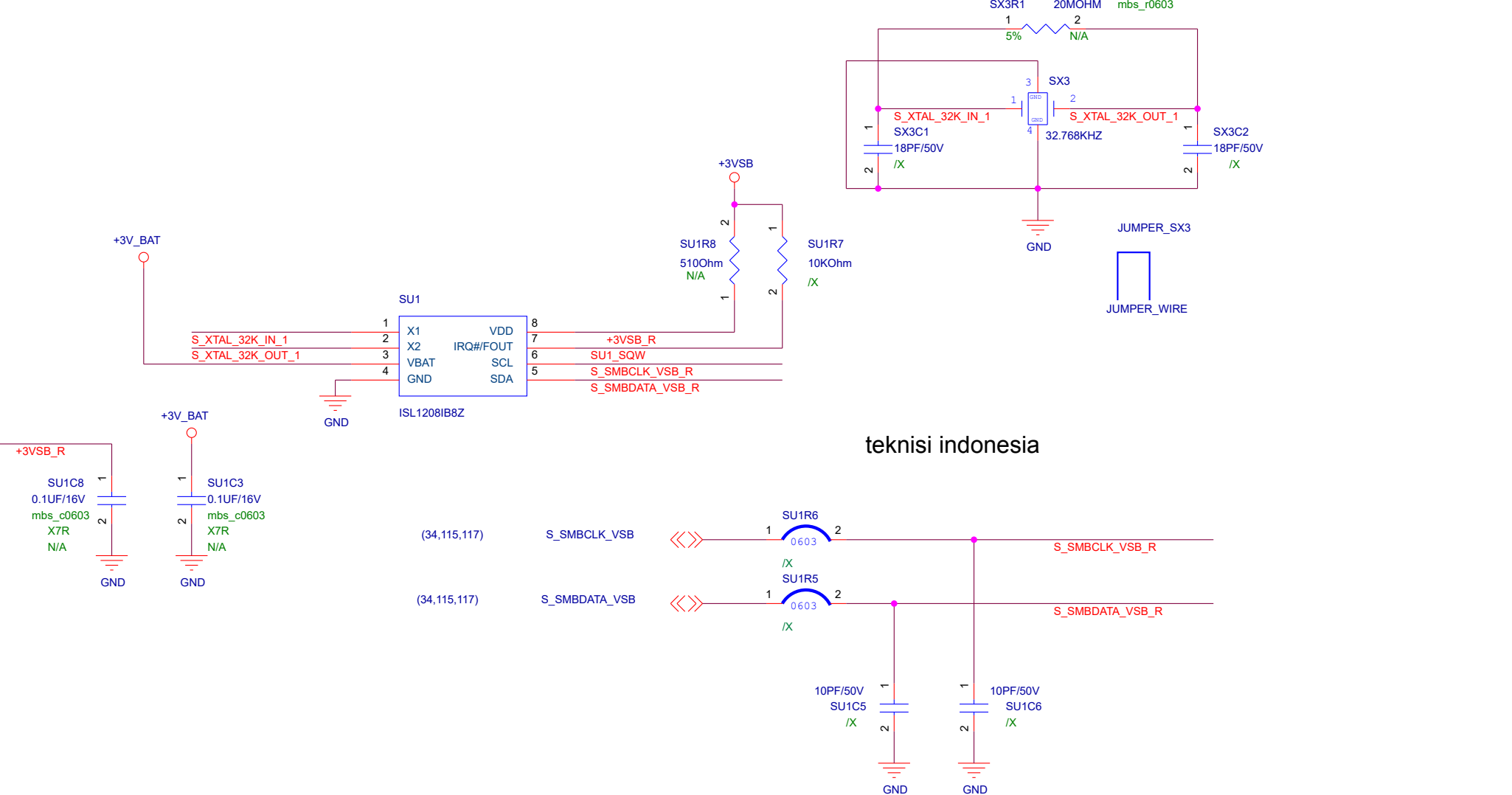
DIMM 附近



place near DIMM\_B2







Title		
<Title>		
Size	Document Number	Rev
A	<Doc>	<RevCode>
Date:	Wednesday, August 29, 2018	Sheet 44 of 117



**Title :** **DP\_MUX\_PS8331**

**ASUSTeK COMPUTER INC**

**Engineer:** **Morse\_Peng**

Size

**A2**

Project Name

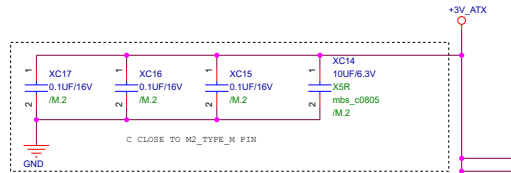
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Rev

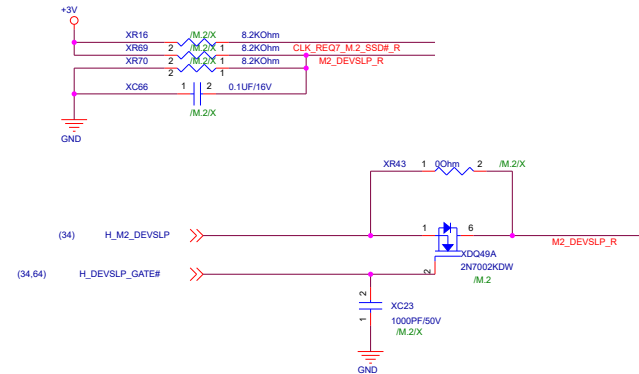
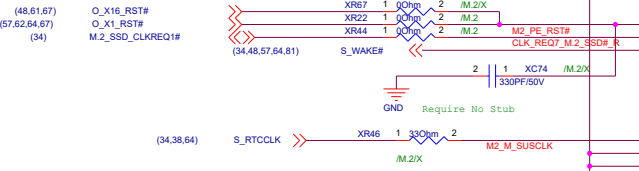
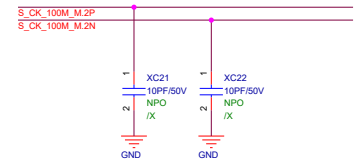
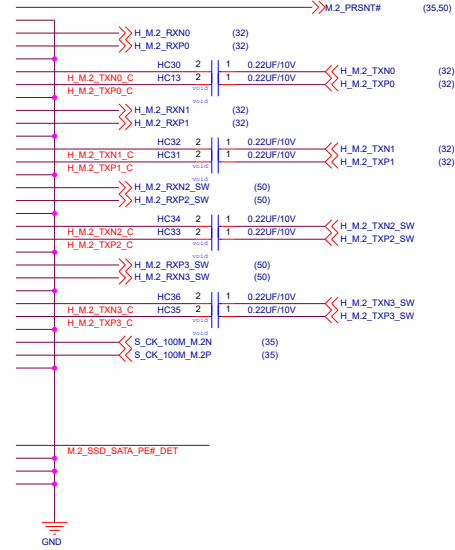
**R1.00**

Date: **Friday, August 17, 2018**

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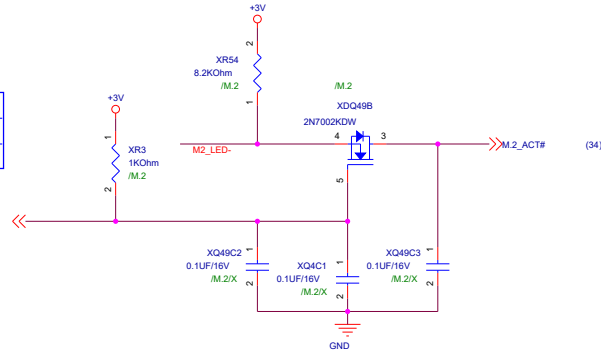


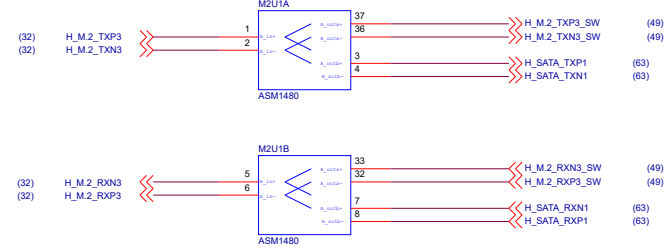
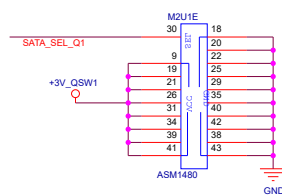
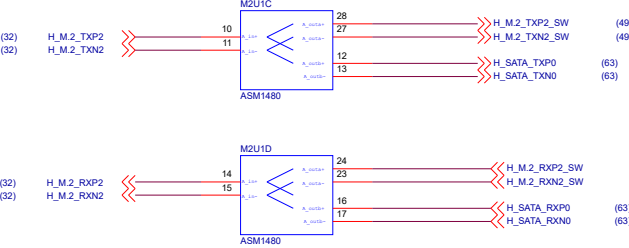
### M.2\_1(SOCKET3)



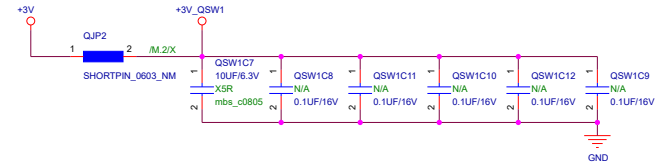
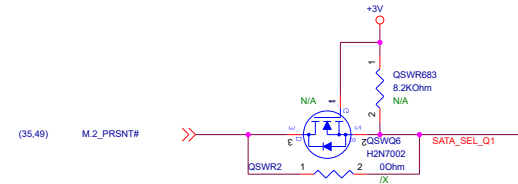
M.2_SSD_PEDET	
0	M.2 SATA Mode
1	M.2 PCIe Mode

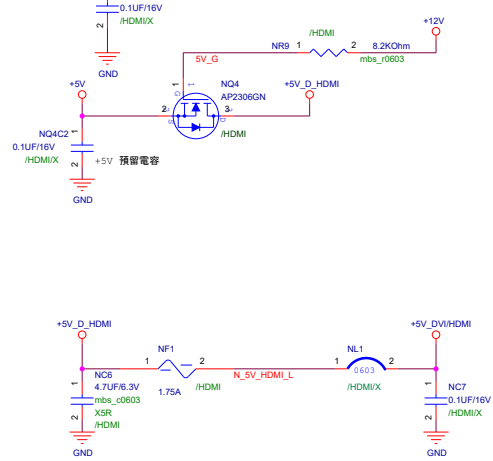
(34) M2\_SSD\_SATA\_PER\_DET





M.2_PRSNT#	Function	
L	N_in to N_outa	M.2
H	N_in to N_outb	SATA



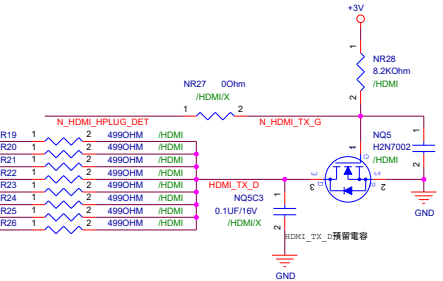


The image displays three circuit diagrams for connecting Del for EMS components. Each diagram shows a component with multiple pins connected to various signals and ground.

**Diagram 1 (Top):** Shows component **ND3** (AZ1045-04F /HDMI/X). It has 9 pins. Pin 1 is connected to **H\_HDMI\_TXCN\_R**. Pin 2 is connected to **H\_HDMI\_TXCP\_R**. Pin 3 is connected to **H\_HDMI\_TXDND\_R**. Pin 4 is connected to **H\_HDMI\_TXDP0\_R**. Pin 5 is connected to **GND**. Pin 6 is connected to **NC1**. Pin 7 is connected to **NC2**. Pin 8 is connected to **NC3**. Pin 9 is connected to **NC4**.

**Diagram 2 (Middle):** Shows component **ND4** (AZ1045-04F /HDMI/X). It has 9 pins. Pin 1 is connected to **H\_HDMI\_TXDN1\_R**. Pin 2 is connected to **H\_HDMI\_TXDP1\_R**. Pin 3 is connected to **H\_HDMI\_TXDN2\_R**. Pin 4 is connected to **H\_HDMI\_TXDP2\_R**. Pin 5 is connected to **GND**. Pin 6 is connected to **NC1**. Pin 7 is connected to **NC2**. Pin 8 is connected to **NC3**. Pin 9 is connected to **NC4**.

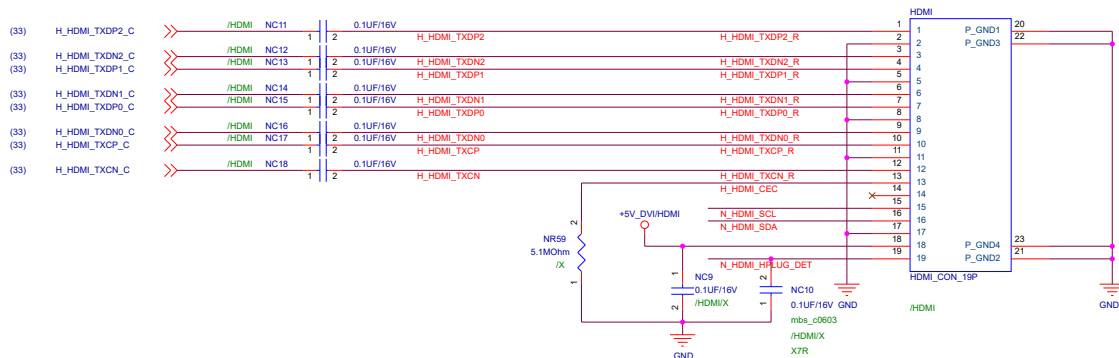
**Diagram 3 (Bottom):** Shows component **ND2** (IP4225C2B /HDMI/X). It has 6 pins. Pin 1 is connected to **N\_HDMI\_SCL**. Pin 2 is connected to **GND**. Pin 3 is connected to **N\_HDMI\_HPLUG\_DET**. Pin 4 is connected to **X**. Pin 5 is connected to **+5V\_D\_HDMI**. Pin 6 is connected to **N\_HDMI\_SDA**.



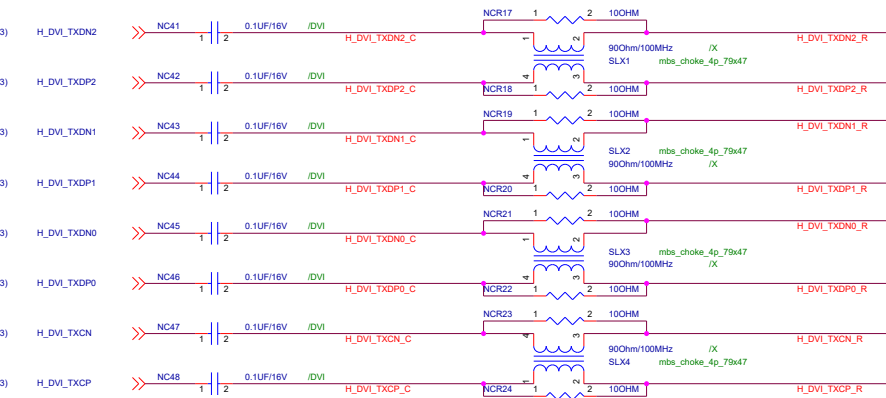
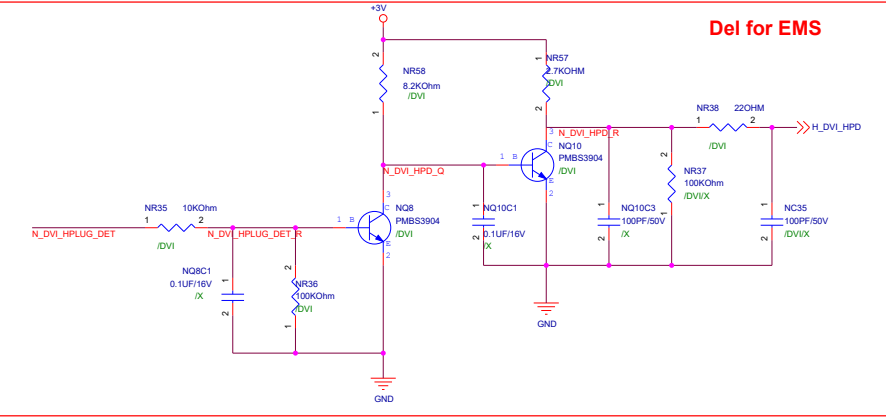
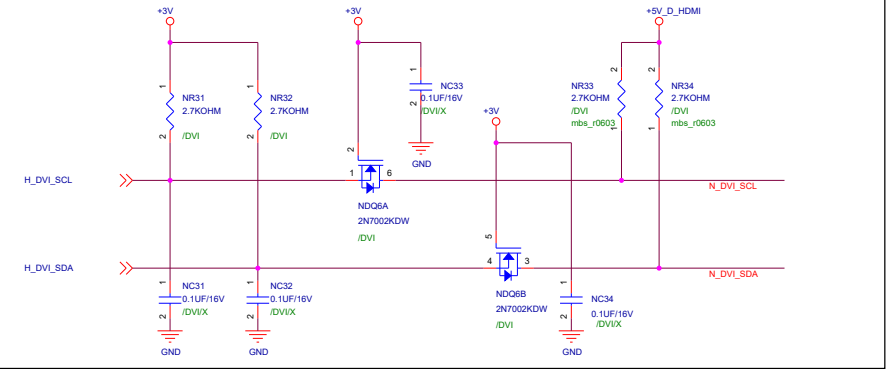
Del for EMS

(33)

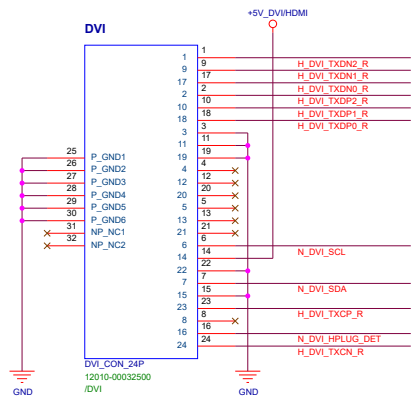
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DVI I2C clk&Data Levelshift

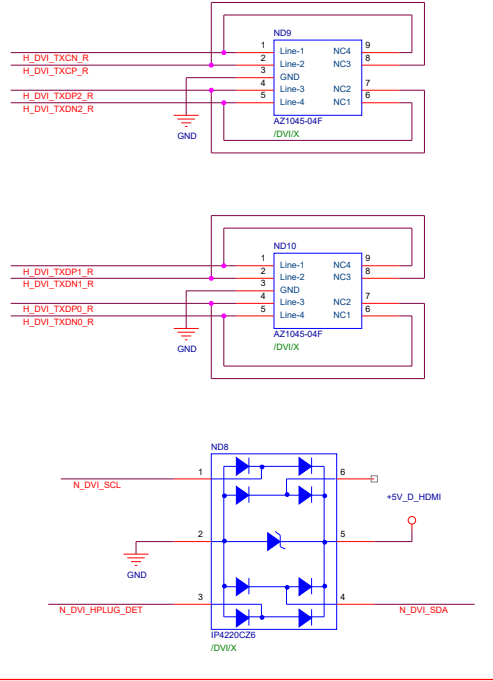


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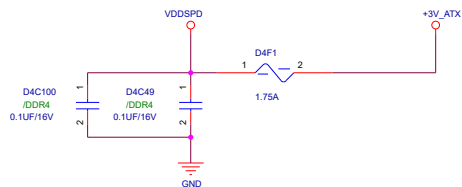
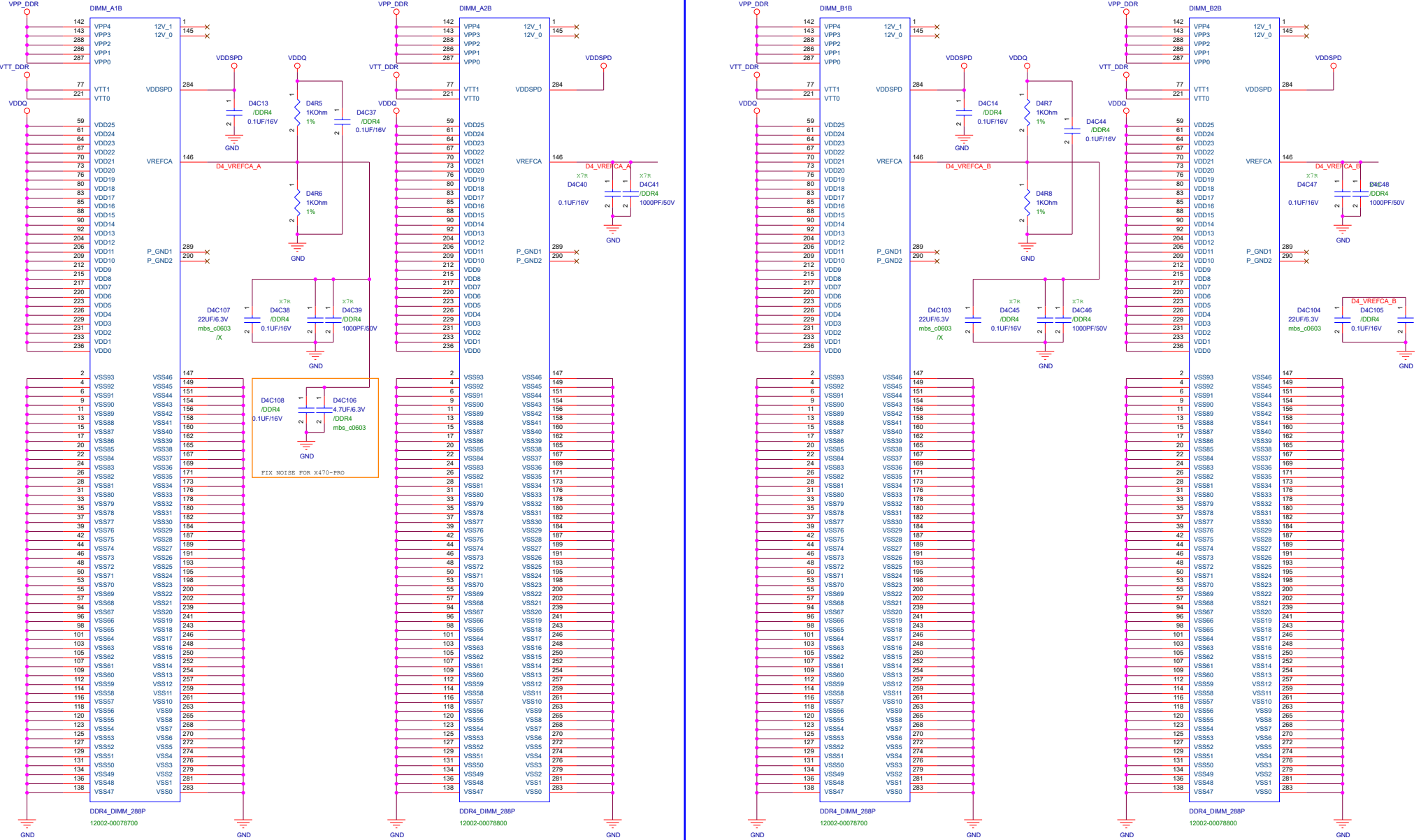


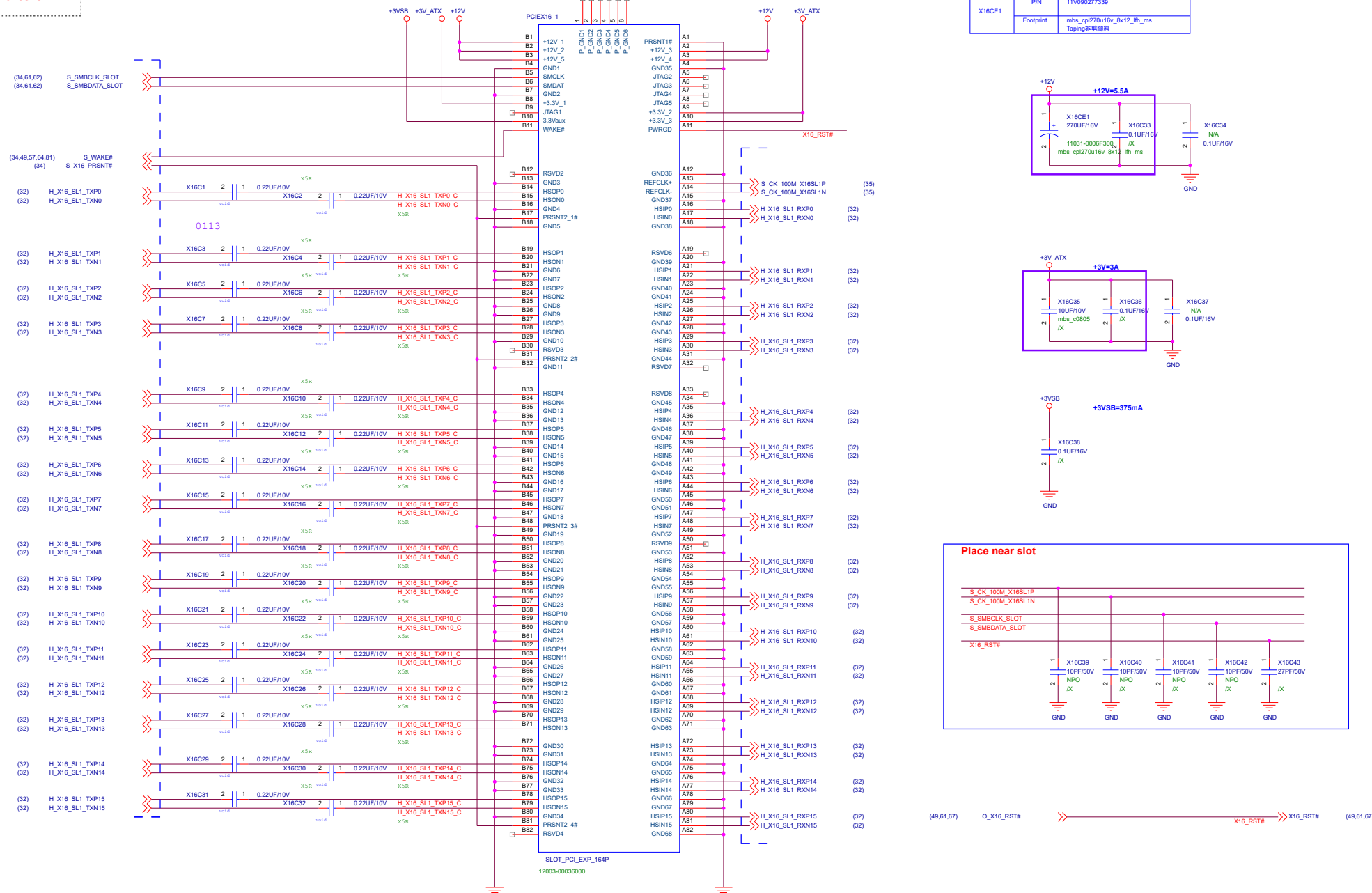
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Del for EMS

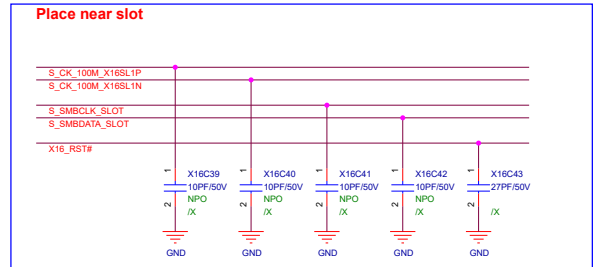
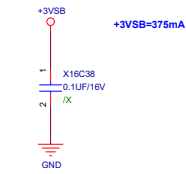
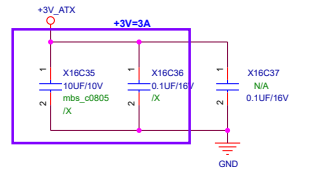
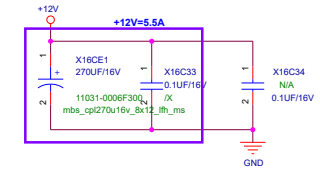




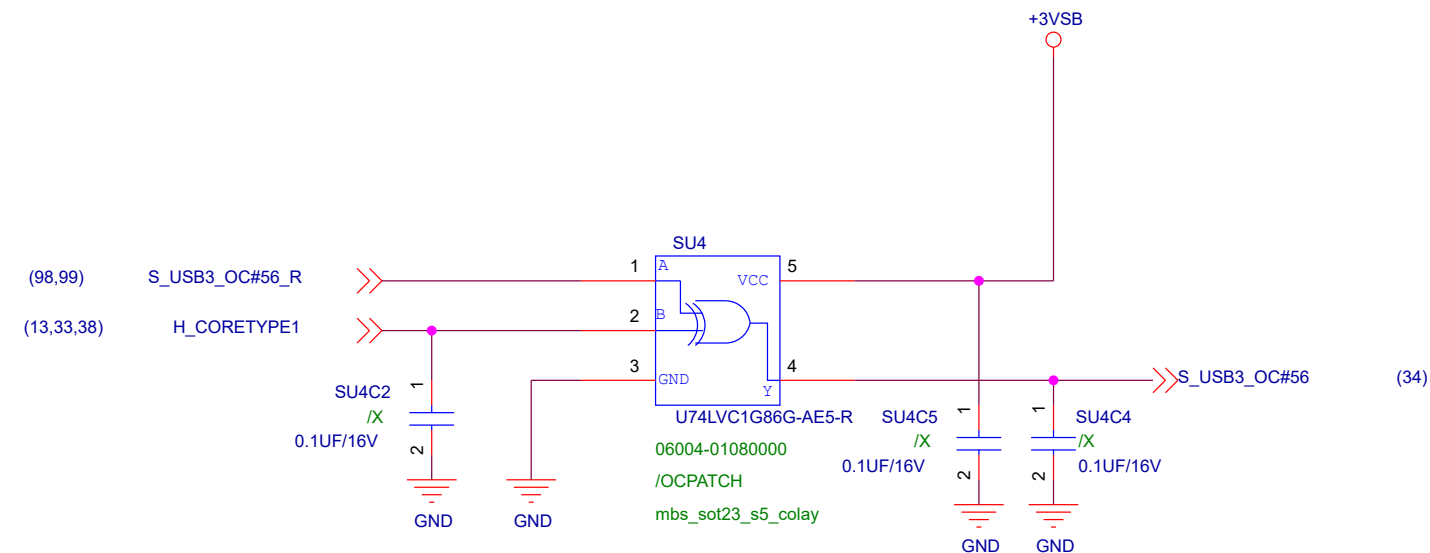
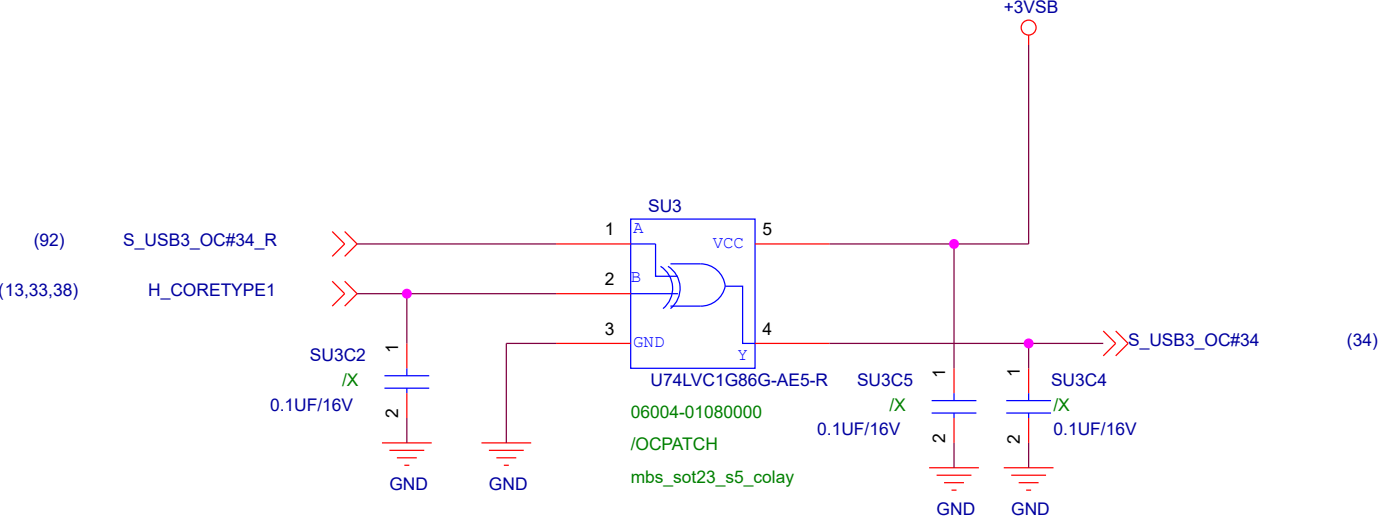





X16E1	PIN	11V090277339
	Footprint	mbs_cpl270u16v_8x12_1h_ms Taping非剥離材



包鐵殼透明灰 (不放燈) :  
12003-00036000  
Symbol:s\_pci\_exp\_164p\_6hod\_fox\_if3

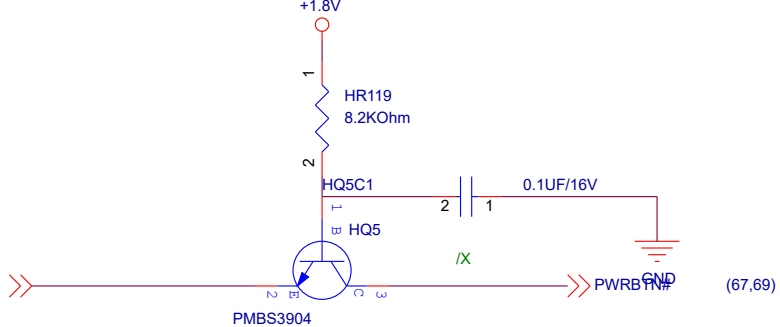


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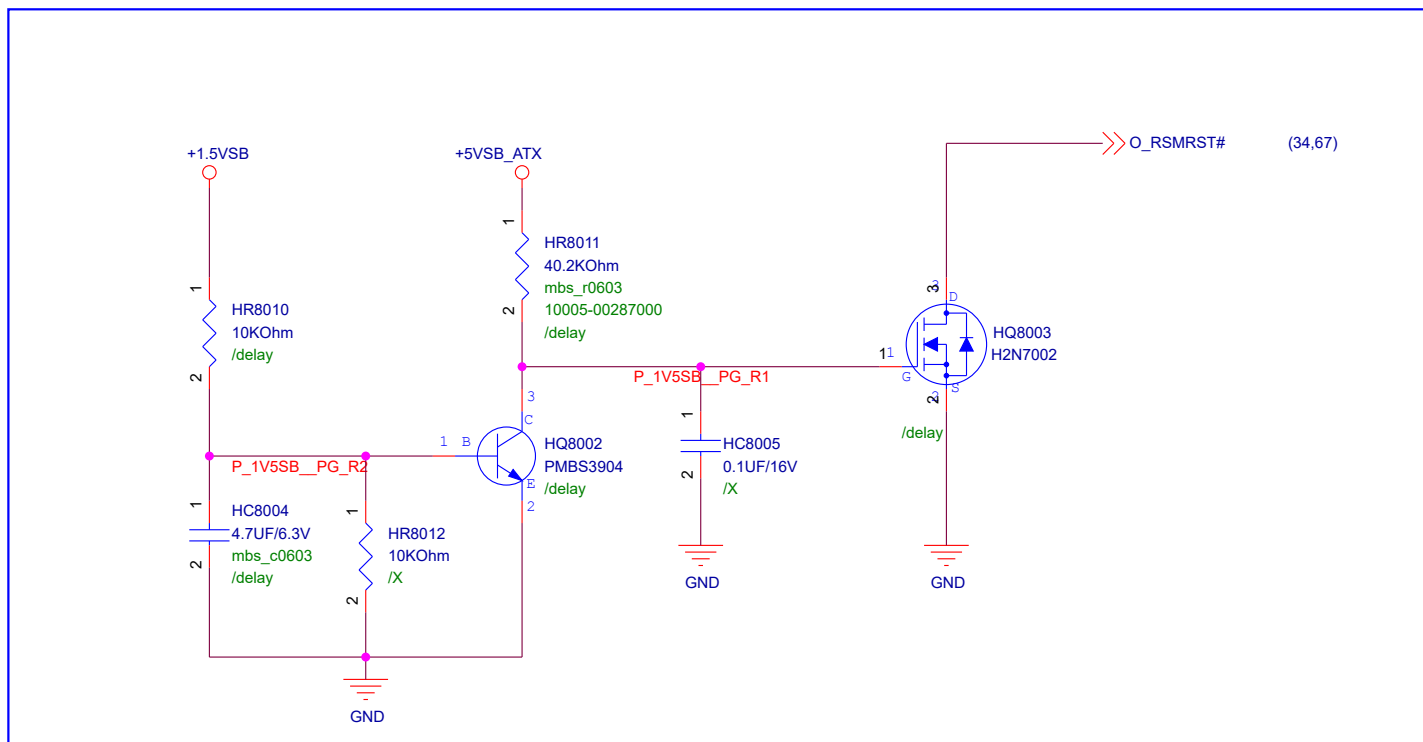
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ASUSTEK COMPUTER INC		<b>Engineer:</b>	
Size A4	Project Name		Rev 0.0
Date: Wednesday, August 29, 2018		Sheet 52 of 117	

(6,33)

H\_THERMTRIP#

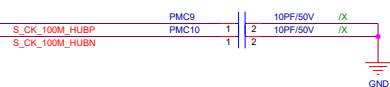


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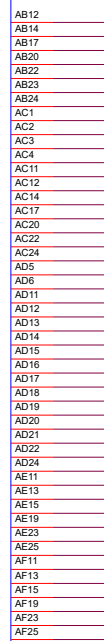
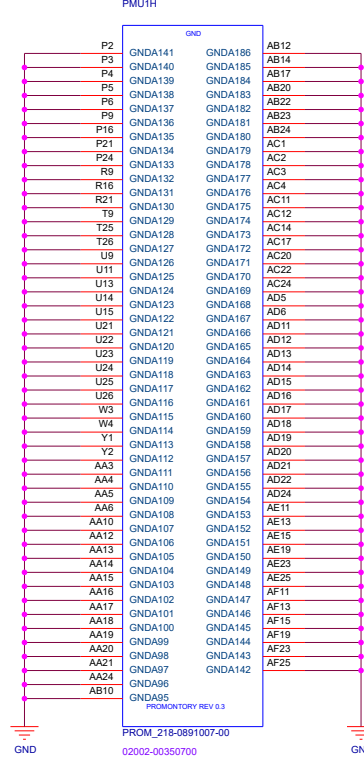
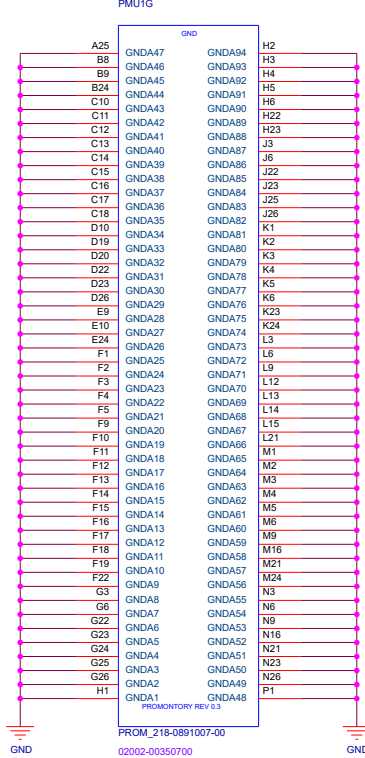
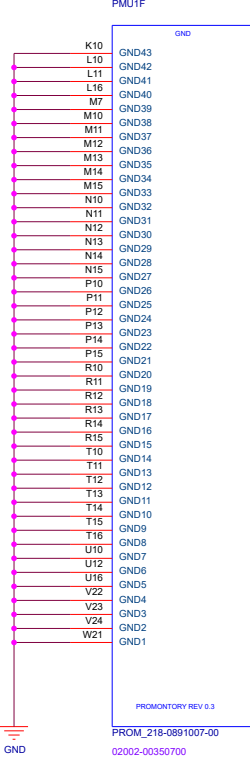


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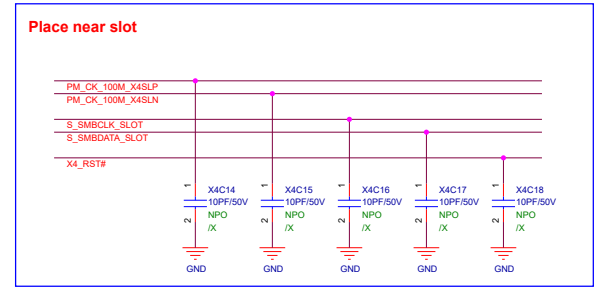
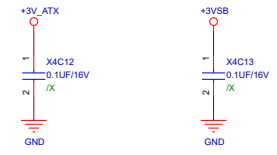
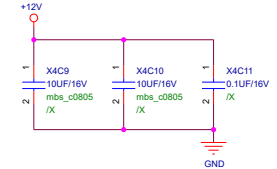
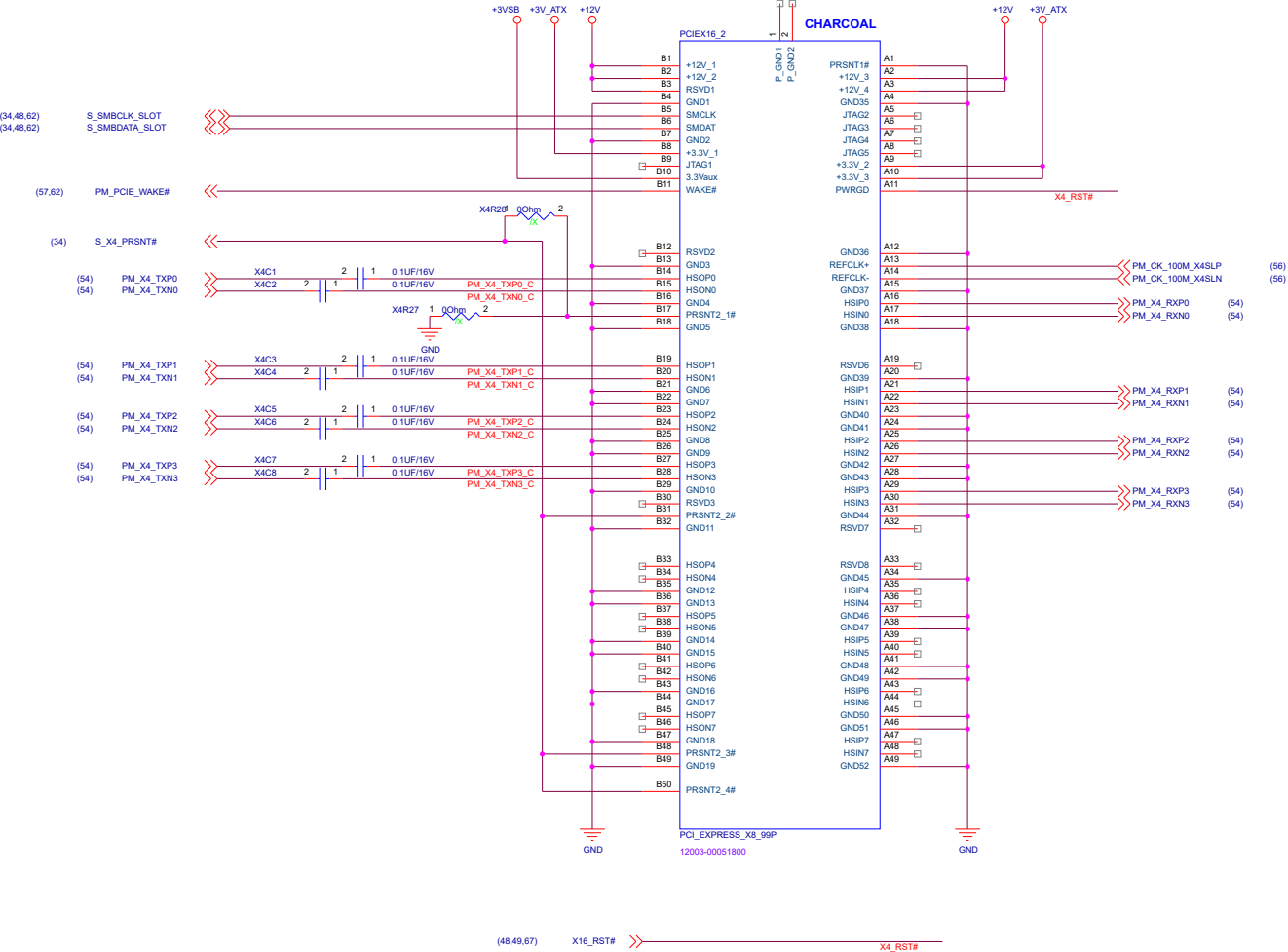


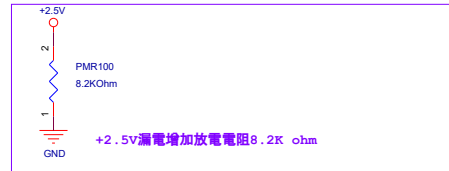
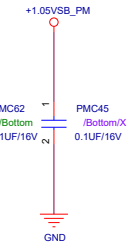
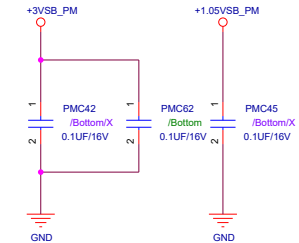
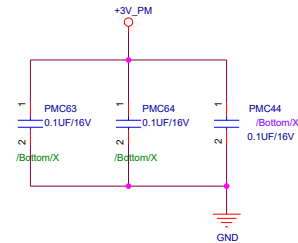
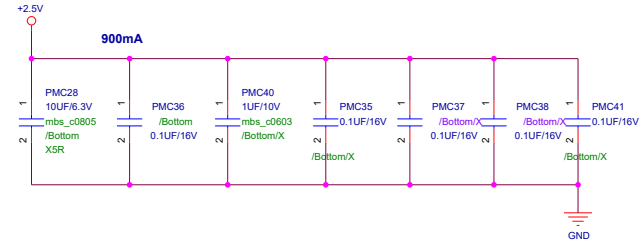
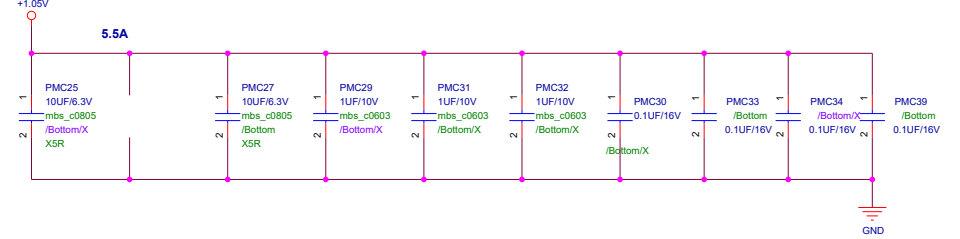
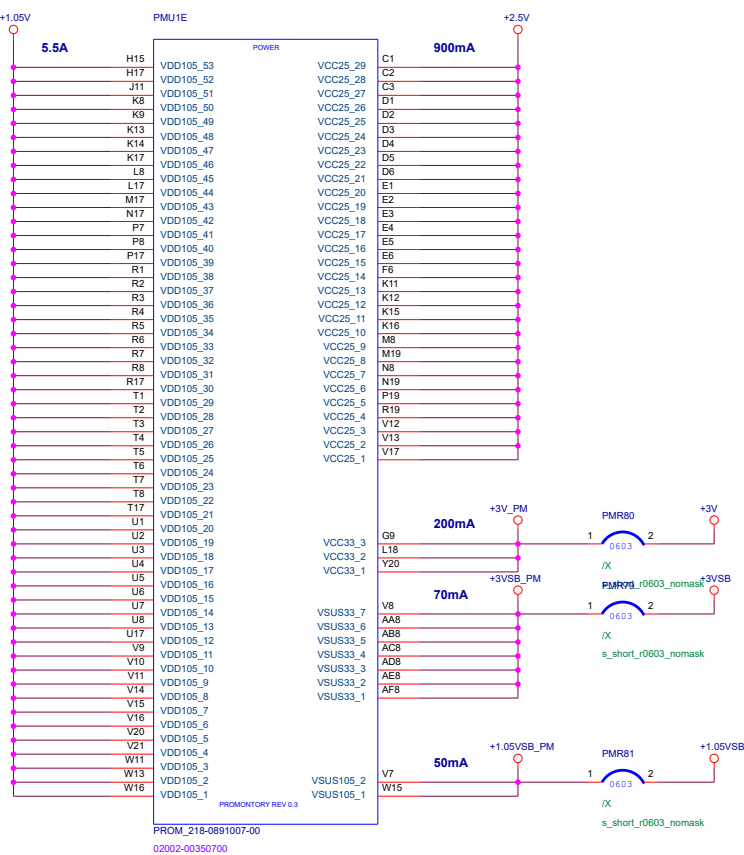


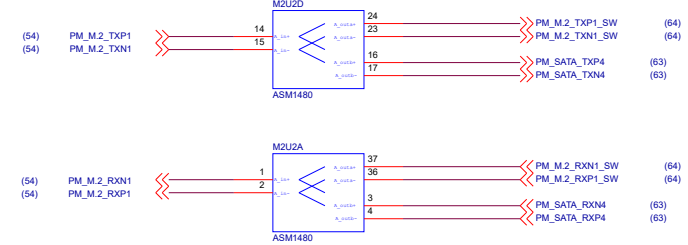
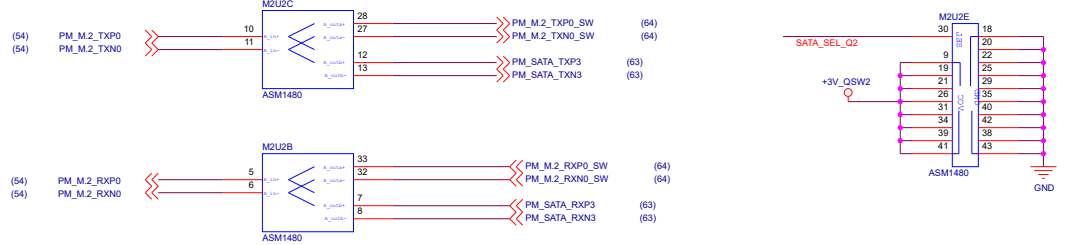




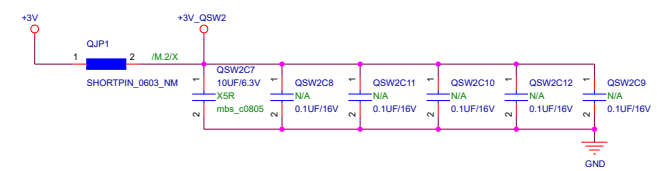
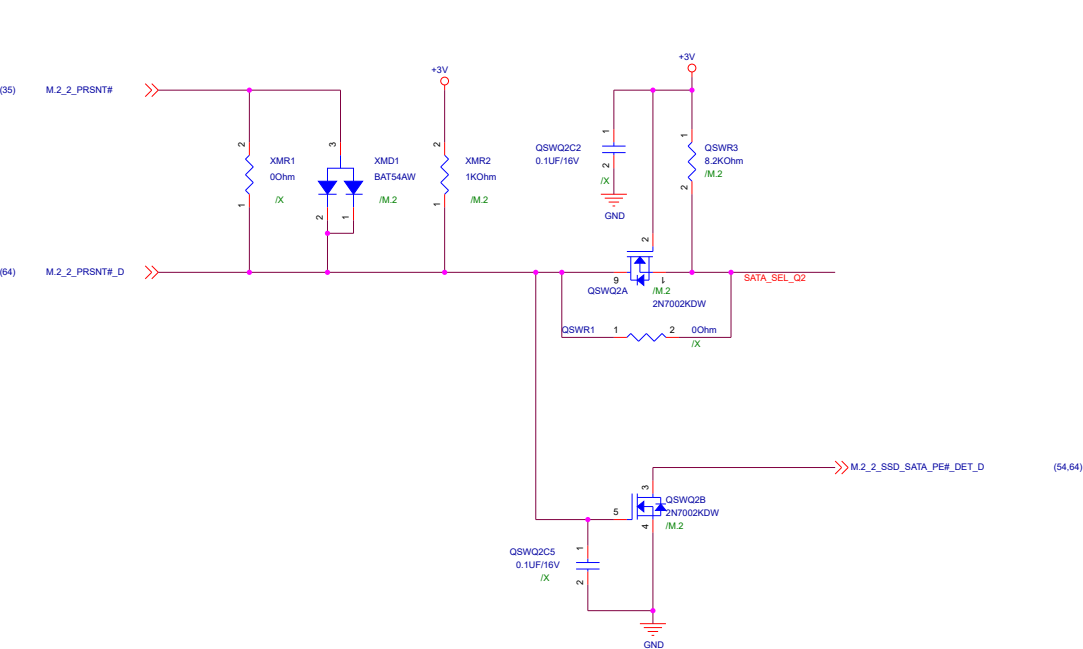


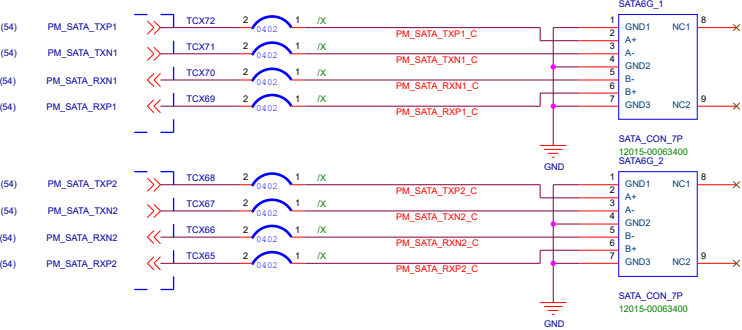




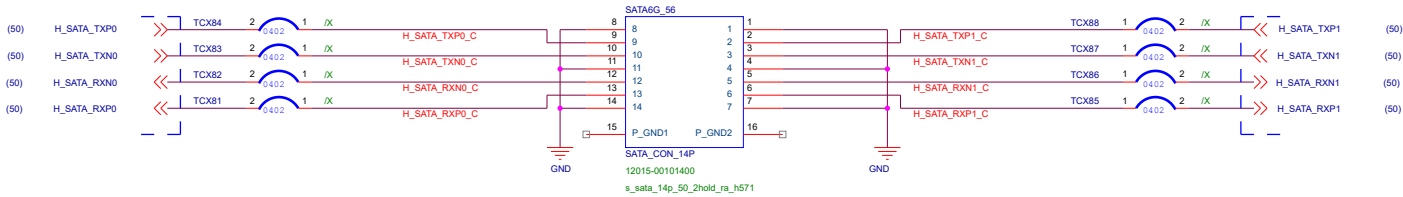
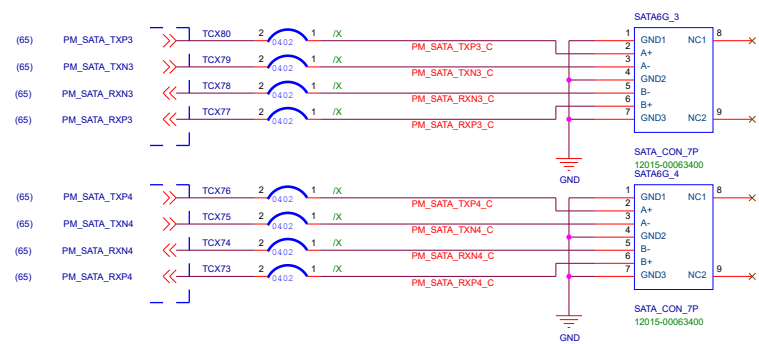


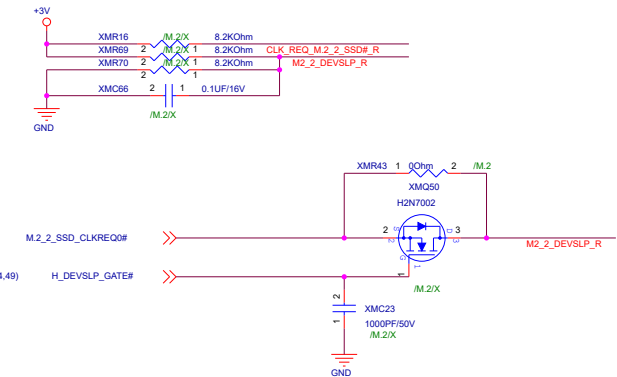
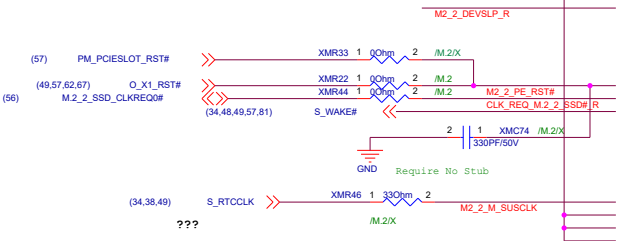
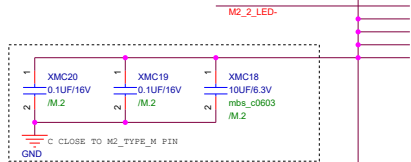
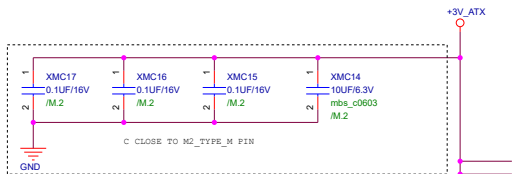
M.2_PRSNT#	Function	
L	N_in to N_outa	M.2
H	N_in to N_outb	SATA





for Pad reference 層挖空

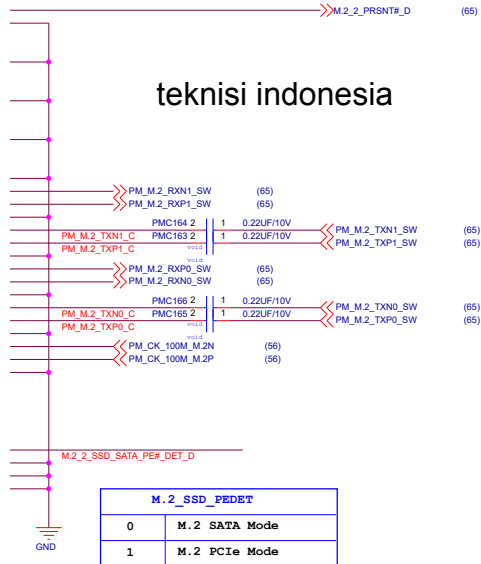




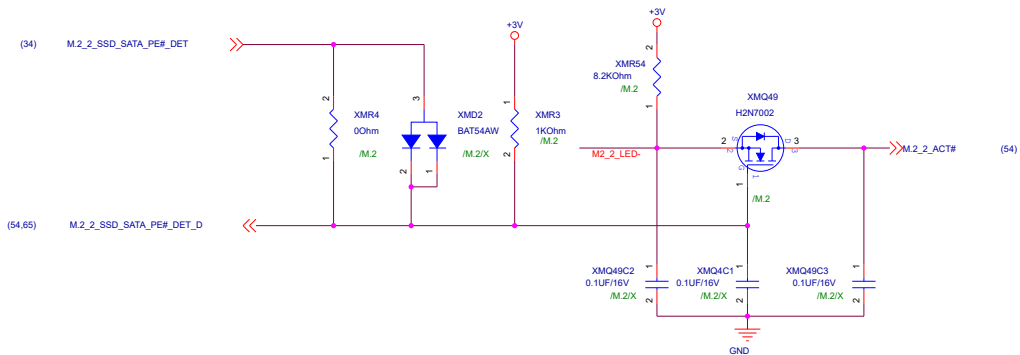
## M.2\_2(SOCKET3)



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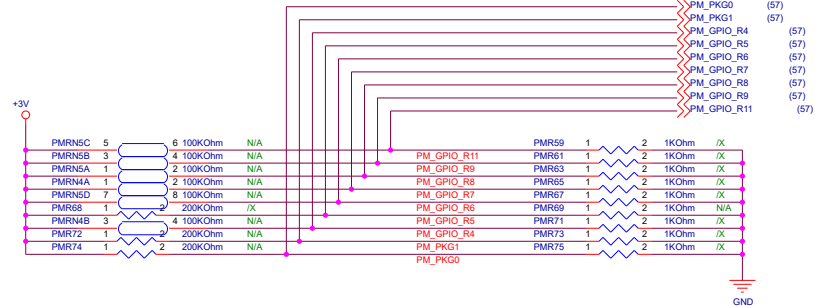


M.2_SSD_PEDET	
0	M.2 SATA Mode
1	M.2 PCIe Mode



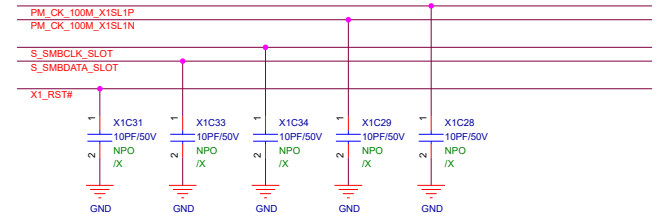
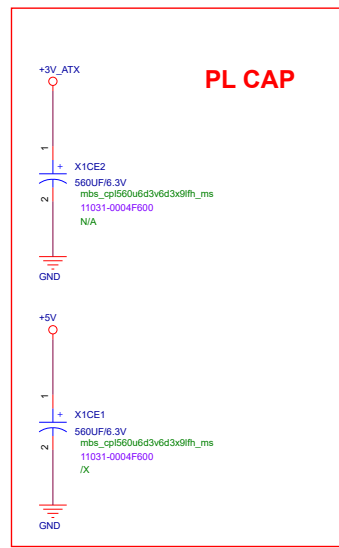
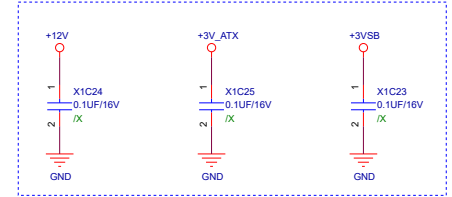
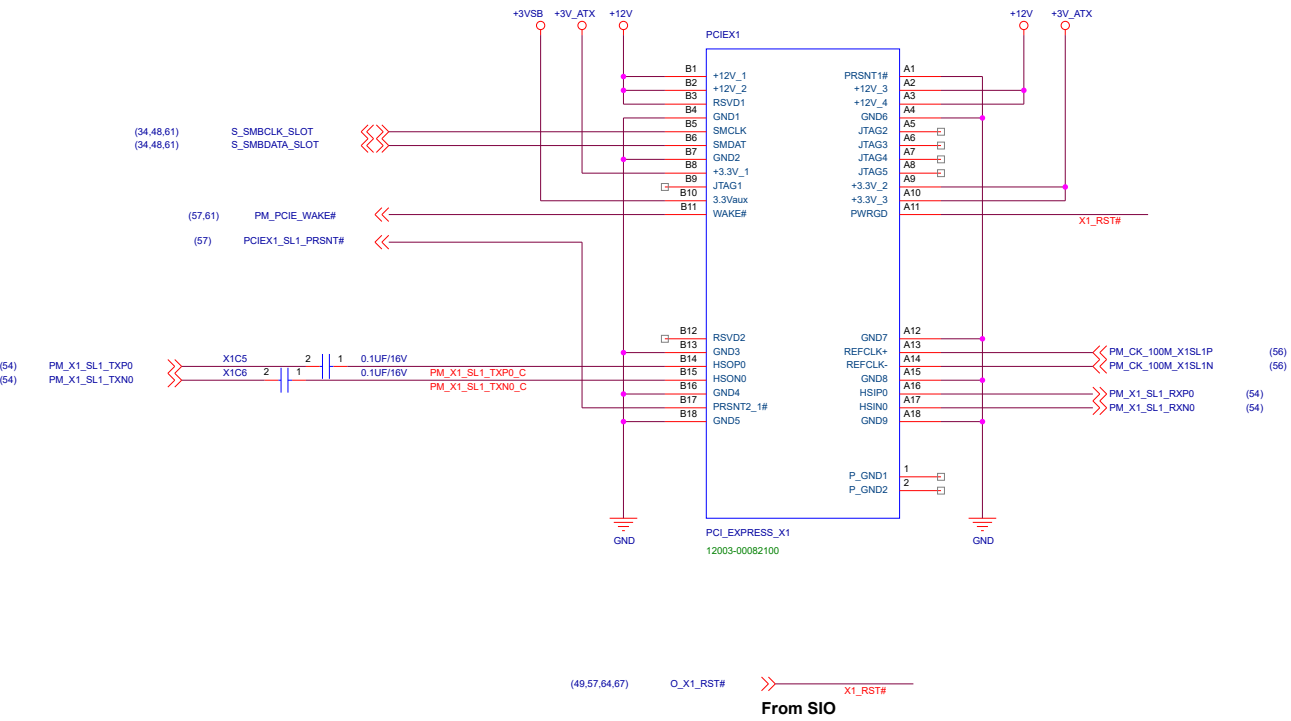
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Size	Document Number	Rev
A	<Doc>	<RevCode>
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UART_TX	PCIe Group 1 configuration: Pull-up resistor to VCC33 is implemented of value:	1	200 k	$\Omega$
	PCIe Group 1 configuration: Pull-down resistor to VSS is implemented of value:	1	1 k	$\Omega$
SPI_SDI	PCIe Group 1 configuration: Pull-up resistor to VCC33 is implemented of value:	1	200 k	$\Omega$
	PCIe Group 1 configuration: Pull-down resistor to VSS is implemented of value:	1	1 k	$\Omega$
SPI_SDO	PCIe Group 0 configuration: Pull-up resistor to VCC33 is implemented of value:	1	200 k	$\Omega$
	PCIe Group 0 configuration: Pull-down resistor to VSS is implemented of value:	1	1 k	$\Omega$
SPI_SCK	PCIe Group 0 configuration: Pull-up resistor to VCC33 is implemented of value:	1	200 k	$\Omega$
	PCIe Group 0 configuration: Pull-down resistor to VSS is implemented of value:	1	1 k	$\Omega$
DEBUG_ENABLE	Debug Mode: Pull-up resistor to VCC33 is implemented of value:	1	200 k	$\Omega$
	Function Mode (default): Pull-down resistor to VSS is implemented of value:	1	1 k	$\Omega$
TESTEN	TEST mode enable: Pull-up resistor to VCC33 is implemented of value:	1	200 k	$\Omega$
	Function Mode (default): Pull-down resistor to VSS is implemented of value:	1	1 k	$\Omega$

GPIO_R[4]	GPP clock source from APUCCLK implemented (default):	1	200 k	$\Omega$
	Pull-up resistor to VCC33 is implemented of value:	1	1 k	$\Omega$
GPIO_R[5]	GPP clock source from Crystal Implemented:	1	200 k	$\Omega$
	Pull-up resistor to VCC33 is implemented of value:	1	1 k	$\Omega$
	USB SSC disable implemented (default):	1	200 k	$\Omega$
GPIO_R[6]	Pull-up resistor to VCC33 is implemented of value:	1	1 k	$\Omega$
	Pull-down resistor to VSS is implemented of value:	1	200 k	$\Omega$
	SATA SSC disable implemented (default):	1	1 k	$\Omega$
GPIO_R[7]	Pull-up resistor to VCC33 is implemented of value:	1	1 k	$\Omega$
	SATA Express SSC disable implemented (default):	1	200 k	$\Omega$
	Pull-up resistor to VCC33 is implemented of value:	1	1 k	$\Omega$
GPIO_R[8]	Pull-down resistor to VSS is implemented of value:	1	200 k	$\Omega$
	GPP SSC disable implemented (default):	1	1 k	$\Omega$
	Pull-up resistor to VCC33 is implemented of value:	1	1 k	$\Omega$
GPIO_R[9]	GPP SSC enable Implemented:	1	200 k	$\Omega$
	Pull-down resistor to VSS is implemented of value:	1	1 k	$\Omega$
	Whole Chip SSC disable implemented (default):	1	1 k	$\Omega$
GPIO_R[11]	Pull-up resistor to VCC33 is implemented of value:	1	200 k	$\Omega$
	Whole Chip SSC enable implemented.	1	1 k	$\Omega$
	Pull-down resistor to VSS is implemented of value:	1	1 k	$\Omega$

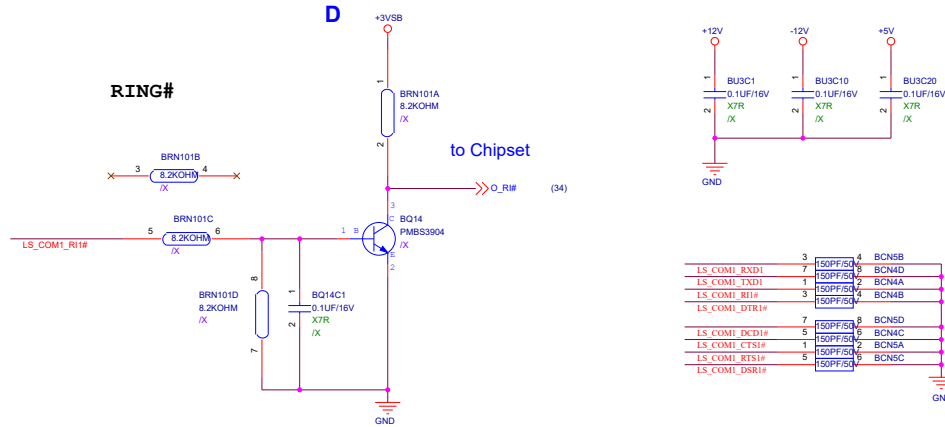
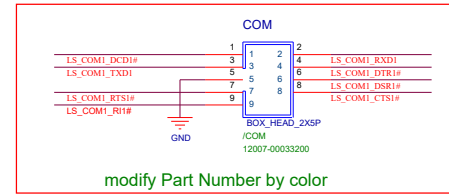


COM PORT

- A. Choose COM Port Connector/Header Type
- B. Choose use RI# to do Deep S4/S5 wake-up or not by Project
- C. Modify Part Number of COM Connector/Header by Color
- D. Modify O\_RI# pill-high power by Project

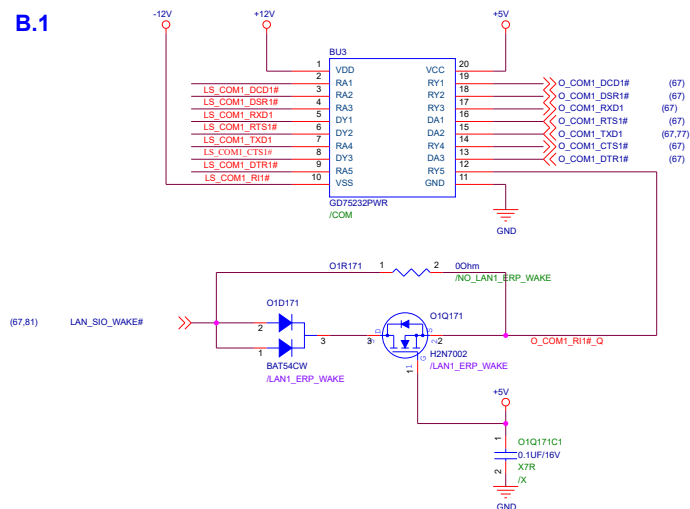
## A.1

## COM Box Header



```
for use COM Port RI# to do Deep S4/S5 wake-up function
  modify SIO RI# Pin net name to LAN_SIO_WAKE#
```

## B.1



When mount /COM

LAN Deep S4/S5 wake-up	O1R171	O1Q171 & O1D171
support	unmount	mount
not support	mount	unmount

When unmount /COM

LAN Deep S4/S5 wake-up	O1R171	O1Q171 & O1D171
support	unmount	unmount
not support	unmount	unmount

BOM	need COM Port	no COM Port
/COM	mount	unmount

<Variant Name>

# EATX Power Circuit

A. Choose EATX Power Circuit by Project

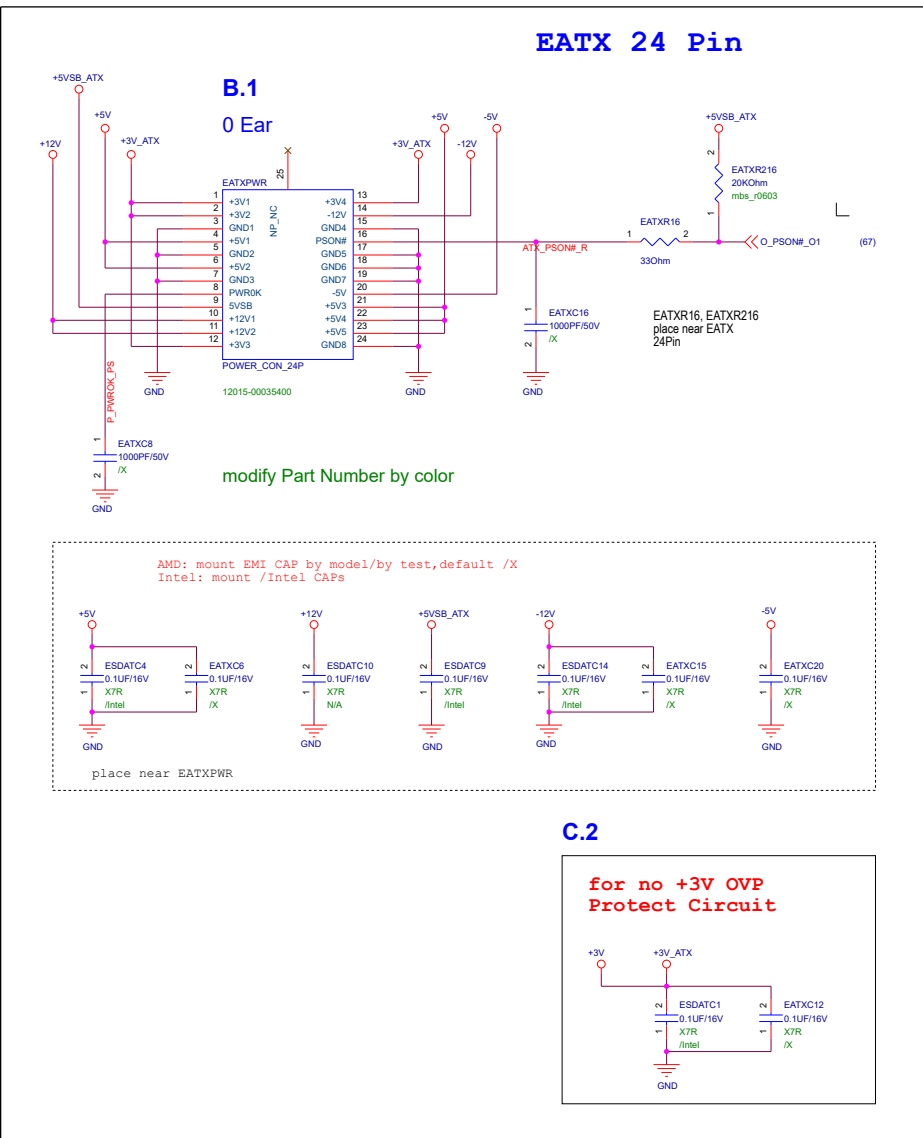
B. If choose EATX 24Pin Circuit, choose EATX Connector with 0 Ear, 1 Ear or 2 Ears by Project

C. If choose EATX 24Pin Circuit, choose +3V\_ATX & +3V Circuit by Project

D. If support Intel S0ix, add SC945, SC946 & Off-Page Net O\_PSON#\_O1 change to ATX\_PSON#

E. Modify Part Number of EATX Connector by Color

## A.1



<Variant Name>

## 8655E Circuit

- Delete LPC Bus Signal Pull High Resistor if not need
- Delete Pin 20 KBRST# Circuit if don't connect KBRST# to Chipset
- Delete O\_CASEOPEN# off-page if not used
- Delete COM1 Port Signal if don't need, but keep Strapping Pin Signal
- Modify FAN IN/PWM Signal by Project

- Delete AUDIO\_LED\_PWM Signal if not need
- If SIO Breathing LED is reserved, unmount AUDIO\_LED\_PWM pull high resistor
- Add COM Debug Signal by Project, choose GPIO by mapping table
- Add OVT#/SM# Signal by Project, choose GPIO by mapping table
- Add BEEP Signal by Project, choose GPIO by mapping table
- If use MS as FAN or GPIO, remove pull high resistor ORN404/ORN404D
- If use SIO Anti Surge Function, mount O1C32, O1C34
- Choose RSMRST# Circuit by Project

## IT8655E FAN Header Pin Table for AMD AM4

SIO FAN	FAN IN	FAN PWM	FAN Header
FAN1	Pin 64	Pin 1	CPU_FAN
FAN2	Pin 2	Pin 3	CHA_FANCHA_FAN1
FAN3	Pin 4	Pin 5	CHA_FAN
FAN4	Pin 40	Pin 39	CHA_FAN2

## FAN Net Name Table

FAN	FAN IN	FAN PWM
CPU_FAN	CPU_FANIN	CPU_FANPWM
CPU_FAN	CPU_FANIN	CPU_FANPWM
CHA_FANCHA_FAN1	CHA_FANIN1	CHA_FANPWM1
CHA_FAN2	CHA_FANIN2	CHA_FANPWM2
CHA_FAN3	CHA_FANIN3	CHA_FANPWM3
CHA_FAN4	CHA_FANIN4	CHA_FANPWM4
AD_FANP	AD_FANPIN	AD_FANPWM
W_PUMP	W_PUMP_IN	W_PUMP_PWM
M2_FAN	M2_FANIN	M2_FANPWM

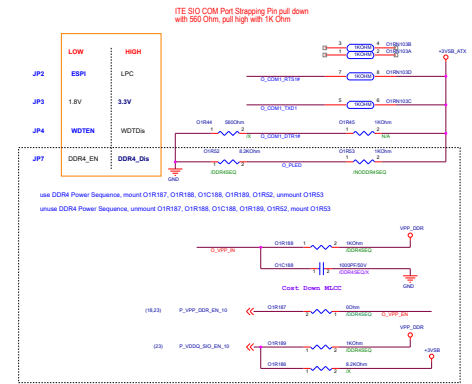
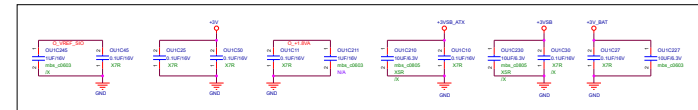
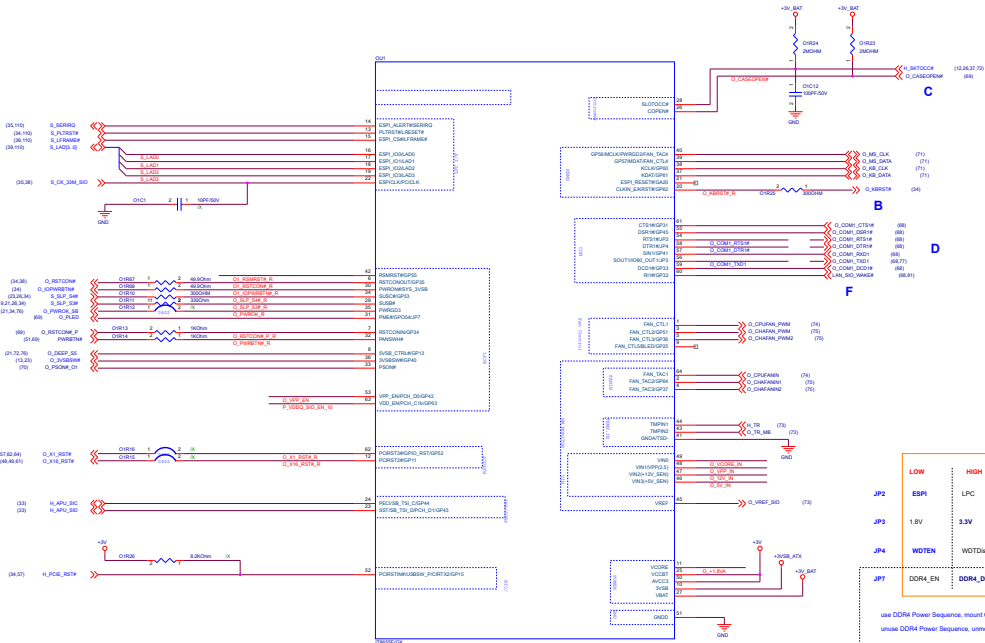
## IT8655E VIN Table

SIO VIN	VIN0	VIN1	VIN2	VIN3
VIN IN	VCORE	VPP_3DR	+12V	+5V

## IT8655E TIN Table

SIO TIN	TIN0	TIN1	TIN2
TIN IN	CPU	MS	

## N.1



BOM	use SIO DDR4 Sequence	unuse SIO DDR4 Sequence
/DDR4SEQ	mount	unmount
/NODDR4SEQ	unmount	mount

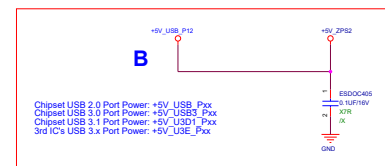
BOM	STANDARD CIRCUIT
N/A	mount
/X	unmount

ASUS	Title : IT8655E_AMD
ASUSTeK COMPUTER INC.	Engineer: SZ Design IP
Site	Project Name
Customer	Super I/O Demo Circuit

- A. Choose KBMS Power Source by Project
- B. If KBMS share power with USB Port, modify Share Power Net Name by Project
- C. Choose KBMS Port Connector by Project
- D. If choose KBMS Connector, KBMS Signal to-GND Cap choose Single Capacitor or RES Cap by Project
- E. If choose KB & USB 2.0 Connector, check USB 2.0 Port D+/D- Signal begin with 0 or 1, then modify USB 2.0 Port D+/D- Signal Net Name by Project
- F. If choose KB & USB 3.0 Connector, modify USB Port TX/RX/D+/D- Signal Net Name by Project
- G. If choose KB & USB Connector, modify USB Port Power Net Name by Project
- H. If choose KB & USB Connector, modify Connector Port Reference by Project
- I. If choose KB & USB Connector, for ITE SIO. ORN404 could /X for cost down

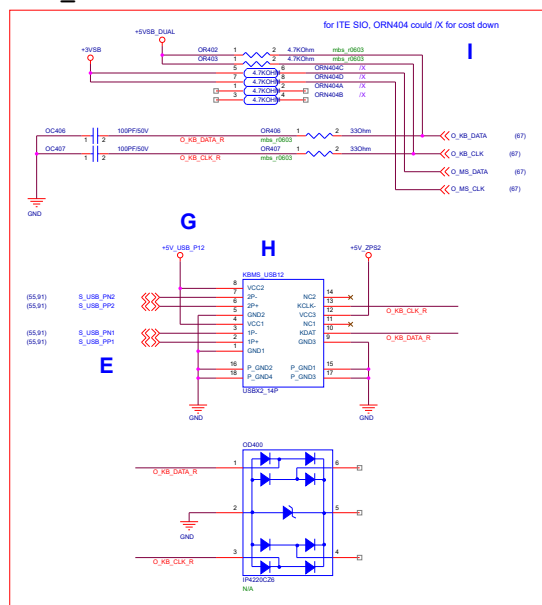
## A.1

share USB Port Power



### C.3

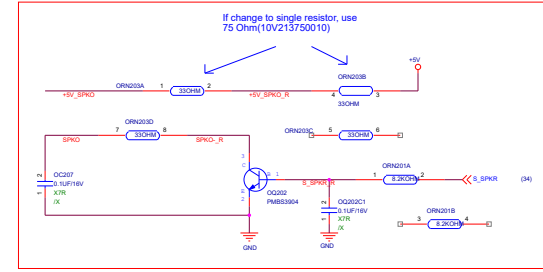
## KBMS USB910



## Panel Circuit

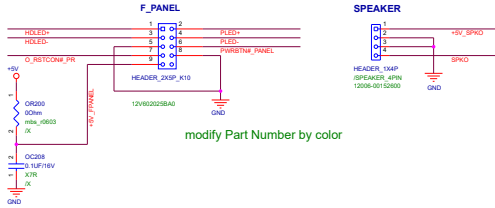
- Choose PANEL/F\_PANEL Signal ESD Solution by Project
- Choose PANEL/F\_PANEL Circuit + Chassis Intruder Circuit by Project
- Choose Chassis Intruder Signal connect to SIO or Chipset by Project
- Choose SPEAKER Header Circuit + BUZZER Circuit by Project
- Choose PLED Circuit by Project
- Choose PLED control by SIO or Chipset
- If use Memory Power control PLED, check Memory Power Net Name
- Modify Part Number of PANEL/F\_PANEL/SPEAKER Header by Color

## D.1

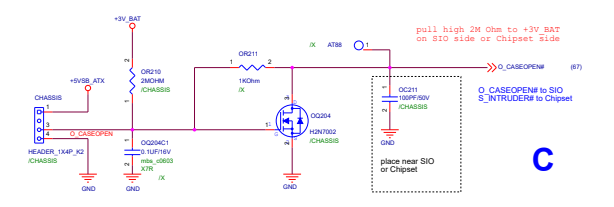


## B.1

### 10 Pin F\_PANEL + 4 Pin SPEAKER

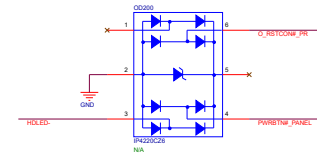
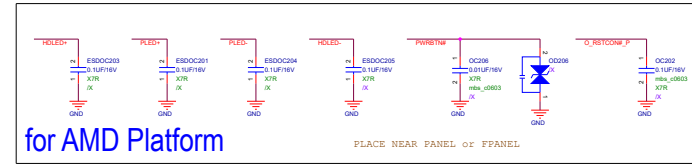


### CHASSIS INTRUDER HEADER



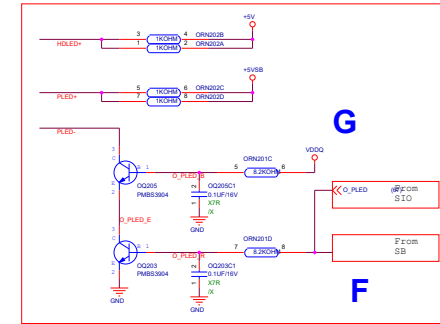
- GPIO with blink function, default GPIO(no internal pull-down resistor)
- stand by power plane, 3V tolerance
- Porting Guide: default keep GPIO, enable blink 0.5Hz or 1Hz function when enter S3, disable blink function and back to GPIO when resume from S3

## A.2



## E.1

Power LED power source use +5VSB



BOM	need SPEAKER	no SPEAKER
/SPEAKER_4PIN	mount	unmount

BOM	need BUZZER	no BUZZER
/BUZZER	mount	unmount

BOM	need CHASSIS	no CHASSIS
/CHASSIS	mount	unmount

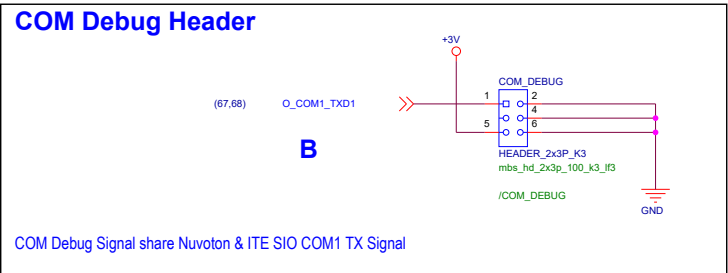
ASUS		Title : PANEL
ASUSTEX COMPUTER INC		Engineer: SZ Design IP
Rev	Project Name	Super I/O Demo Circuit
Rev	Rev	Rev
Rev	Rev	Rev

# Debug Header Circuit

- A. Choose Debug Header by Project
- B. If choose COM Debug Header, take care Debug Signal Net Name is different by Project
- C. If choose LPC Debug Header, modify Clock Signal Net Name by Project

## A.1

Delete it for EMS



BOM	need COM Debug Header	no COM Debug Header
/COM_DEBUG	mount	unmount

BOM	need LPC Debug Header	no LPC Debug Header
/LPC_DEBUG	mount	unmount

<Variant Name>

		Title :	Debug Header
ASUSTEK COMPUTER INC		Engineer:	SZ Design IP
Size	Project Name	Super I/O Demo Circuit	
B			Rev 0.0
Date:	Wednesday, August 29, 2018	Sheet	77 of 117

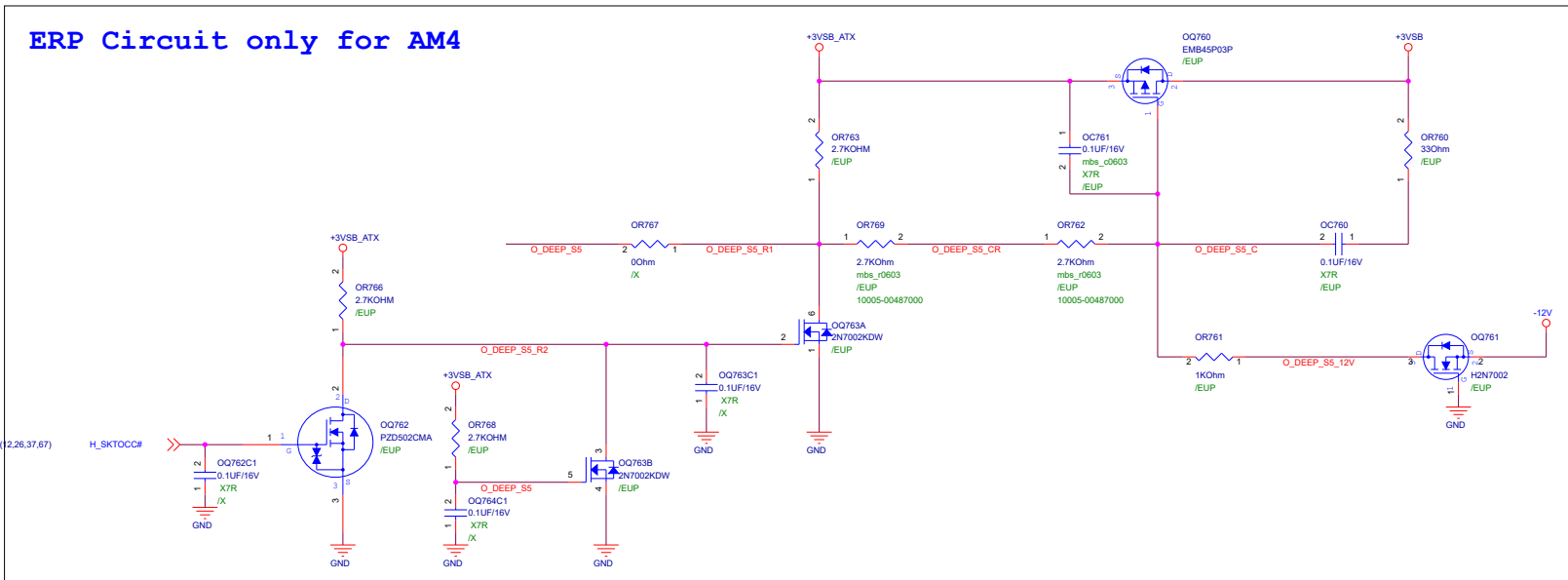


## ERP Circuit

A. Choose ERP Circuit by Project

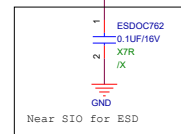
B. OR764, OR765 choose Short-Pin, Resistor or delete by Project

### A.3



(21,67,76)

O\_DEEP\_SS



BOM	no SIO ERP & SIO DSW	SIO ERP	SIO DSW
/NO_EUP	mount	unmount	unmount
/EUP	unmount	mount	mount
/NO_SIODSW	mount	mount	unmount
/SIODSW	unmount	unmount	mount

### B.2

#### Resistor



<Variant Name>

Title  <Title>		
Size  A	Document Number  <Doc>	Rev  <RevCode>
Date:	Friday, August 17, 2018	Sheet 78 of 117

## CHA\_FAN Circuit use Single Resistor

A. Choose QFAN Mode Type by Project

B. If choose PWM Mode, choose with FAN RGB Header or not by Project

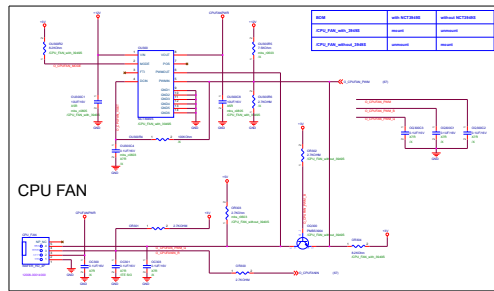
C. Remove CPU\_OPT if don't need

D. Choose O\_PWROK or O\_PWROK\_SB by Platform for FAN Expert 3 and above Mode

E. Modify Part Number of CPU\_FAN & CPU\_OPT by Color

### PWM Mode with FAN RGB Header for AM4

B.2



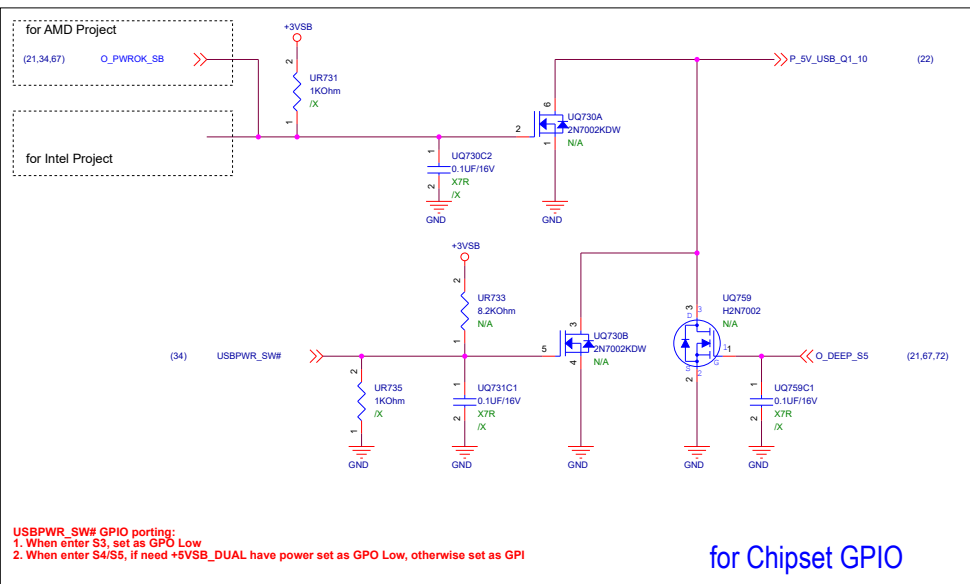
ASUS		Title : CPU_FAN
ASUS		Author : SZ Design IP
Regen 1/10 Design Circuit		

# USBPWR\_SW# Circuit for ITE SIO GPIO

A. Choose USBPWR\_SW# Circuit by Project

## A.1

+5VSB\_DUAL default no power, reserve USB Inrush Circuit



USBPWR\_SW# GPIO select:

1. could be GPI & GPOD both, default GPI (no internal pull-down/pull-high resistor)
2. stand by power plane, 3V tolerance

<Variant Name>

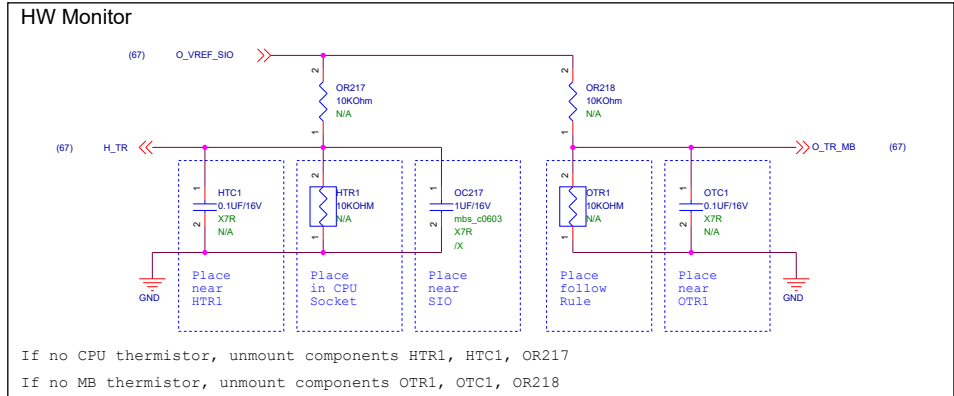
# Stand By LED & HW Monitor Circuit

- A. Choose Stand By LED Circuit by Project
- B. Keep or delete TR\_PCH Circuit by Project
- C. Keep or delete T\_SENSOR Circuit by Project
- D. Keep or delete VCORE Power Controller TEMP Detect Circuit by Project
- E. Keep or delete GFX Power Controller TEMP Detect Circuit by Project
- F. Modify Part Number of T\_SENSOR Header by Color

BOM	need Stand By LED	no Stand By LED
/StandByLED	mount	unmount

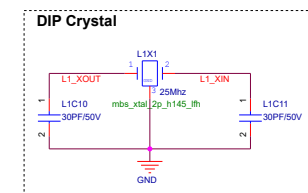
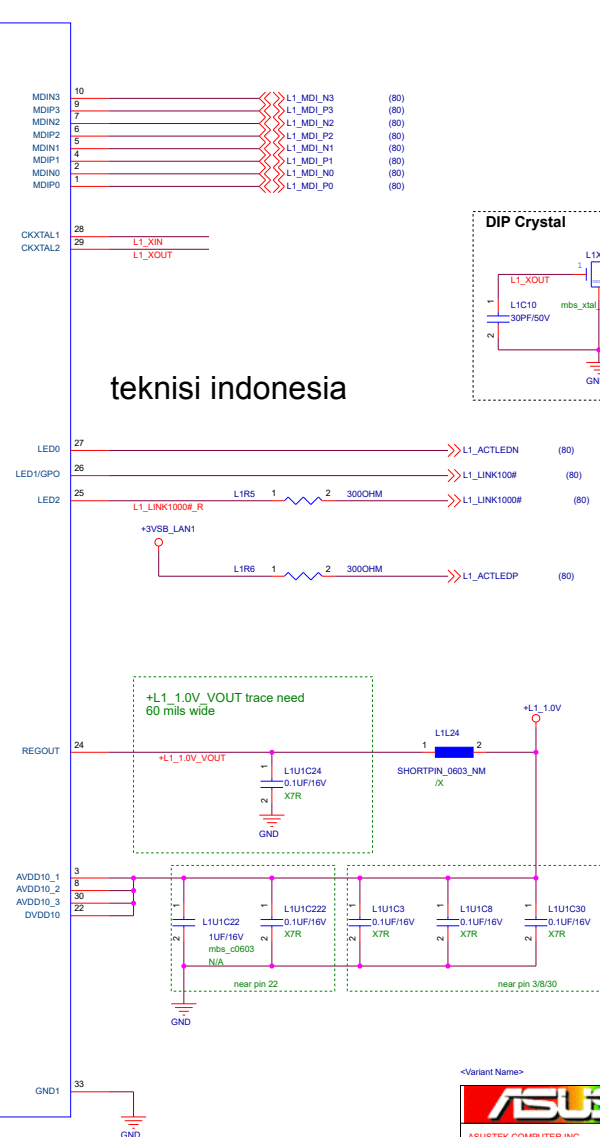
BOM	need TR_PCH	no TR_PCH
/TR_PCH	mount	unmount

BOM	need T_SENSOR	no T_SENSOR
/T_SENSOR	mount	unmount



<Variant Name>

6. select block 1 or 2 according to if you support S0IX

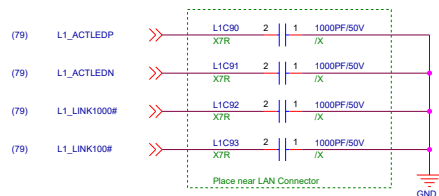


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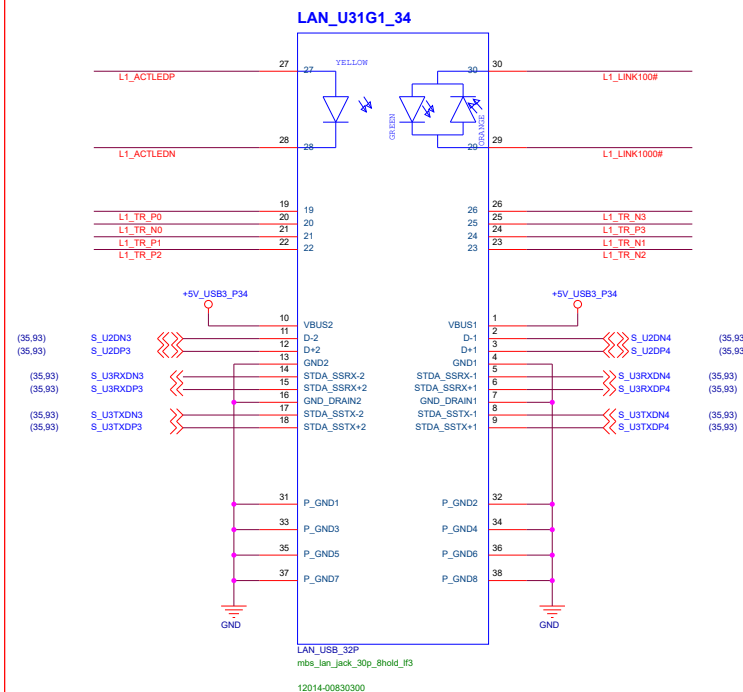
BOM	
N/A	mount
/X	unmount

		<b>Title :</b> RTL8111H	
ASUSTEK COMPUTER INC.		<b>Engineer:</b> SZ Design IP	
Size A3	Project Name <b>LAN Demo Circuit</b>	Rev 0.0	
Date: Wednesday August 29, 2018		Sheet 79	of 117

### 3. change usb signal name



single LAN named LAN\_USB31G1\_xx  
dual LAN named LAN1\_USB31G1\_xx



ASUS® Title : LAN Connector

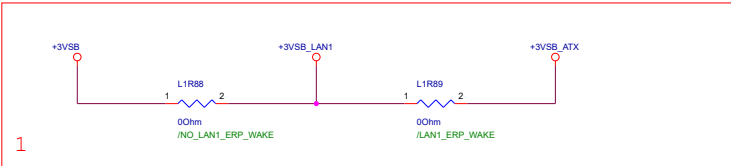
ASUSTEK COMPUTER INC		Engineer: SZ Design IP	
Size A3	Project Name <b>LAN Demo Circuit</b>	Rev 0.0	
Date: Wednesday, August 29, 2018	Sheet 80 of 117		

Title			
<Title>			
Size	Document Number		Rev
A	<Doc>		<RevCode>
Date:	Friday, August 17, 2018	Sheet	82 of 117



LAN1 Deep S4/S5 Wake-up Circuit

- 1. Remove Short-Pin L1R88 in LAN1 IC Page

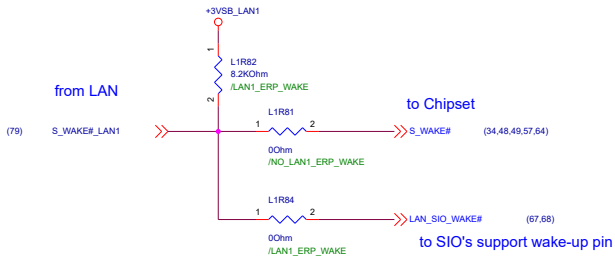


for Intel PHY

- 2. for Intel PHY LAN, L1\_LAN\_DISABLE# renamed L1\_LAN\_DISABLE#\_R in LAN1 IC Page
- 3. for Intel PHY LAN, L1\_LAN\_WAKE# renamed L1\_LAN\_WAKE#\_R in LAN1 IC Page

for PCIE LAN1

- 4. for PCIE LAN, S\_WAKE# renamed S\_WAKE#\_LAN1 in LAN1 IC Page
- 5. for Intel PCIE LAN, make sure L1\_DEV\_OFF# choose +3VSB\_ATX power plane GPIO



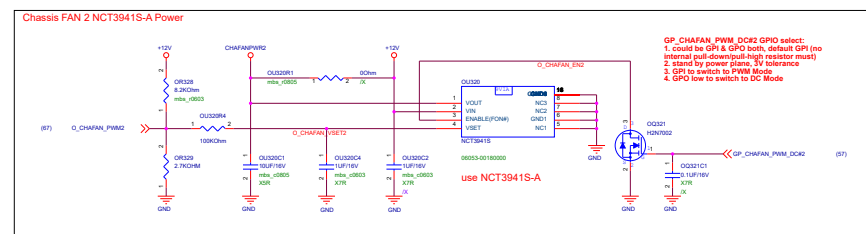
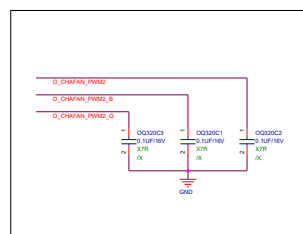
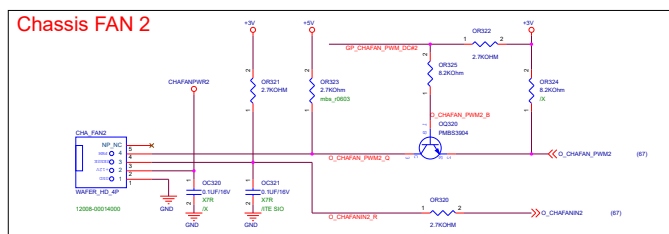
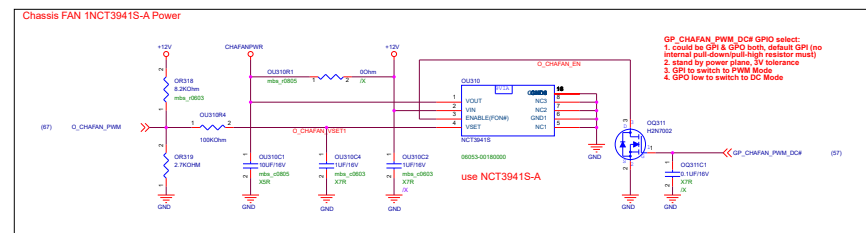
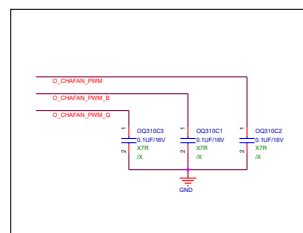
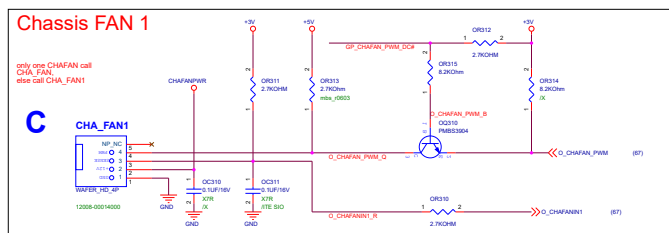
# CHA\_FAN\_PWM Mode & DC Mode QFAN Circuit Use Single Resistor

- A. Choose QFAN Mode Type by Project
- B. Remove the CHA\_FAN which don't need

- C. If only one CHA\_FAN, rename CHA\_FAN1 to CHA\_FAN
- D. Modify Part Number of CHA FAN Header by Color

## A.1

### 4 Pin PWM Mode & DC Mode



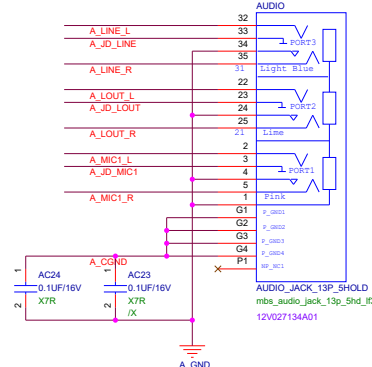
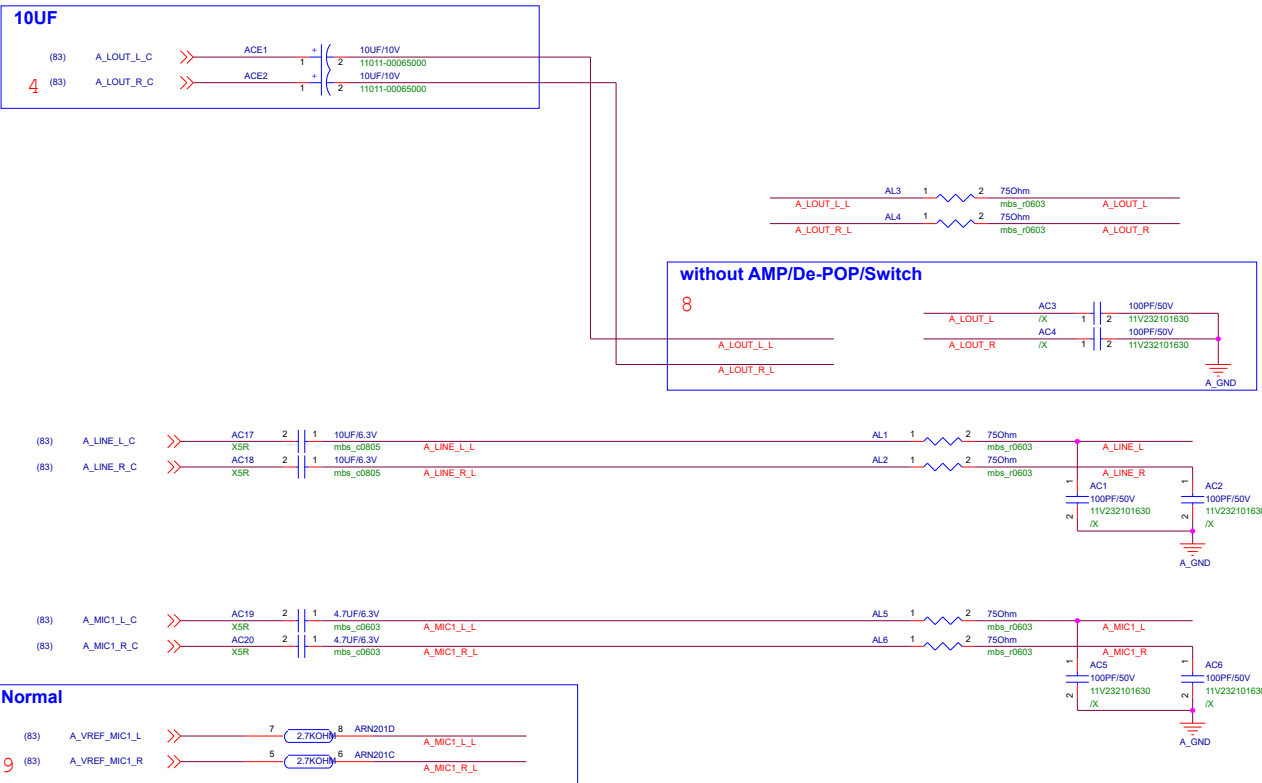
# Rear 3Jacks Circuit

1. Choose Jack Detect Circuit by Codec,block 1,2,3
2. Choose LOUT DIP CAP Type by Codec & Project,block 4,5,6
3. Choose LOUT Circuit with or without De-POP/Switch by Project,block 7,8
4. Modify ACE1, ACE2 Part Number by Project
5. Choose Rear MIC VREF Circuit by Project ,block9,10
6. For Gamer/Gaming modity AC17, AC18 part by request
- 7 if you use 1220 ,Modify AC1,AC2,AC3, AC4, ,AC5,AC6, Part Number to varistor and Optional to N/A

for ALC1150



Delete it for EMS



Audio CAP using rule,pls change all dip caps partnumber according bellow rule

Z390,B450 ROG / Strix series	Nichicon
Z390,B450 PRIME / TUF Series	ELNA
Intel H310,H310C,H110&AMD A320 series	Chemicon
other chipsets except above series	Nichicon

<Variant Name>

ASUS		Title :	3 Jacks
ASUSTEK COMPUTER INC		Engineer:	SZ Design IP
Size	Project Name	AUDIO Demo Circuit	
A3	Date: Wednesday, August 29, 2018	Sheet	85 of 100
Rev	0.0		

DIP CAP  
EL 10U : 11G040822620  
PL 10U : 11V090106207

Taping DIP CAP  
Chemicon 10U T: 11011-00064100  
Elan 10U: 11011-00065000  
Nichicon 10U T: 11011-00066200

DIP CAP  
EL 100U : 11V040107321  
PL 100U : 11031V0001F000

Taping DIP CAP  
Chemicon 100U T: 11011-00024100  
Elan 100U : 11011-00025000  
Nichicon 100U T: 11011-00026200

AC1, AC2, AC3, AC4, AC5, AC6  
100PF : 11V232101630  
Varistor: 07V200402020

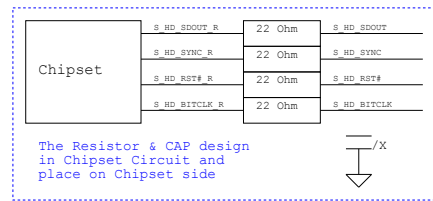
Taping DIP CAP  
PL 100U T: 11031V0001F400

# ALC1150 Circuit

1. Modify IO Power by Project
2. Delete A\_SELET\_AMP if not need
3. Delete A\_EAPD if not need

4. Delete A\_SPDIFO\_HEADER if not need
5. Delete A\_SPDIFO\_OPTICAL if not need
6. Delete Side Surround for Rear 3 Jacks or 5Jacks

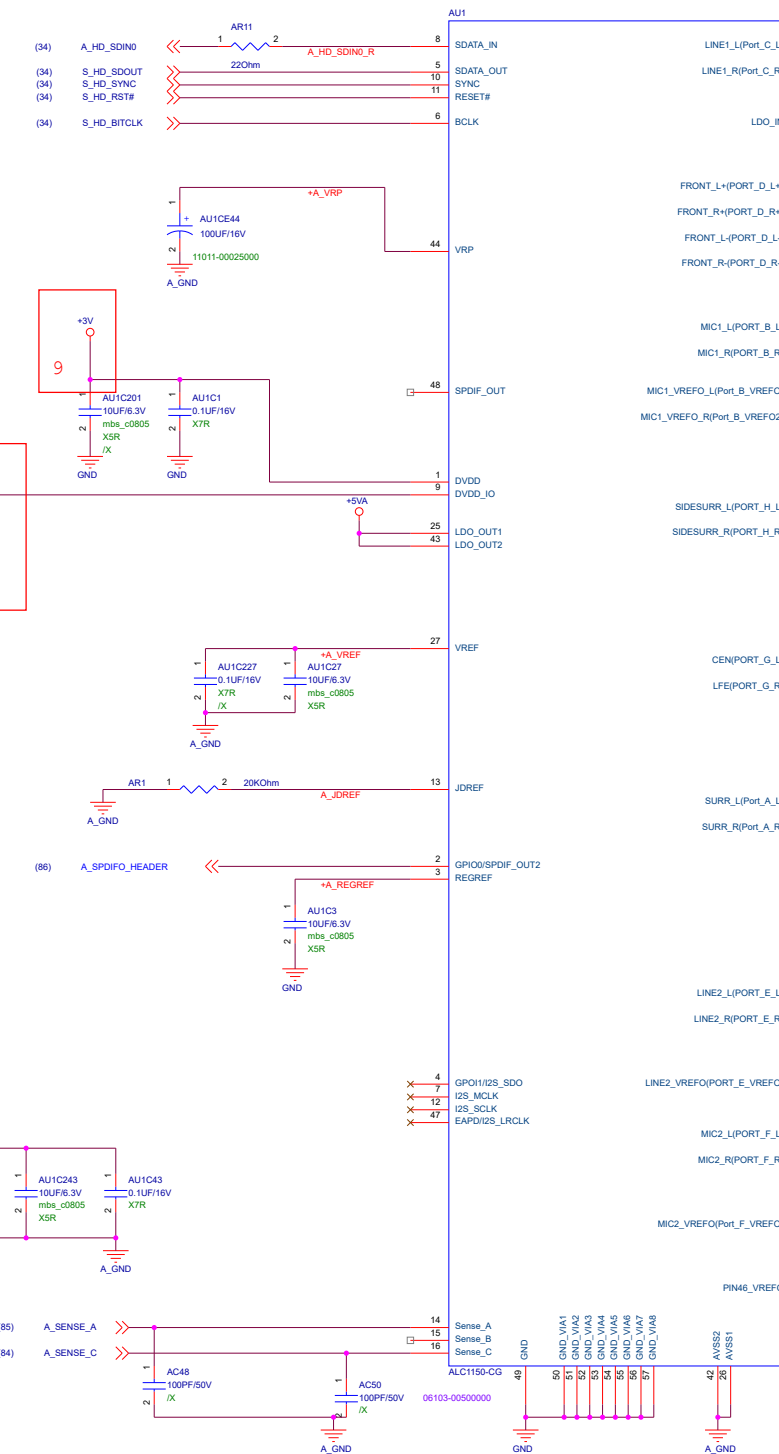
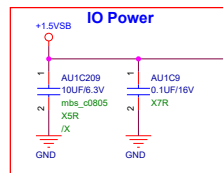
7. Delete CEN/LFE & Surround for Rear 3 Jacks
8. Modify AU1CE44 Part Number by Project
9. Block 8,9, select one of them according if support s0ix



DIP CAP  
EL 100U : 11V040107321  
PL 100U : 11031V0001F000

Taping DIP CAP  
PL 100U T:11031V0001F400

Taping DIP CAP  
Chemicon 100U T: 11011-00024100  
Elan 100U :11011-00025000  
Nichicon 100U T: 11011-00026200



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BOM	
N/A	mount
/X	unmount

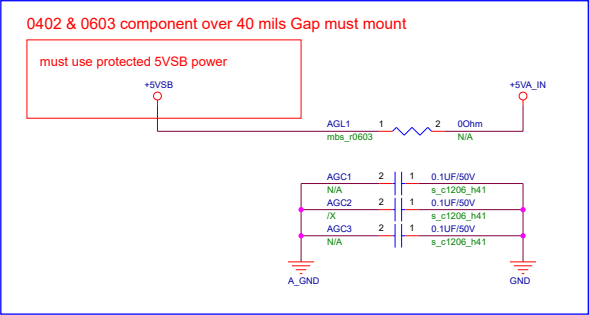
STANDARD CIRCUIT	
ICOMB	Audio
SZ_Audio_10F	
HD_STANDARD_AUDIO	

<Variant Name>

# Audio GAP & Power Circuit

- 1. Choose Resistor & Capacitor over GAP Circuit by Project
- 2. Keep or delete Audio Power LDO Circuit by Project
- 3. Modify APCE4 Part Number by Project

## 40 mils Gap for XU



BOM	Audio Power from 5VSB	Audio Power from 12V LDO 5V
/AUDIO_PWR_5VSB	mount	unmount
/AUDIO_PWR_LDO	unmount	mount

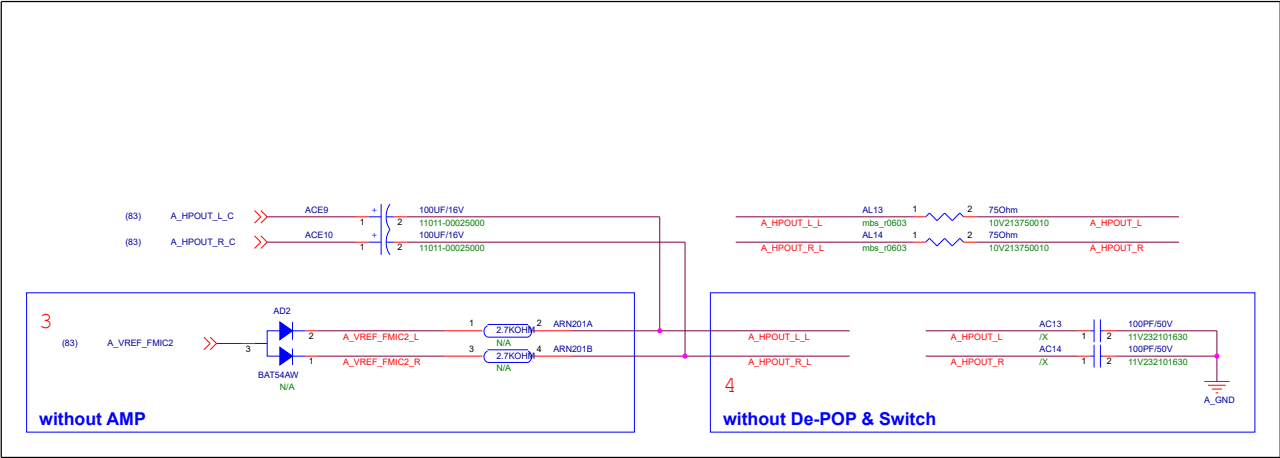
<Variant Name>

AAFP Circuit

- 1. Choose AAFP Header Circuit by Codec, and change AAFP part number by your request, block 6, 7, or 8
- 2. Choose HP Circuit with or without AMP/De-POP/Switch by Project, block 1, 2, 3, 4
- 3. Modify ACE9, ACE10 Part Number by Project
- 4. IF you use 1220, AC13, AC14, AC15, AC16 option must change to N/A and change part number to varistor
- 5. Modify ARN202 value to 4.7k if you use 887, block 5
- 6. For Gamer Project with ALC1150, AL13, AL14 change to 470Ohm
- 7. change AC37, AC38 part number if you have AMP, block 6

AAFP

for ALC887-VD2/ALC892/ALC1150/ALC1220X



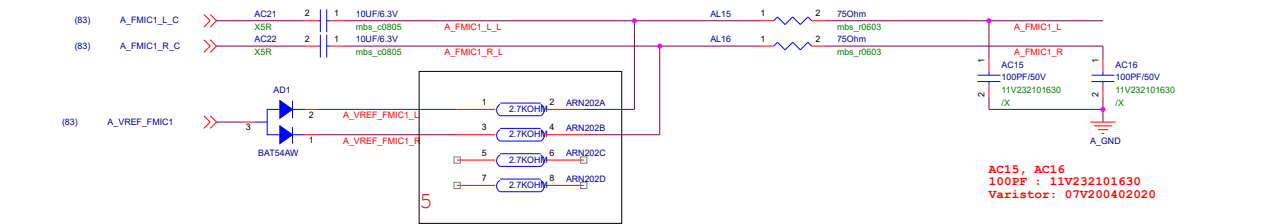
DIP CAP  
EL 100U : 11V040107321  
PL 100U : 11031V0001F000

AL13, AL14  
75 Ohm: 10V213750010  
47 Ohm: 10V213470010

AC13, AC14  
100PF : 11V232101630  
Varistor: 07V200402020

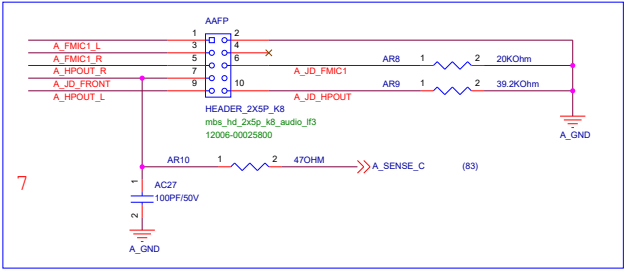
Taping DIP CAP  
Chemicon 100U T: 11011-00024100  
Elan 100U : 11011-00025000  
Nichicon 100U T: 11011-00026200

Taping DIP CAP  
PL 100U T: 11031V0001F400



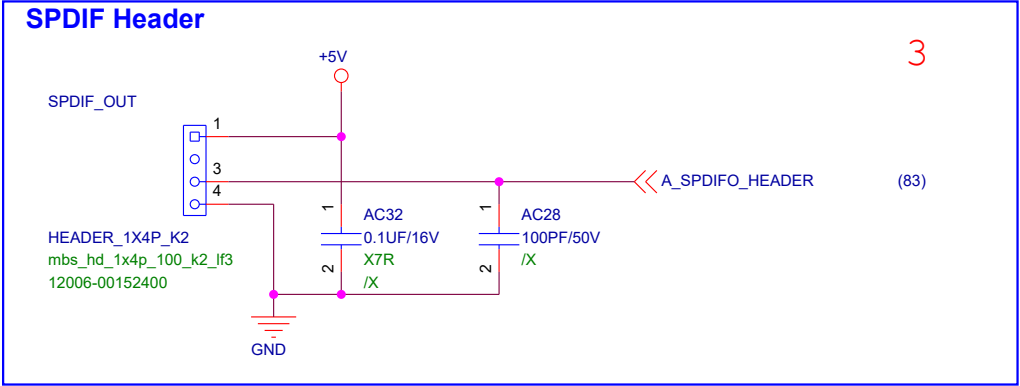
AC15, AC16  
100PF : 11V232101630  
Varistor: 07V200402020

for ALC1150



Delete it for EMS

# SPDIF



<Variant Name>



Title : SPDIF

ASUSTEK COMPUTER INC

Engineer: SZ Design IP

Size  
A

Project Name  
**AUDIO Demo Circuit**

Rev  
0.0

Title		
<Title>		
Size	Document Number	Rev
A	<Doc>	<RevCode>
Date:	Friday, August 17, 2018	Sheet 89 of 117

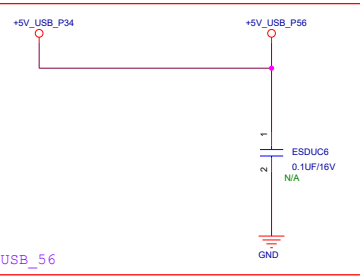
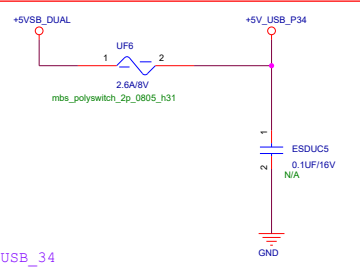
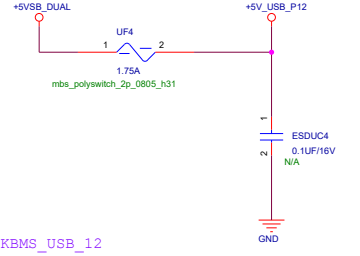
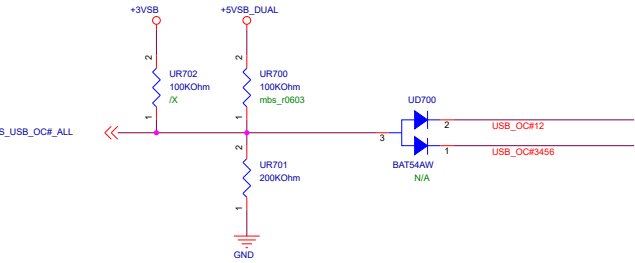


place near Chipset

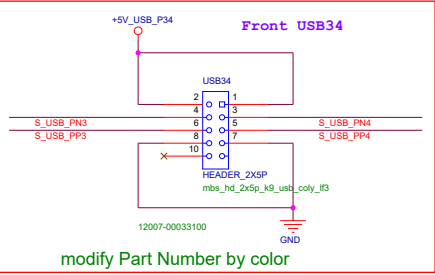
KBMS\_USB\_12

place near Chipset

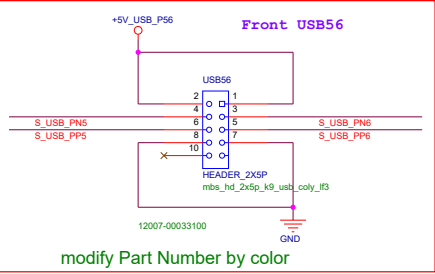
USB\_34 & USB\_56



USB2 Header



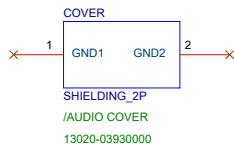
USB2 Header



<Variant Name>

# AUDIO COVER

TUF Cover

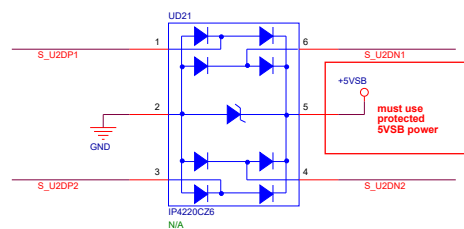
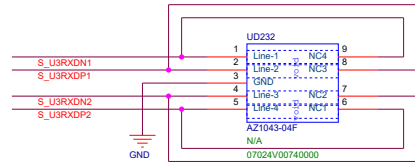
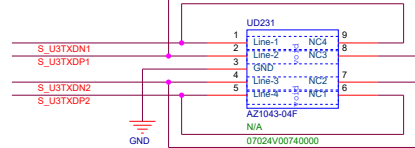
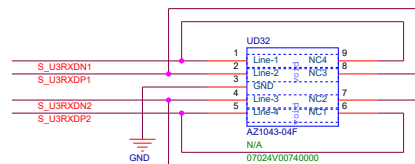
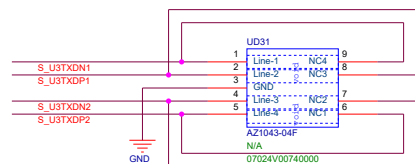


# Codec Cover LED

<Variant Name>

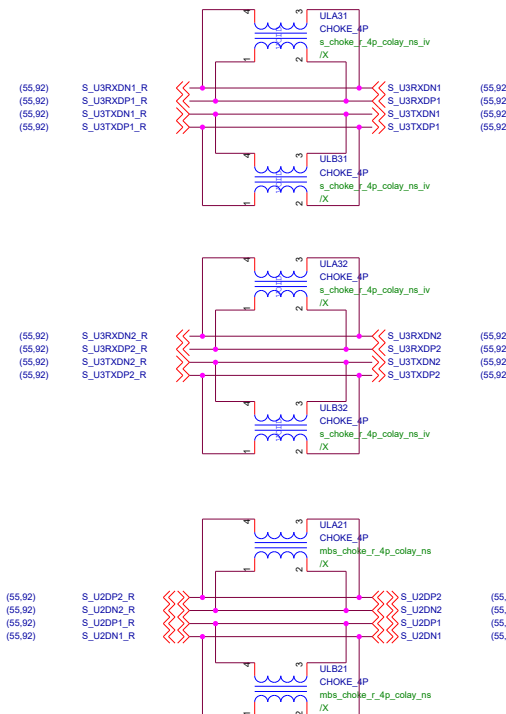
		Title :	Cover_LED
ASUSTEK COMPUTER INC		Engineer:	SZ Design IP
Size A3	Project Name <b>AUDIO Demo Circuit</b>		Rev 0.0
Date: Friday, August 17, 2018	Sheet	88	of 117

## ESD Diode



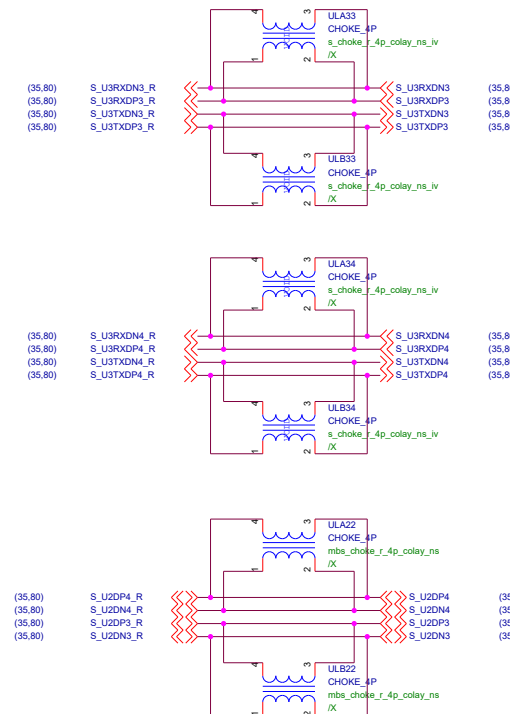
Front U31G1\_12

## Reserve Location (RES A)



Front U31G1\_12

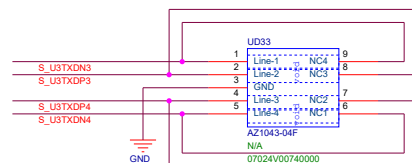
## Reserve Location (Single RES)



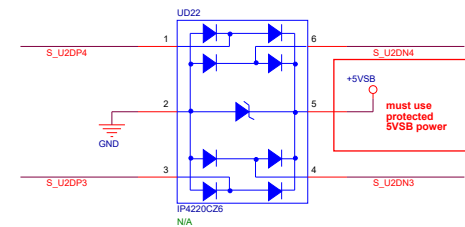
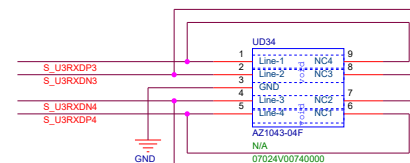
BACK LAN\_U31G1\_34

Delete it  
for EMS

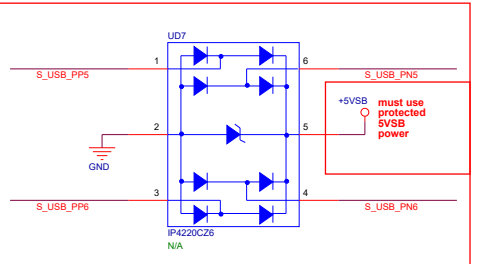
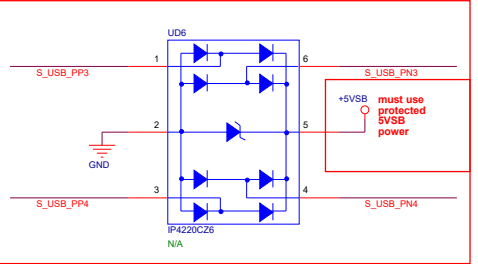
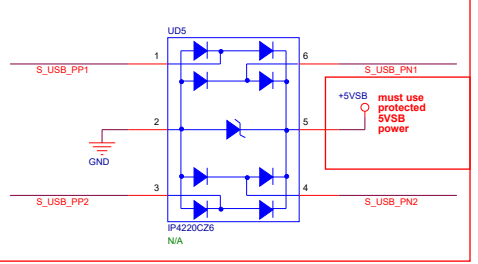
## ESD Diode



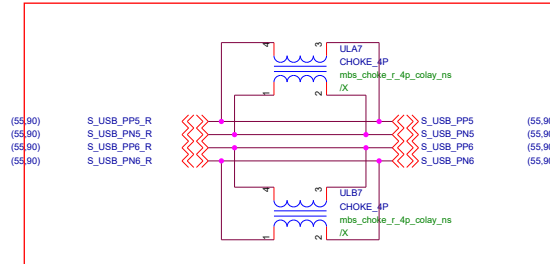
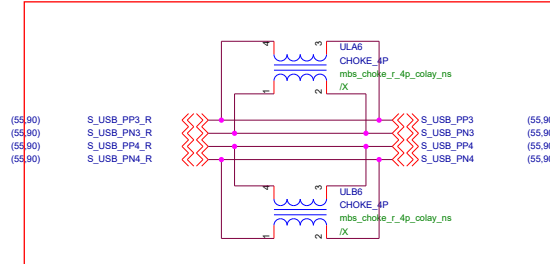
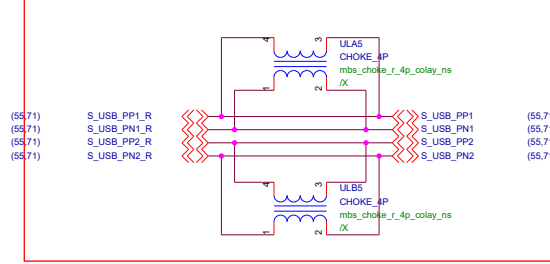
BACK LAN\_U31G1\_34



&lt;Variant Name&gt;

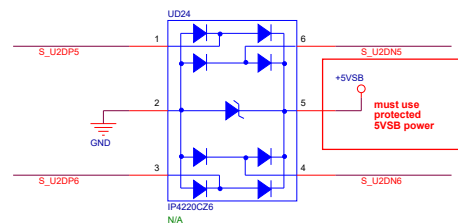
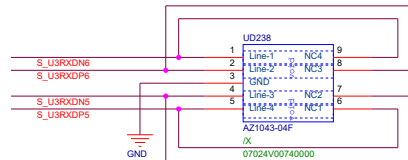
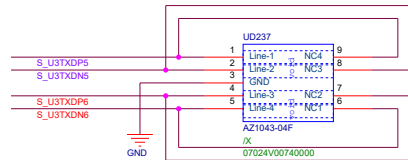
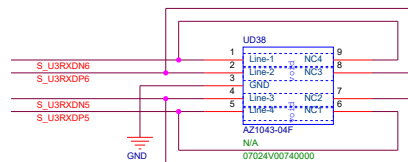
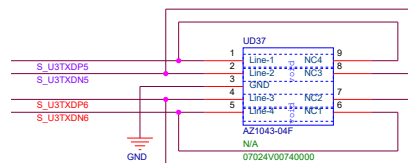


Reserve Location (RES A)



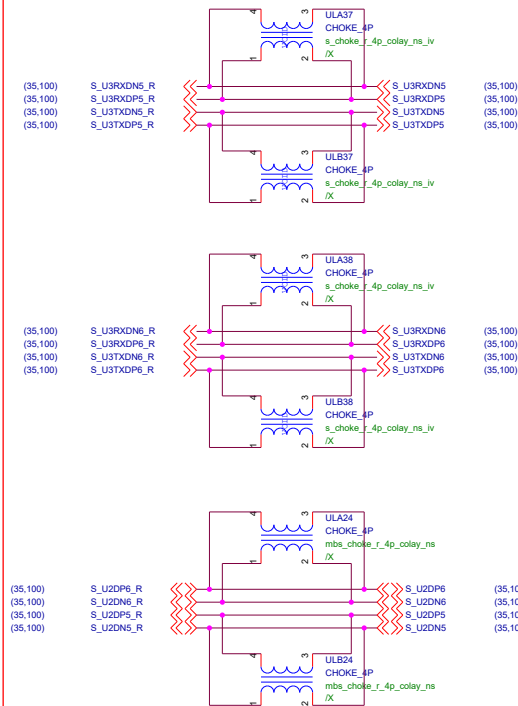
<Variant Name>

## ESD Diode



BACK U31G1 C5

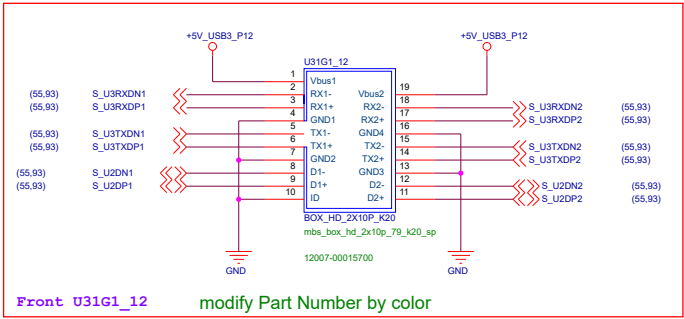
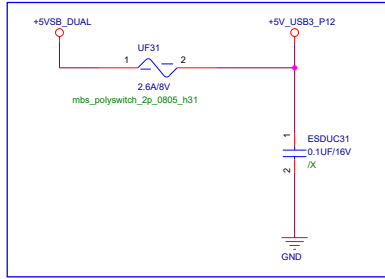
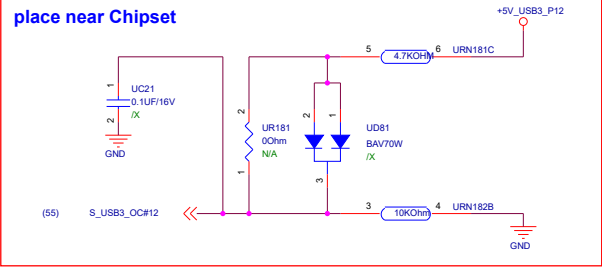
### Reserve Location (RES A)



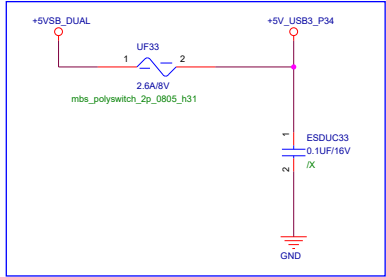
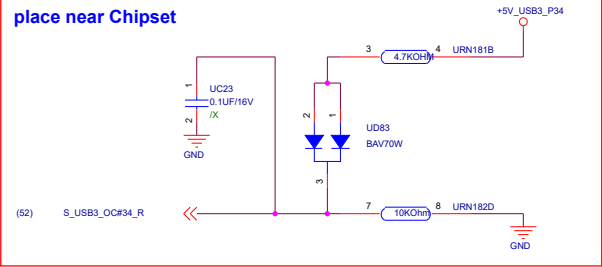
BACK U31G1\_C5

OC# circuit for AMD

place near Chipset



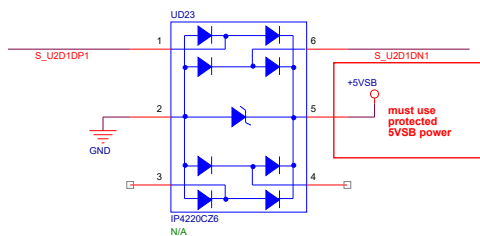
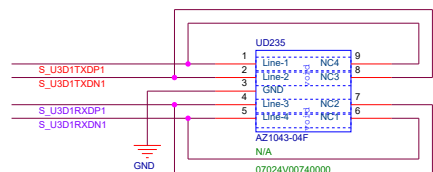
place near Chipset



<Variant Name>

*Delete it for*  
EMS

Pin connection diagram for the AZ1043-Q4F component. The component is shown as a rectangular package with pins numbered 1 through 9. Pin 1 is connected to S\_U3D1TXDP1. Pin 2 is connected to S\_U3D1TXDN1. Pin 3 is connected to S\_U3D1RXDP1. Pin 4 is connected to S\_U3D1RXDN1. Pin 5 is connected to GND. Pin 6 is connected to GND. Pin 7 is connected to GND. Pin 8 is connected to GND. Pin 9 is connected to GND. The component is labeled AZ1043-Q4F and 07024V00740000.



(95,96) S\_U3D1RXDN1\_RDT  
 (95,96) S\_U3D1RXDP1\_RDT  
 (95,96) S\_U3D1TXDN1\_RDT  
 (95,96) S\_U3D1TXDP1\_RDT

ULA35  
 CHOKE\_4P  
 s\_choke\_r\_4p\_colay\_ns\_v  
 /X

ULA36  
 CHOKE\_4P  
 s\_choke\_r\_4p\_colay\_ns\_v  
 /X

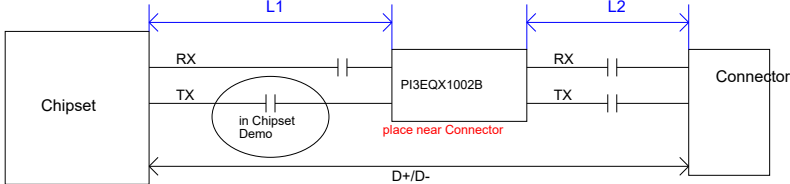
(95,96) S\_U3D1RXDN1  
 (95,96) S\_U3D1RXDP1  
 (95,96) S\_U3D1TXDN1  
 (95,96) S\_U3D1TXDP1

(55,96) S\_U2D1DP1\_R  
 (55,96) S\_U2D1DN1\_R

ULA23  
 CHOKE\_4P  
 mbs\_choke\_r\_4p\_colay\_ns  
 /X

(55,96) S\_U2D1DP1  
 (55,96) S\_U2D1DN1

BACK U31G2\_1



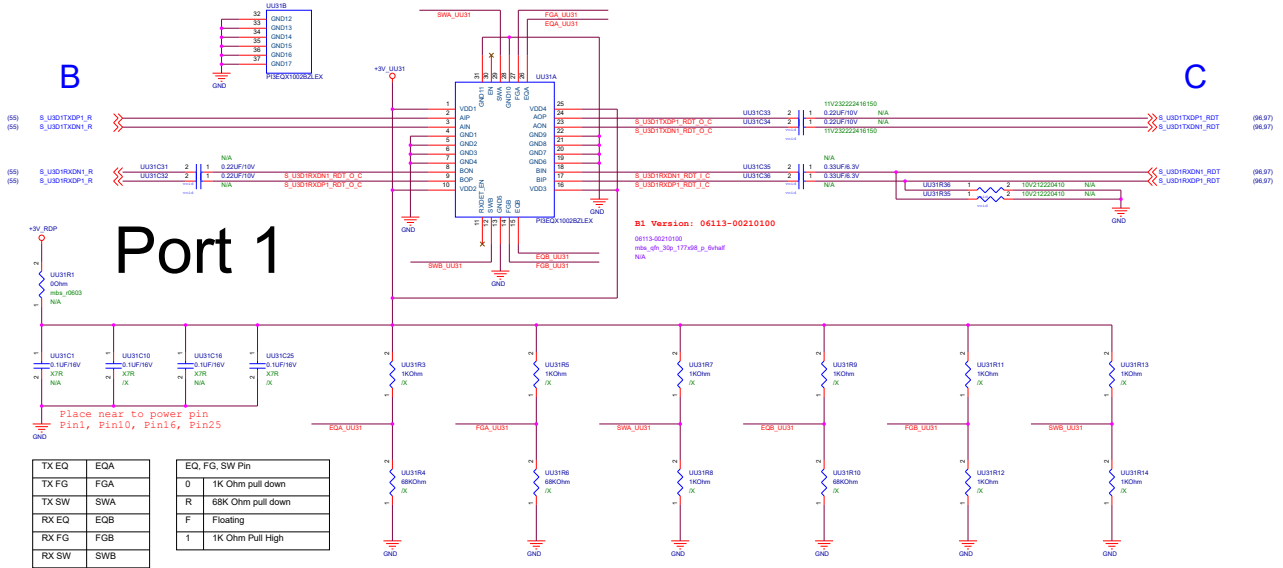
Net	Impedance/Width	Space	Length
TX/RX L1	follow USB 3.1 Controller Rule	30 mils	< 10", prefer 5" - 9"
TX/RX L2		30 mils	< 2.5", prefer 0.5" - 1.5"
+3V_RDP	>= 20 mils		

EQ/FG Setting Table for Intel Platform	L2 < 2.5"					
	EQA	FGA	SWA	EQB	FGB	SWB
L1 < 7"	R	R	F	R	0	F
7" <= L1 <= 9" (demo default)	F	R	F	R	F	F
9" < L1 < 10"	1	R	F	R	1	F

EQ/FG Setting Table for AMD Platform	L2 < 2.5"					
	EQA	FGA	SWA	EQB	FGB	SWB
L1 < 7"	F	F	F	F	F	F
7" <= L1 <= 9"	F	F	F	F	F	F
9" < L1 < 10"	F	F	F	0	1	F

#### USB 3.1 Re-Driver PI3EQX1002B Circuit

- Delete the Re-Driver IC which is not needed by Project
- Modify Input USB 3.1 TX/RX Signal Net Name by Project
- Modify Output USB 3.1 TX/RX Signal Net Name by Project
- If UU31 TX output signals send to ASM1543, UU31C33, UU31C34 change Part Number from 11V23222416150 to 11V232334150 & mount UU31R33, UU31R34, otherwise could delete UU31R33, UU31R34
- If UU32 TX output signals send to ASM1543, UU32C33, UU32C34 change Part Number from 11V23222416150 to 11V232334150 & mount UU32R33, UU32R34 otherwise could delete UU32R33, UU32R34
- Modify EQ/FG/SW Pins' pull high/pull down BOM by layout

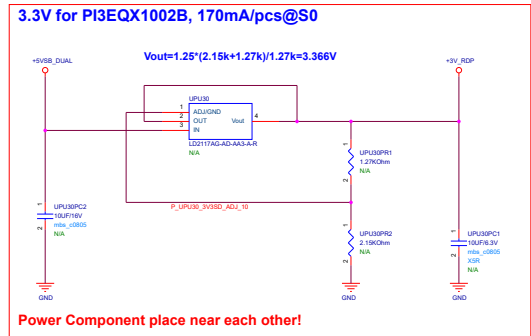


TX EQ	EQA
TX FG	FGA
TX SW	SWA
RX EQ	EQB
RX FG	FGB
RX SW	SWB

EQ, FG, SW Pin	0	1K Ohm pull down
	R	68K Ohm pull down
	F	Floating
	1	1K Ohm Pull High

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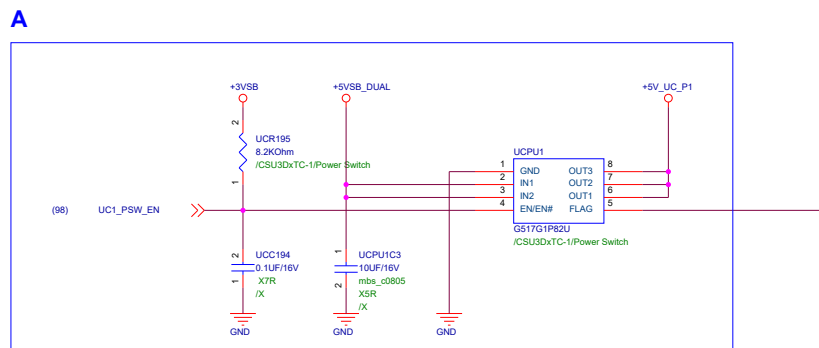
#### Power Solution for PI3EQX1002B \*1/2pcs



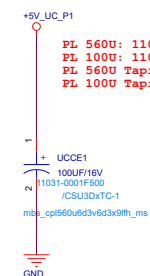




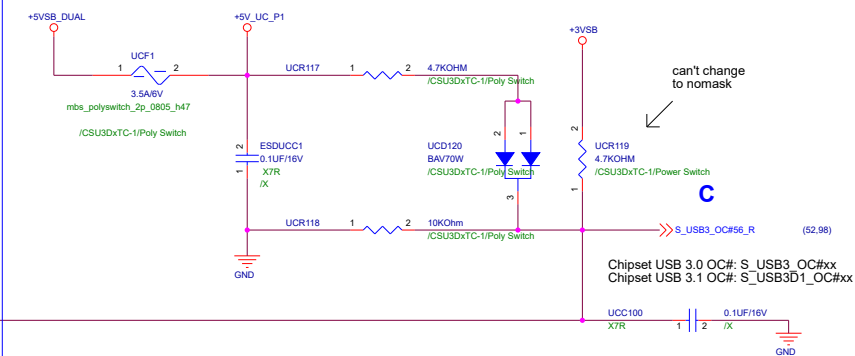
### E. Modify Part Number of UCCE1 by Project



```
+5V_UC_P1
PL 560U: 11031V00046400
PL 100U: 11031V0001F000
PL 560U Taping: 11031-0004F300
PL 100U Taping: 11031-0001F400
```



for Chipset OC# Pin with internal pull high

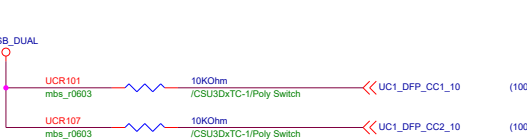


BOM	Type-C with Power Switch	Type-C with Poly Switch
/CSU3DxTC-1	mount	mount
/CSU3DxTC-1/Power Switch	mount	unmount
/CSU3DxTC-1/Poly Switch	unmount	mount

## Two USB 3.x Ports to One Type-C Connector/USB 3.1 Front Header Circuit\_1

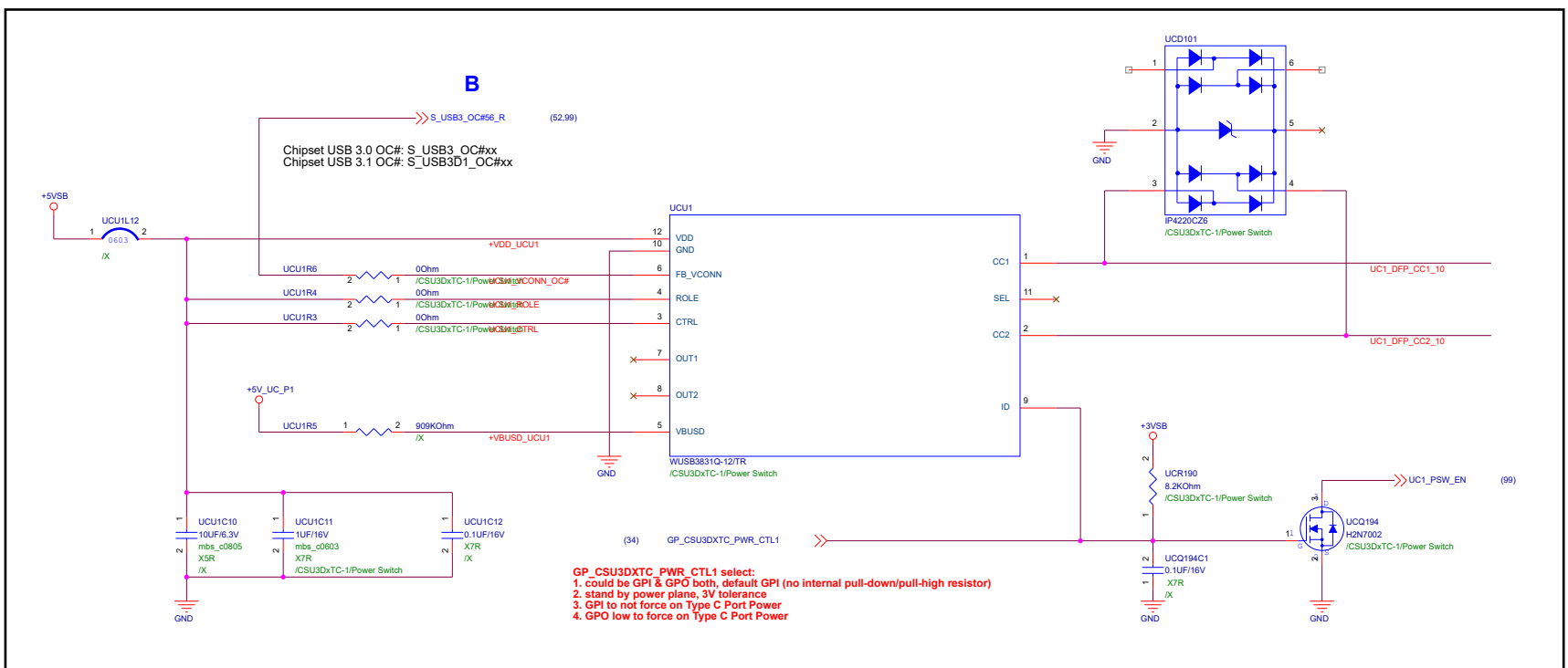
A. If don't need use or reserve Power Switch to control Type-C Connector Power, delete this block

### 3. Modify OC# Signal Net Name by Project



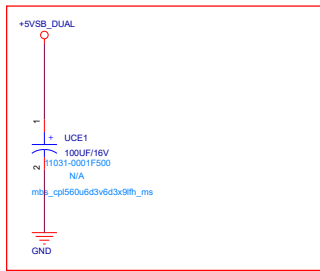
BOM	Type-C with Power Switch	Type-C with Poly Switch
/CSU3DxTC-1	mount	mount
/CSU3DxTC-1/Power Switch	mount	unmount
/CSU3DxTC-1/Poly Switch	unmount	mount

A

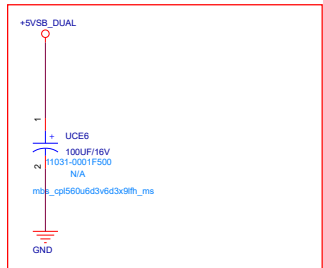


<Variant Name>

PL CAP

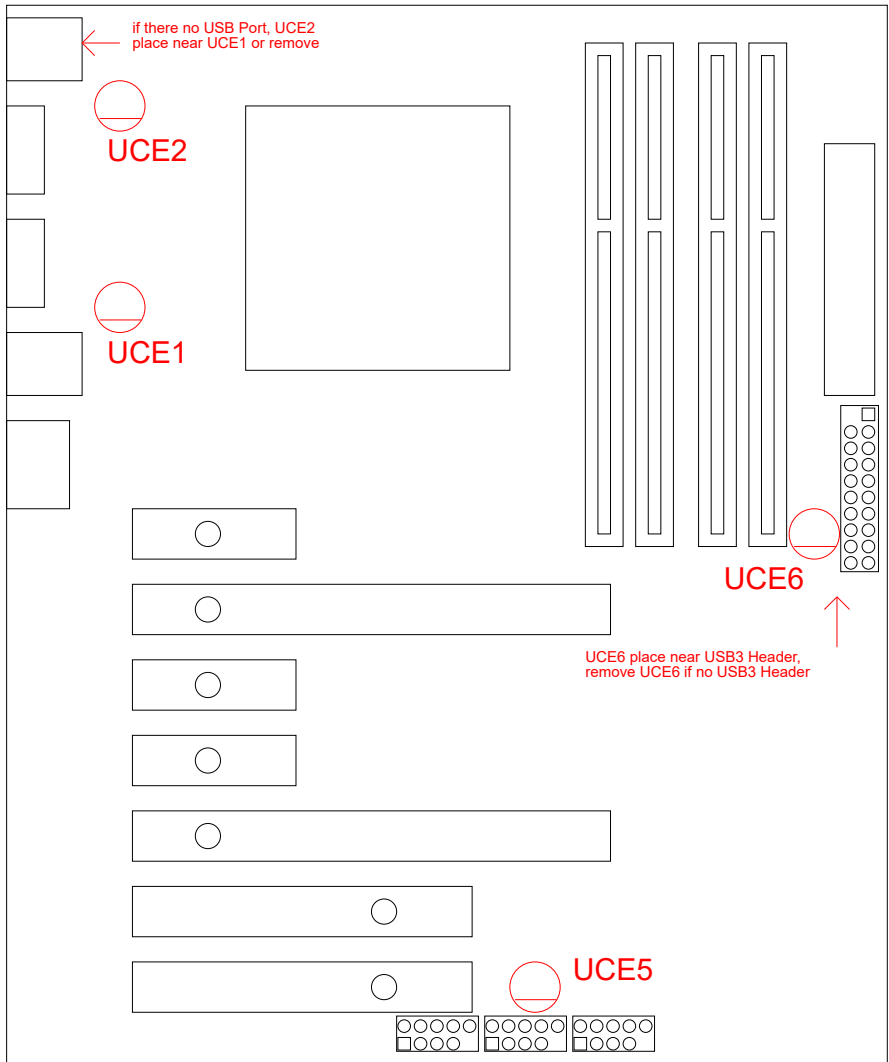


PL CAP



CAP PL 100UF/16V 6.3\*9 DIP 20%  
GAMING : 黑色11031-0001F500

# USB Power CAP recommended placement



BOM	
N/A	mount
/X	unmount

STANDARD CIRCUIT	
XC98B	USB
CS_USB_0.2E	
HD_DEMO_USB	

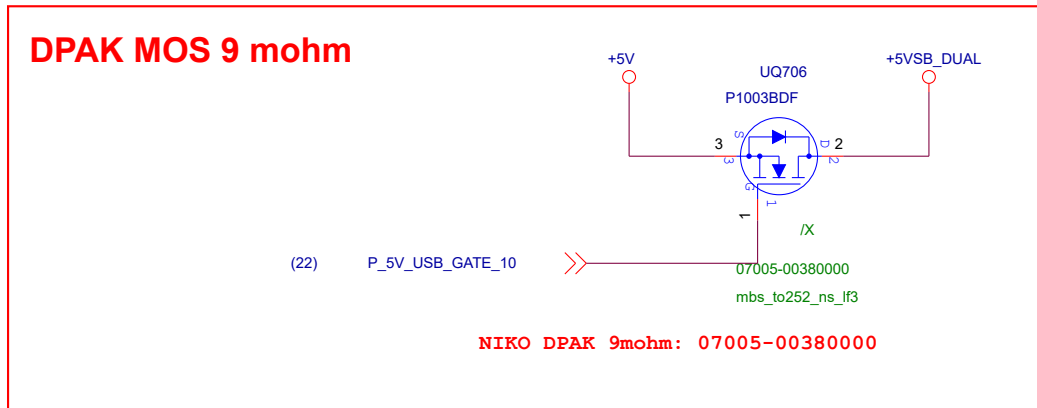
/X

<Variant Name>

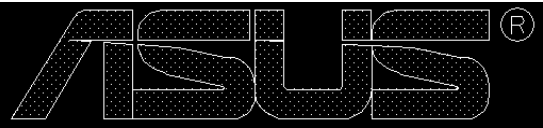
ASUS		Title : USB Power CAP	
ASUSTEK COMPUTER INC		Engineer: Kell_Huang	
Size	Project Name	Chipset USB Demo Circuit	
A3			Rev 0.0
Date: Friday, August 17, 2018		Sheet 102	of 117

Title		
<Title>		
Size	Document Number	Rev
A	<Doc>	<RevCode>
Date:	Friday, August 17, 2018	Sheet 104 of 117

+5VSB\_DUAL current:  
 DIMM\*4=7A, DIMM\*2=5A  
 USB 2.0=0.5A/port  
 USB 3.x=1A/port  
 USB Type C=3A/port  
 if +5VSB\_DUAL current (DIMM+USB 2.0 Port+USB 3.x Port) > 15A, add UQ706



Title		
<Title>		
Size	Document Number	Rev
A	<Doc>	<RevCode>
Date:	Wednesday, August 29, 2018	Sheet 103 of 117



A

ASUS PCB Logo Circuit

A. Choose ASUS Logo by Project

C. Keep or remove NEED\_COMP\_SILK by Project

B. Choose KCC Logo by Project

LOGO2

FCC

FCC

/X

LOGO7

PCB MADE IN CHINA

PCB\_MADE\_IN\_CHINA

/X

LOGO3

RCM

RCM

/X

LOGO9

CAN ICES-3 (B) /NMB-3 (B)

CAN\_ICES\_3B\_NMB\_3B

/X

LOGO1

EMI\_D33005\_H

EMI\_D33005\_H

/X

LOGO8

VCCI

VCCI

/X

LOGO5

WEEE\_LOGO

WEEE\_LOGO

/X

LOGO6

CE

CE

/X

LOGO11

SFIS\_LABEL

SFIS\_LABEL

/X

B

10mm without Wifi

LOGO10

RC R-RMM-MSQ-XXXXXXXXXXXXXXXXXX

KC\_R\_REM\_LOGO

/X

s\_kc\_r\_logo\_10mm

KCC Logo without Wifi

R-REM-MSQ-XXXXXXXXXXXXXXXXXX

KCC Logo with Wifi

R-RMM-MSQ-XXXXXXXXXXXXXXXXXX

C

LOGO12

UKRAINE LOGO

UKRAINE LOGO

/X

UKRAINE Logo without Wifi

Title			
<Title>			
Size	Document Number		Rev
A	<Doc>		<RevCode>
Date:	Friday, August 17, 2018	Sheet	101 of 117



## Two USB 3.x Ports to One Type-C Connector/USB 3.1 Front Header Circuit\_1

A. Choose Type-C Connector/USB 3.1 Front Header by Project

B. Modify Type-C Connector/USB 3.1 Front Header Part Reference by Project

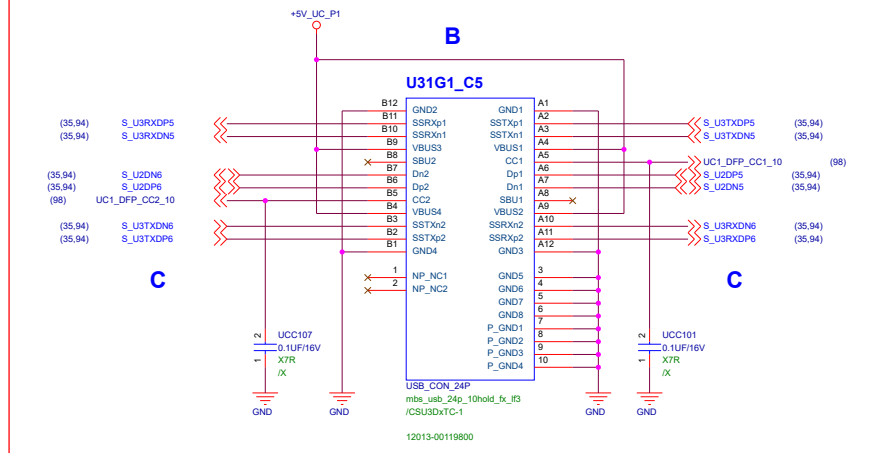
C. Modify USB 3.x Port TX/RX/D+/D- Signal Net Name by Project

BOM	Type-C with Power Switch	Type-C with Poly Switch
/CSU3DxTC-1	mount	mount
/CSU3DxTC-1/Power Switch	mount	unmount
/CSU3DxTC-1/Poly Switch	unmount	mount

### A.1

#### Chipset USB 3.0 Type-C Connector

Chipset USB 3.0 Part Reference: U31G1\_Cx (x=1, 3, 5,...)



<Variant Name>

# AMD Platform

You can only choose **8** pcs PCB Impedance point for your project


0 (must choose if use ASM1142/1143/2142/3142)

ASMedia USB 3.1 TX/RX

80 Ohm +/- 10%



1

DRAM CMD



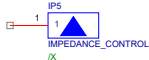

2

DRAM Clock



3

PCIE



4

USB2.0



5

DRAM DQS



6

LAN



7

SATA

8

USB3.1

\*\*\* You can only choose 1 function to place point follow table \*\*\*

Delete it for EMS

## 圓形光學點

LayoutRD 會依空間大小，  
擺放大類或小類光學點；  
所以兩種光學點都需畫入線路中，  
最後再做刪除。

大類光學點

小類光學點

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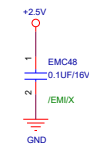
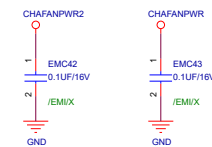
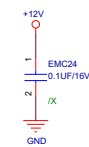
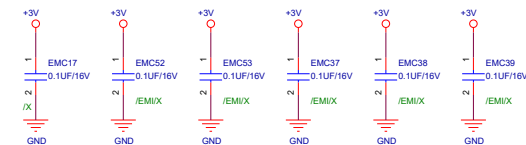
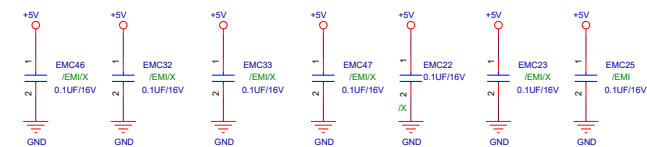
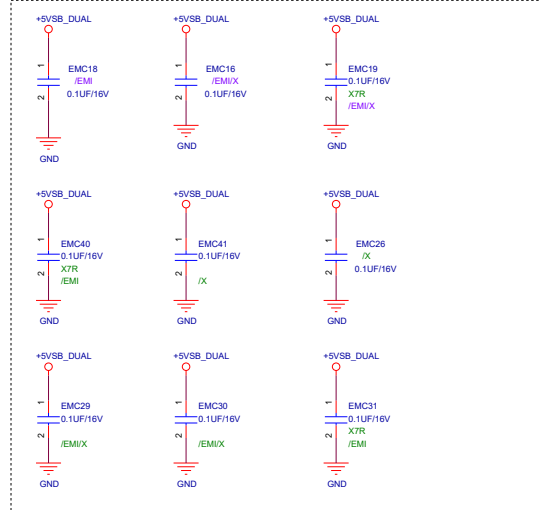
## 十字光學點

LayoutRD 會依空間大小，  
擺放大類或小類光學點；  
所以兩種光學點都需畫入線路中，  
最後再做刪除。

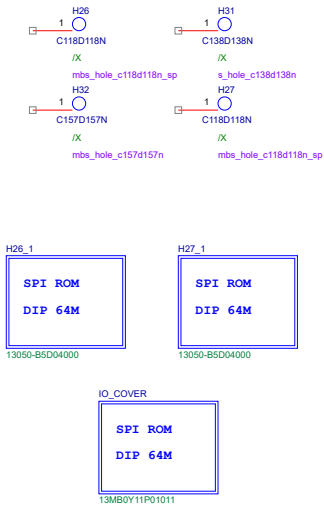
大類光學點

小類光學點



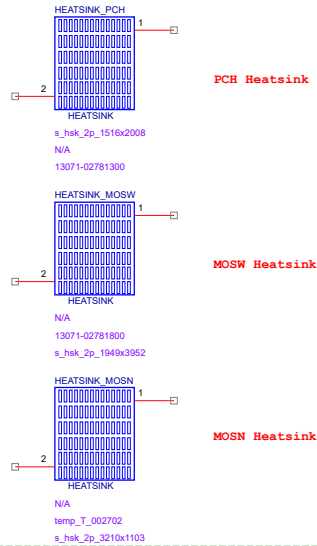


IO Cover




Heatsink

Heatsink follow Intel TUF B360M-PLUS GAMING

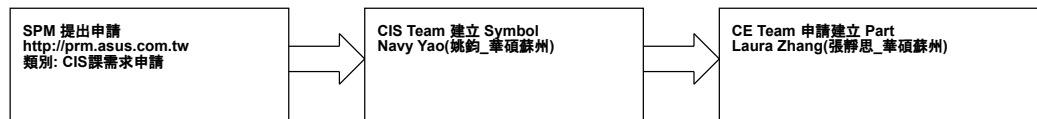


<Variant Name>

		Title : <b>HEAT SINK</b>	
ASUSTeK COMPUTER INC		Engineer: <b>KENNY_CHEN</b>	
Size <b>A3</b>	Project Name <b>Z87-PRO</b>		Rev <b>R1.02A</b>
Date: <b>Friday, August 31, 2018</b>		Sheet <b>112</b> of <b>117</b>	

# Selling Point

## 1. Selling Point 新增流程及窗口人員



## 2. 如何抓取 Selling Point Part, 如下圖

Search results for "PCB Footprint" containing "mb\_text" and "uefi".

Property	Compare	Value
1 PCB Footprint	Contains	mb_text
2 PCB Footprint	Contains	uefi
3		

Search criteria: "PCB Footprint", 內容包含 "mb\_text"  
"PCB Footprint", 內容包含需要的 Selling Point 中的 Key Word

Table	Part Number	Component_Name	Description	Value	Electric
1 ASUS_CIS3	temp_AH0600587062	mb_text_uefi_bios		UEFI BIOS	

## 3. Example

<Variant Name>

Notes:  
1. PWM (Server/ WS only)  
2. TACH (Server/ WS only)

layout request

0613  
swap by layout  
Alex

0530  
swap by layout  
Alex

0706

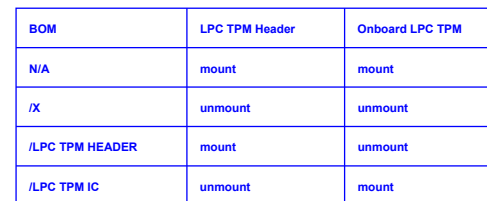
RN change to R

RN change to R

0522

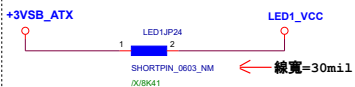
CORETYPE1 GPIO	Bristol (0)	Summit (1)
GPI	S_LED1	O_MEMOKLED#
GPO L	O_MEMOKLED#	S_LED1

- A. Del LPC TPM Header if don't need
- B. Modify LPC TPM Header Clock Net Name by Project
- C. Modify Part Number of LPC TPM Header by Color
- D. Del Onboard LPC TPM IC if don't need
- E. Modify Onboard LPC TPM IC Clock Net Name by Project
- F. Modify Onboard LPC TPM IC's Part Number by Project
- G. Modify Optional of TMR13, TMR14, TMR15 by Onboard LPC TPM IC
- H. Modify +3V to +3V\_S0IX if support Intel S0ix
- I. Choose TPM\_CLKRUN# Circuit by Project

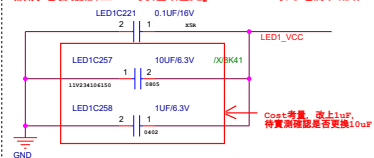




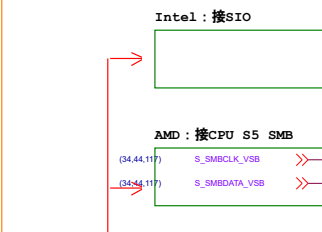
## IC Power (Iop=4.5mA, Isink=320mA)



請將電容擺放至VDD旁邊 (避免power-on時的電源凸波)

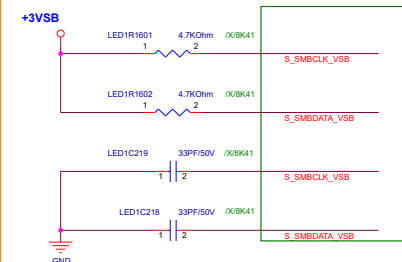


## SMBUS 請依平台選擇SMBUS



SMBUS\_net  
命名, 請自行修改或刪除

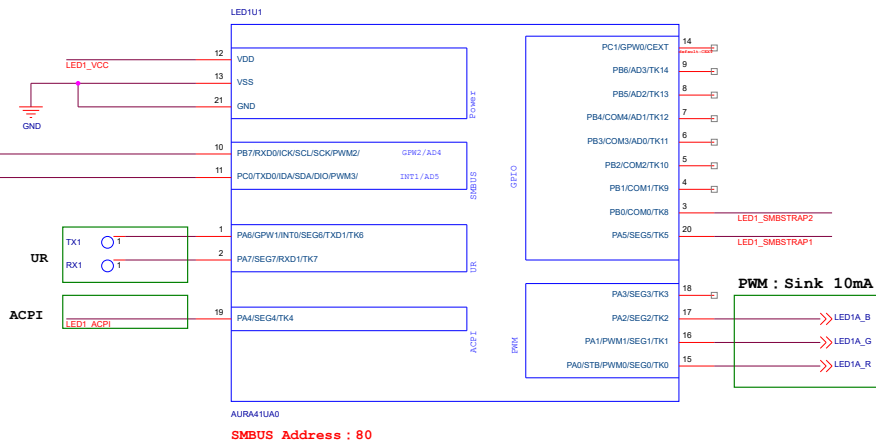
## SMBUS 請放置在IC的SMBUS附近



SMBUS\_net  
命名, 請自行修改或刪除

## ACPI 請選擇ACPI Pin的Power, 請依需求自行刪除

支援開/關機特效



AUR441UA0

SMBUS Address : 80

請註明是否有外接MOS

PWM : Sink 10mA  
LED1\_A\_B (116)  
LED1\_A\_G (116) ? LED (MOS)  
LED1\_A\_R (116)

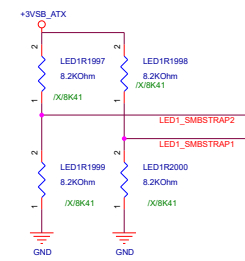
請註明亮燈的區域

- 0: CPU
- 1: VRM
- 2: NB
- 3: PCH
- 4: Audio
- 5: Back IO
- 6: Back Plate
- 7: PCIE
- 8: PCB Surround
- 9: M.2
- 10: Start/retry Button
- 11: Light Bar
- 12: RGB Header

EX : CPU LED (MOS)

SMBUS Address: (預留)

請將零件放置在IC的SMBUS附近



<Variant Name>

<b>ASUS</b>		Title : ENE_8K41	
ASUSTek Computer Inc.		Engineer: Kazier_Luo	
Size	Project Name		Rev
Custom	LED Standard Circuit		1.0
Date: Wednesday, August 23, 2018	Sheet	115	of 117

Title		
<Title>		
Size	Document Number	Rev
A	<Doc>	<RevCode>
Date:	Friday, August 17, 2018	Sheet 111 of 117

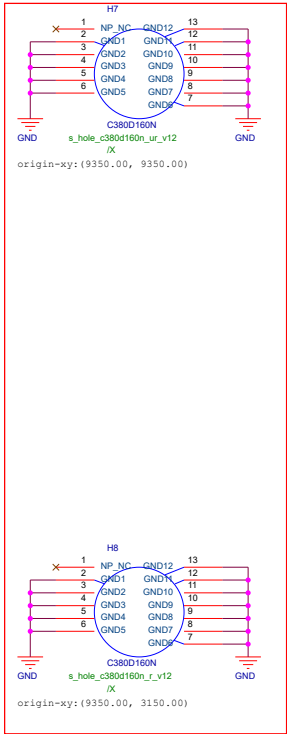
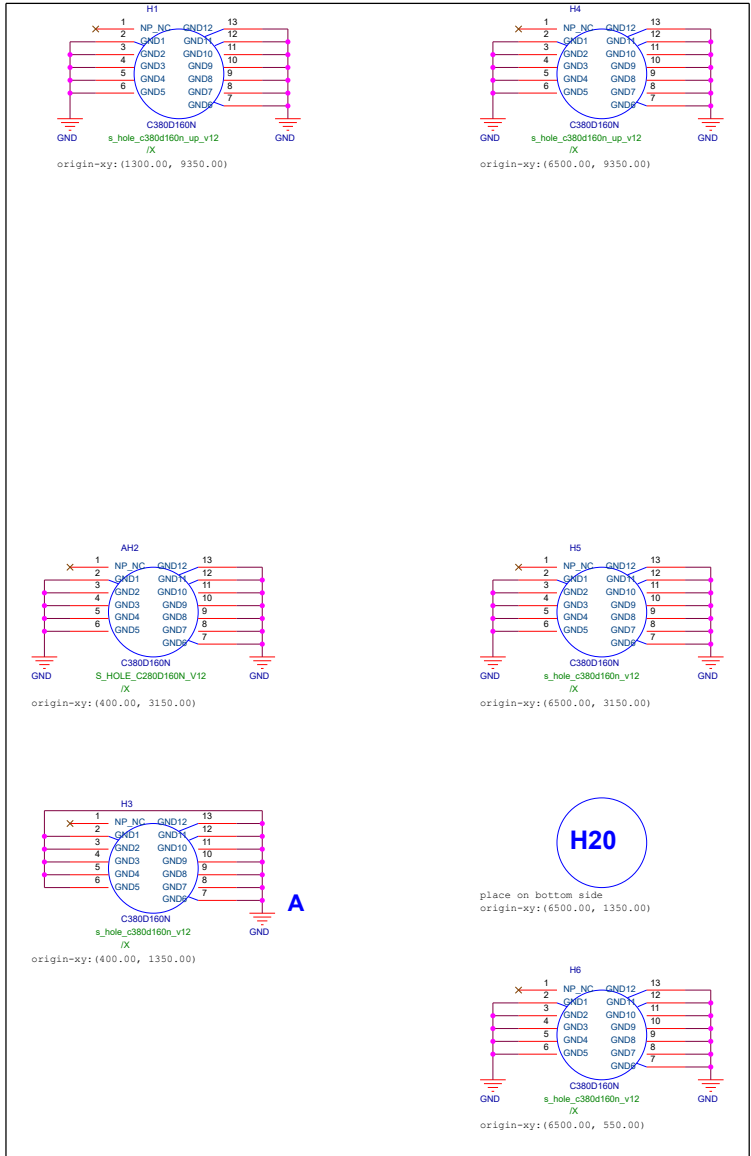
m-ATX Screw Hole Circuit

- A. Connect H3 to GND or A\_GND by Project
- B. Choose Bottom Side Silkscreen of H20 by Project
- C. Choose H7, H8 by Project

Delete it for EMS

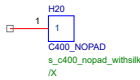
m-ATX Screw Hole

C.1



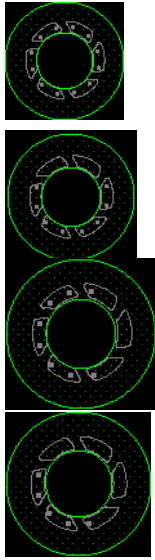
B.2

H20 with Bottom Side Silkscreen



MB SCREW FOOTPRINT

s\_hole\_c380d160n\_v12  
s\_hole\_c380d160n\_up\_v12  
s\_hole\_c380d160n\_r\_v12  
s\_hole\_c380d160n\_ur\_v12



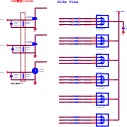
m-ATX Screw Select

	Standard (9.6 x 9.6)	Scale down (9.6 x <9.6)
H1	V	V
H2	V	V
H3	V	V
H4	V	V
H5	V	V
H6	V	V
H7	V	X
H8	V	X
H20	V	V

<Variant Name>

1. Lab 目標 < 20 分

Lab 目標與學生自述的  
目標一致

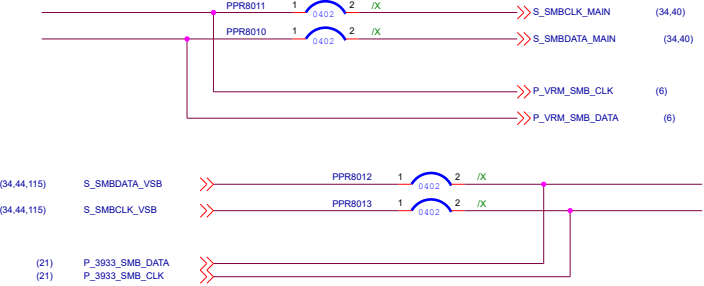


Lab 目標與學生自述

外設目標 目標——成績與學生自述一致，但不要求，請自行判斷。

2. 只有一般電路板的目標





<Variant Name>